

FIG. 1A

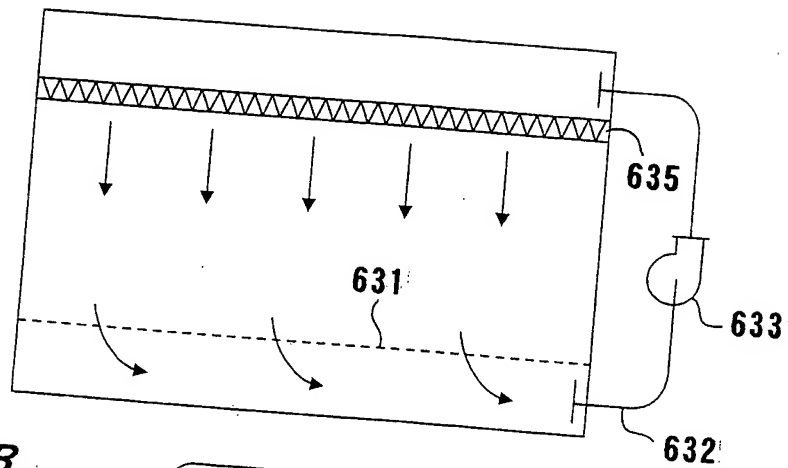


FIG. 1B

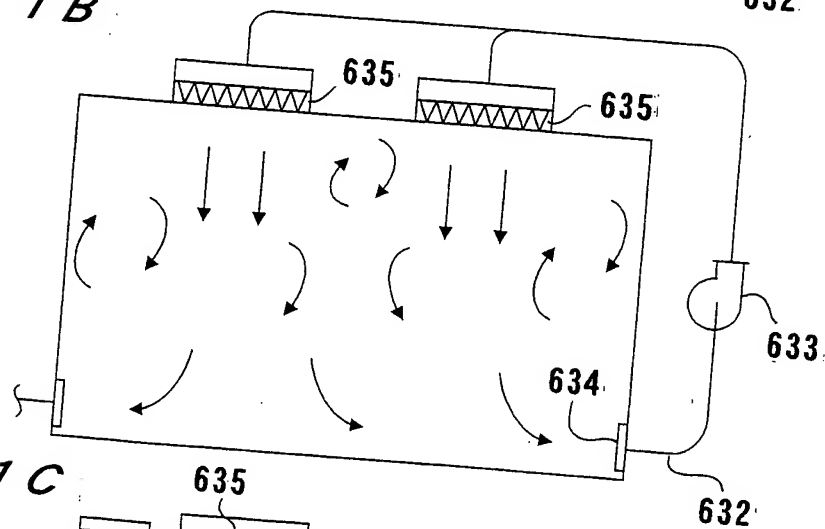
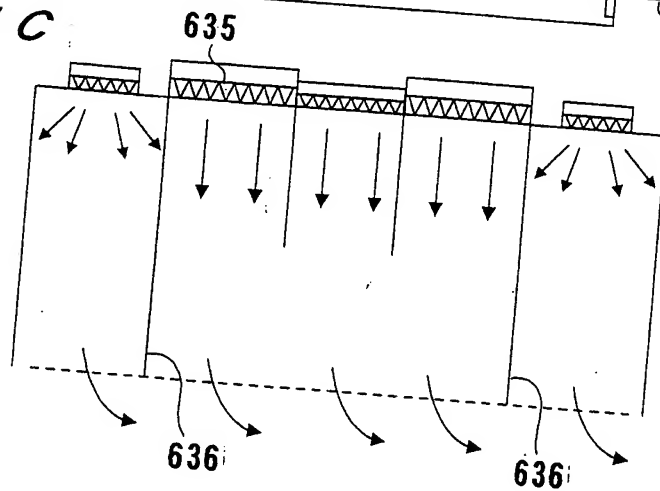
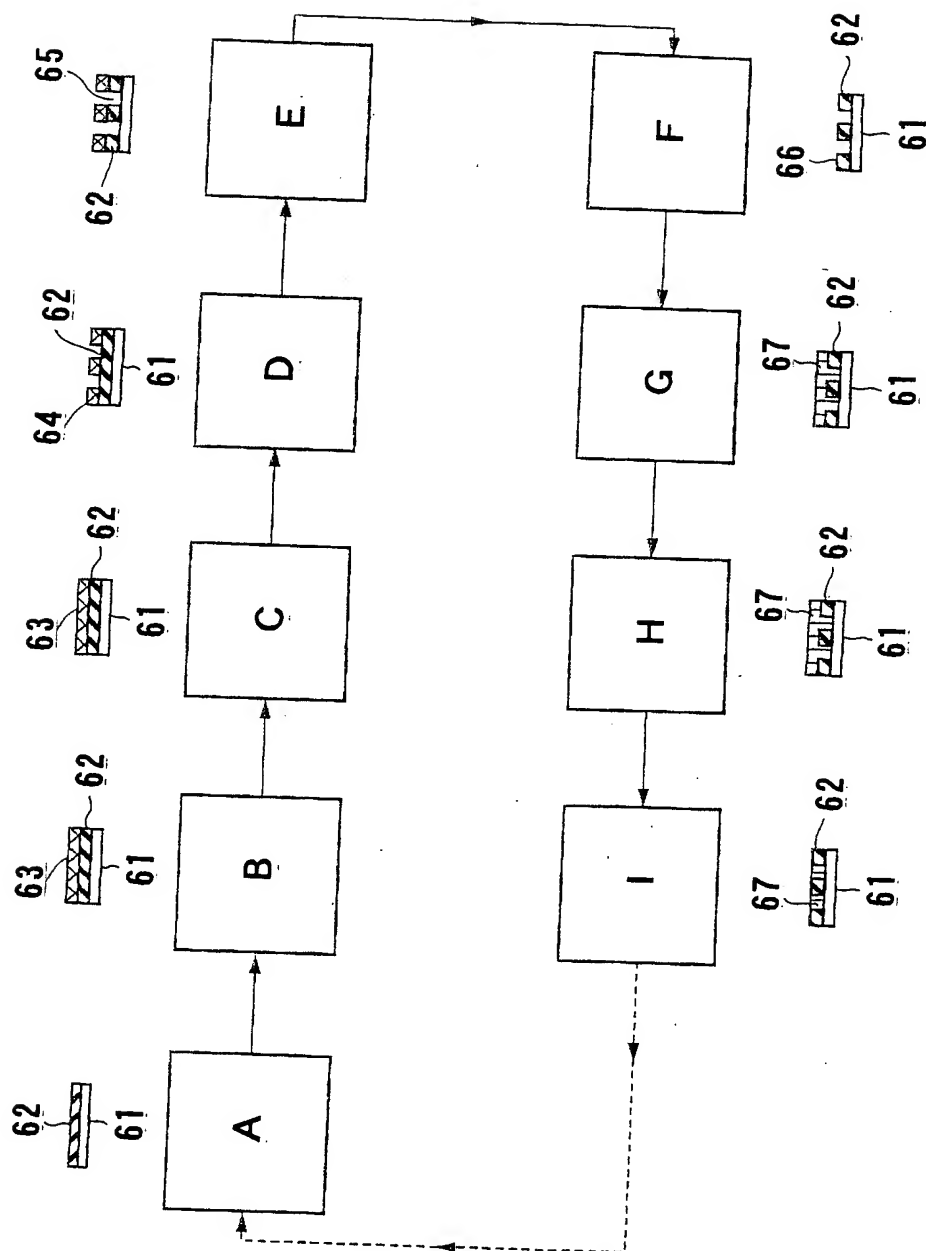


FIG. 1C



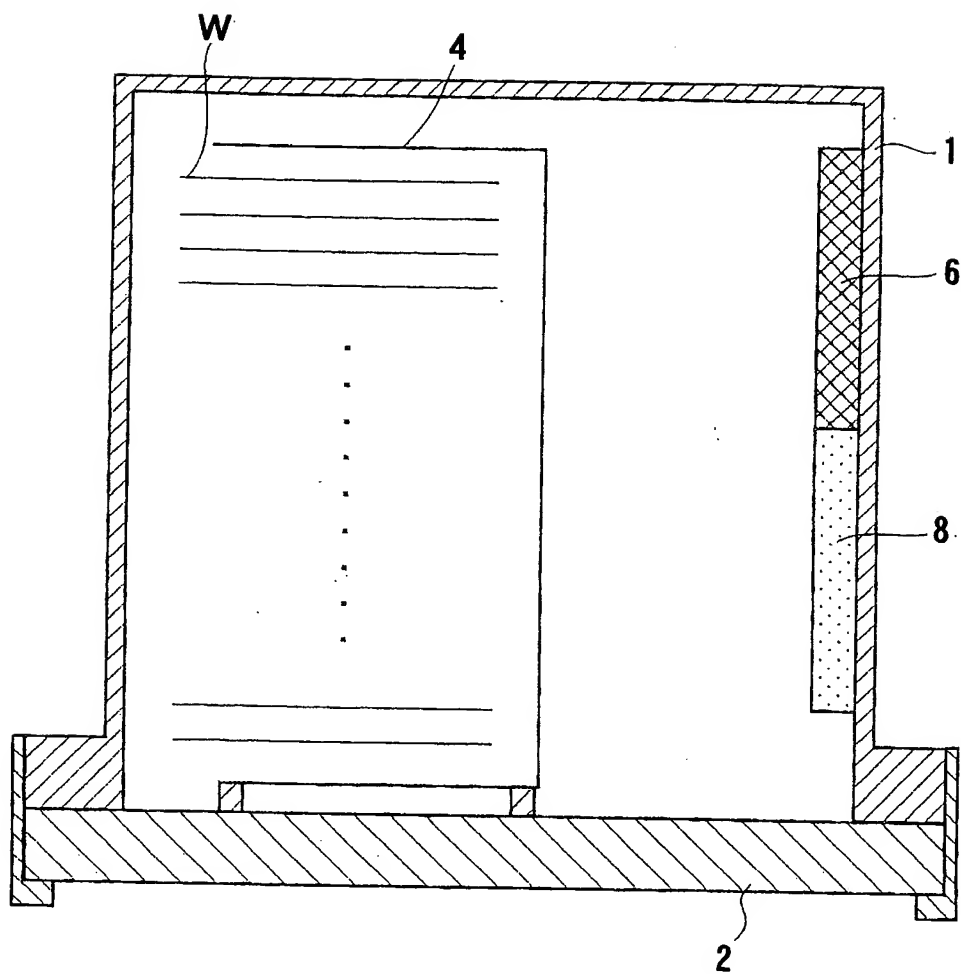
"GATE" METHOD

FIG. 2



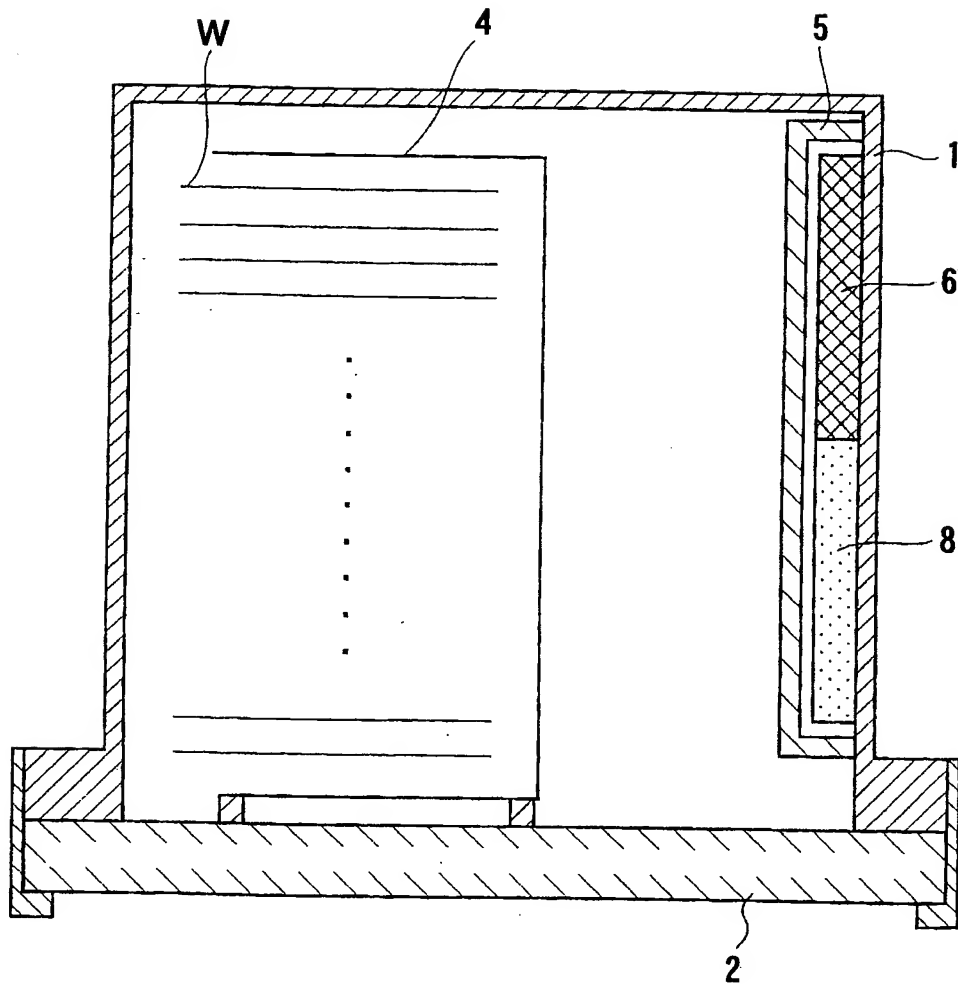
3/101

FIG. 3



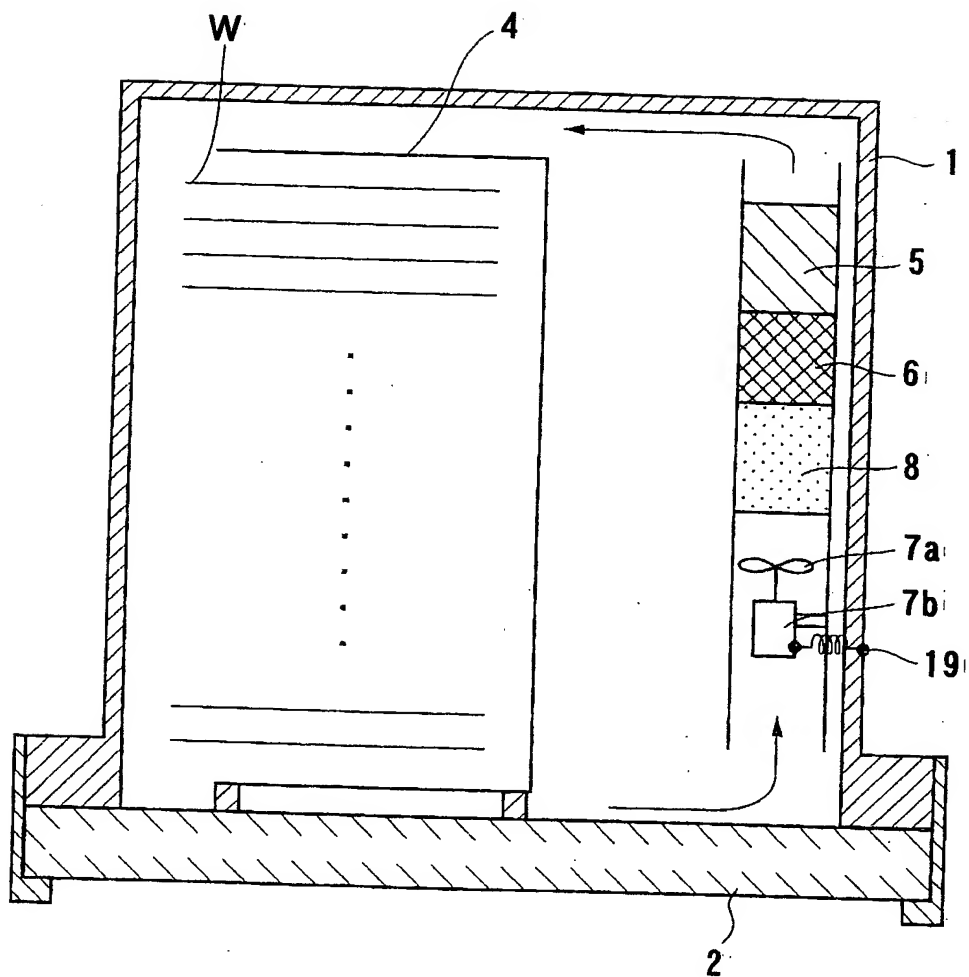
4/101

FIG. 4



5/101

FIG. 5



6/101

FIG. 6

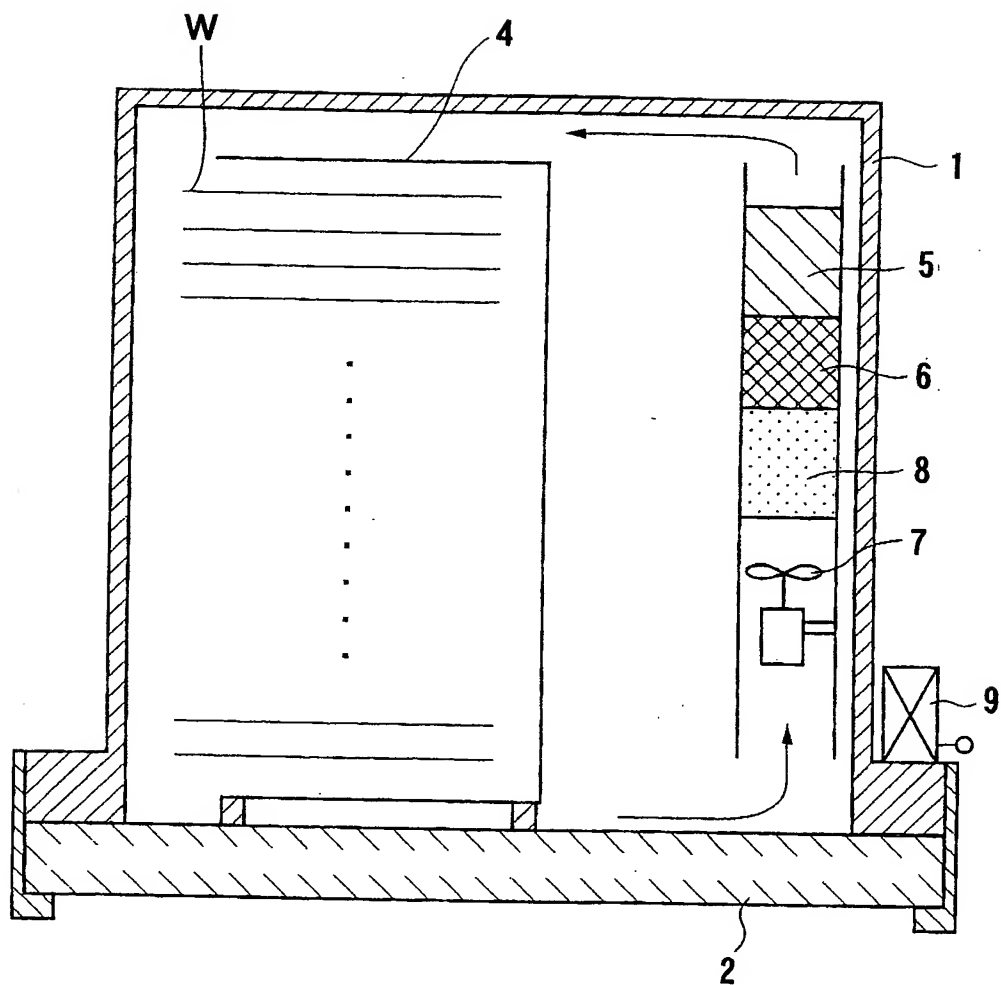
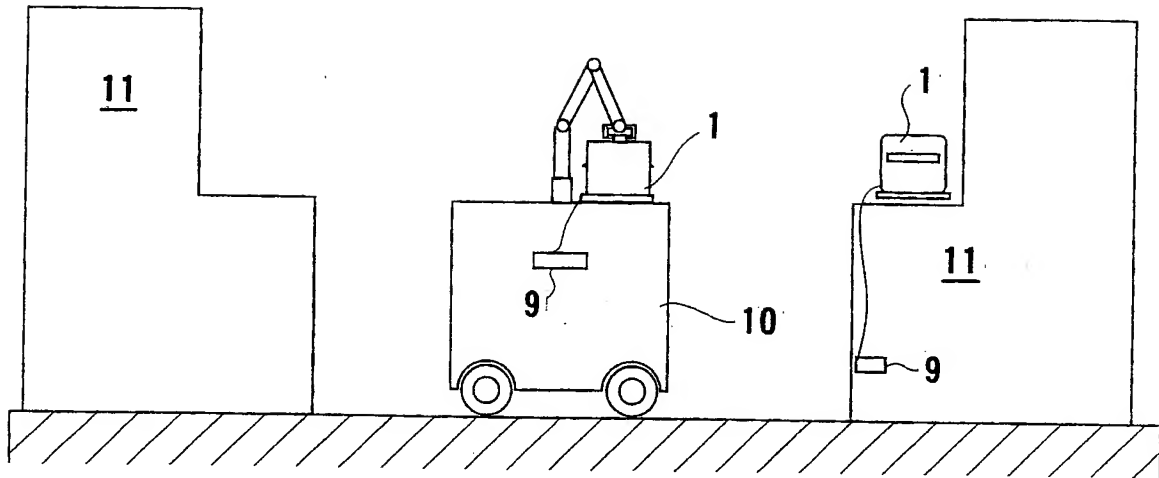


FIG. 7



8/101

FIG. 8

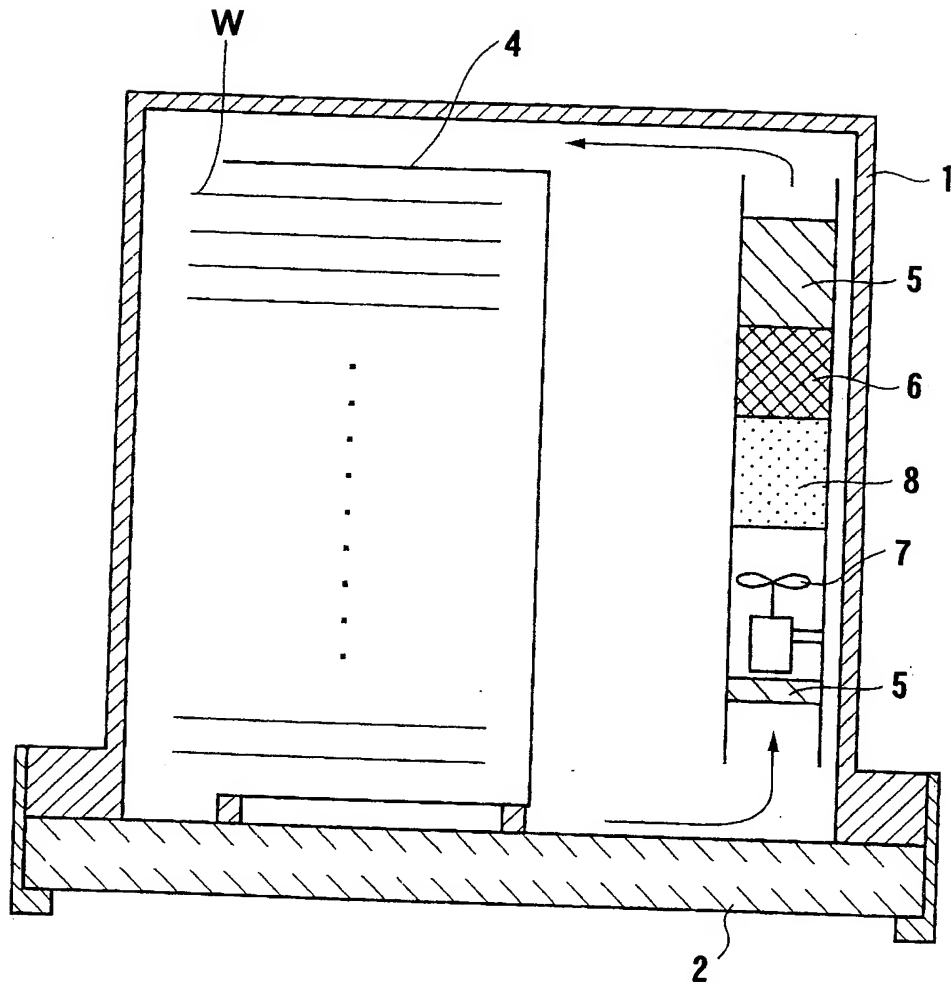
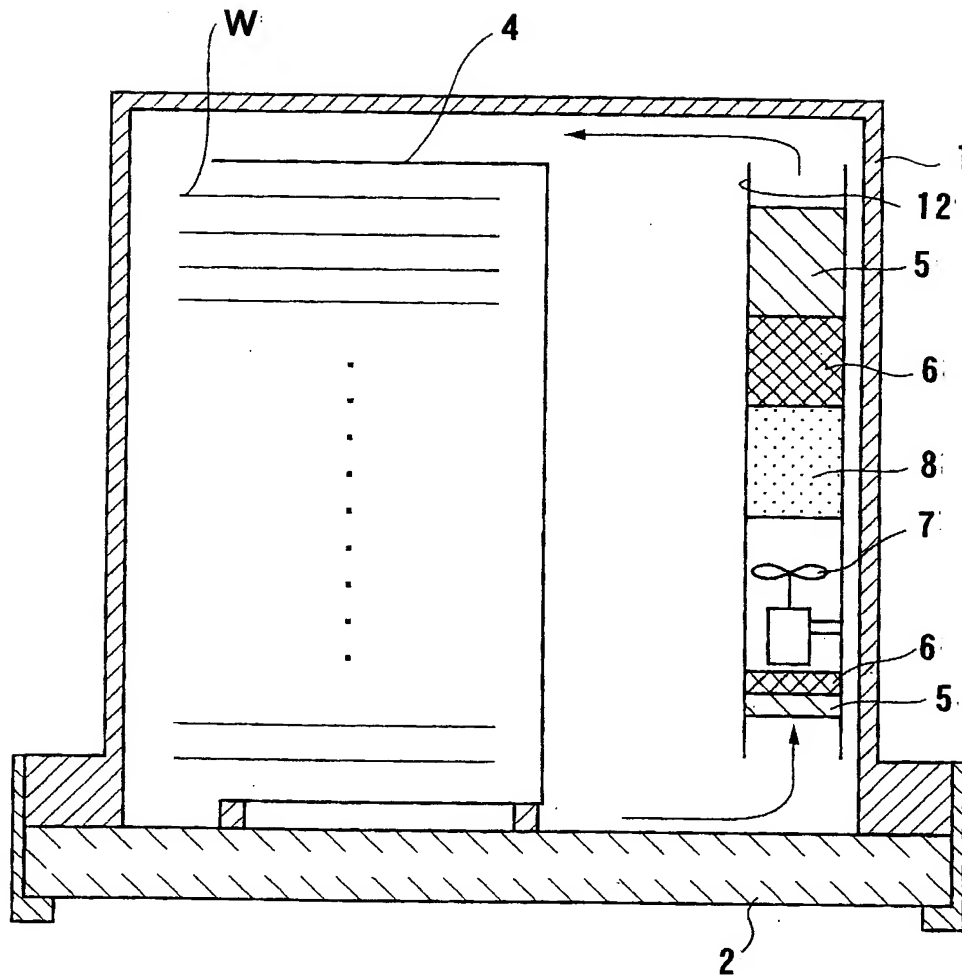
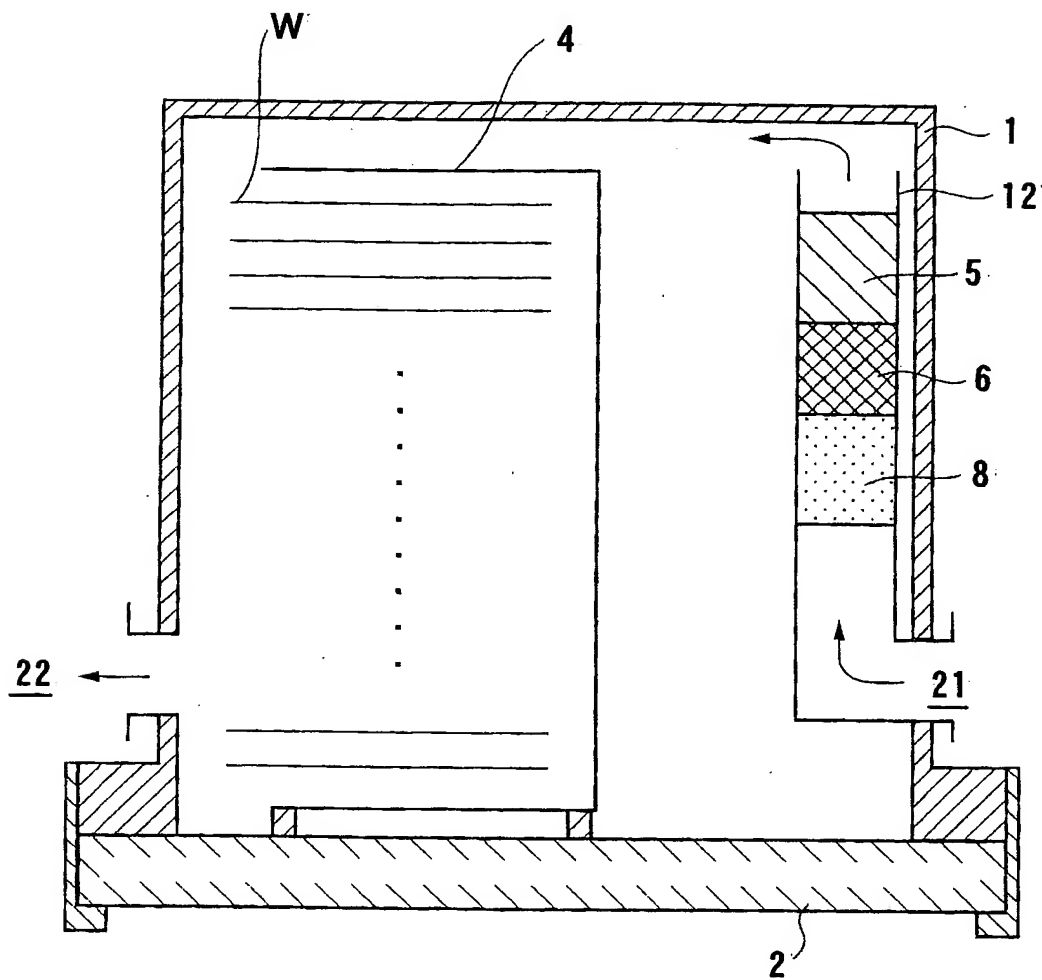


FIG. 9



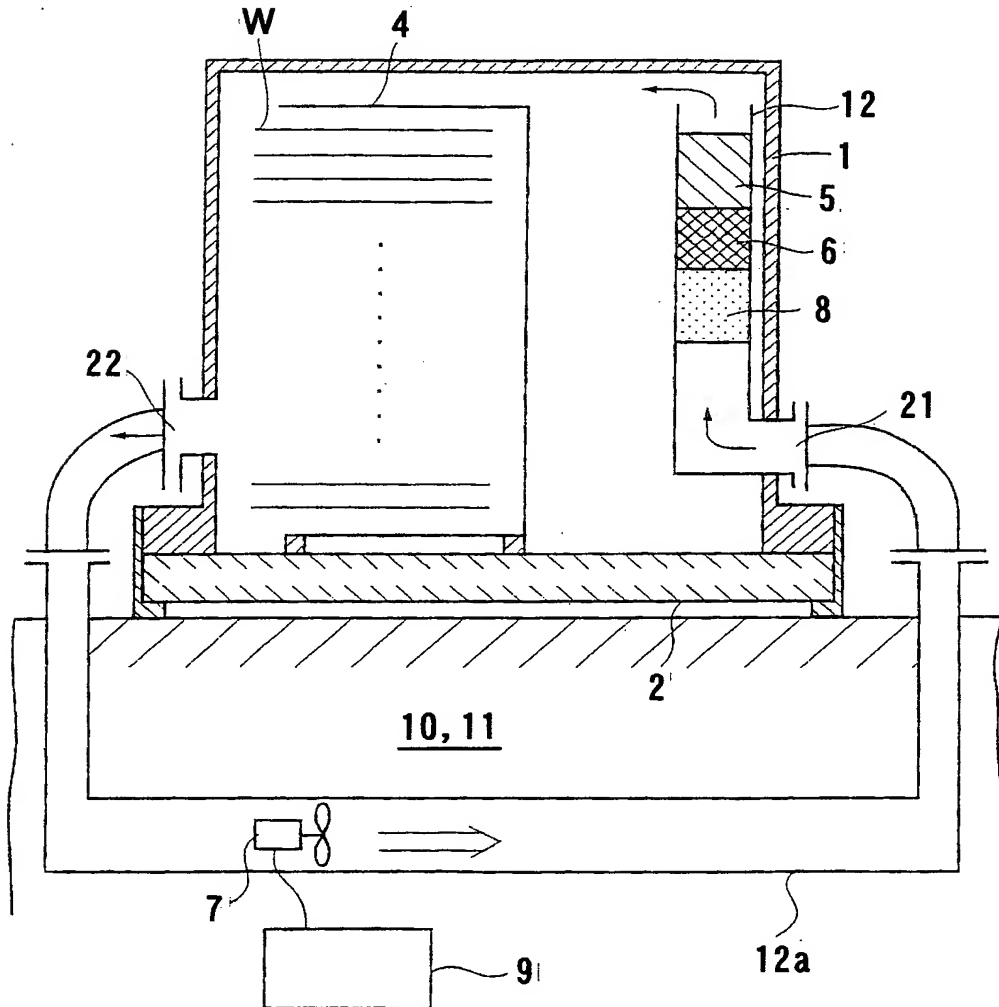
2025 RELEASE

FIG. 10



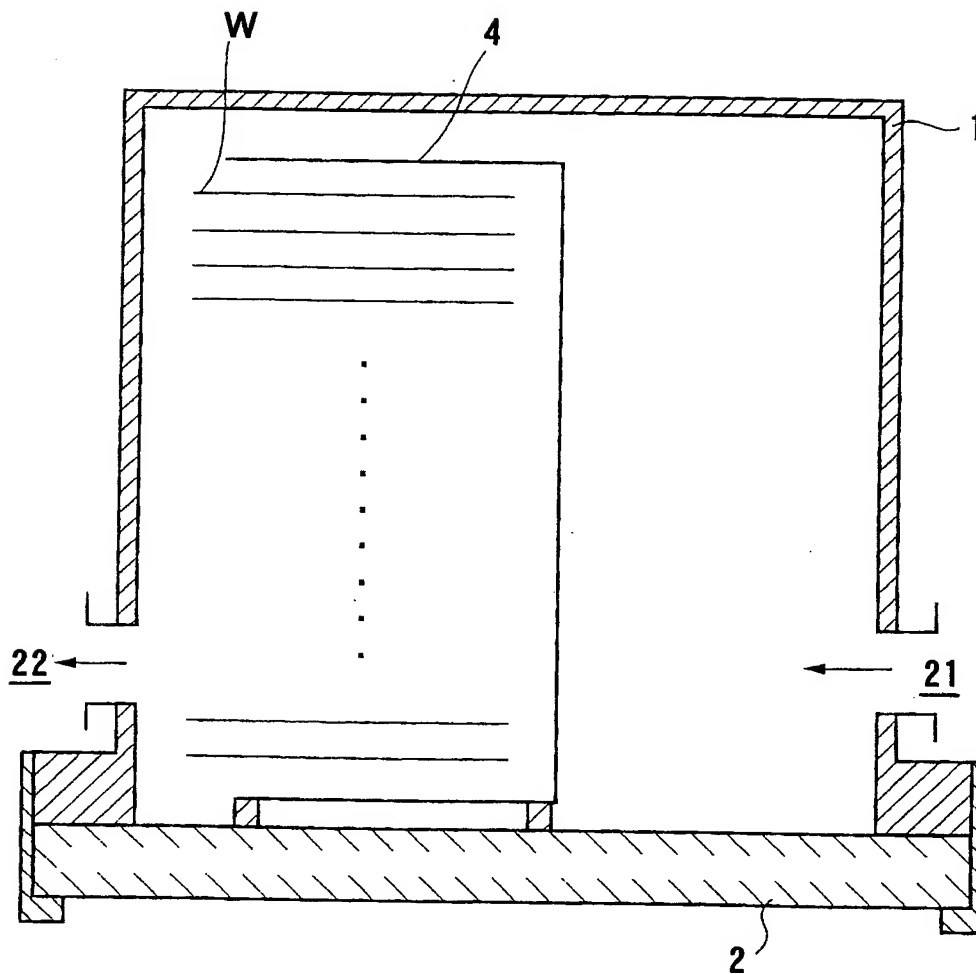
11/101

FIG. 11



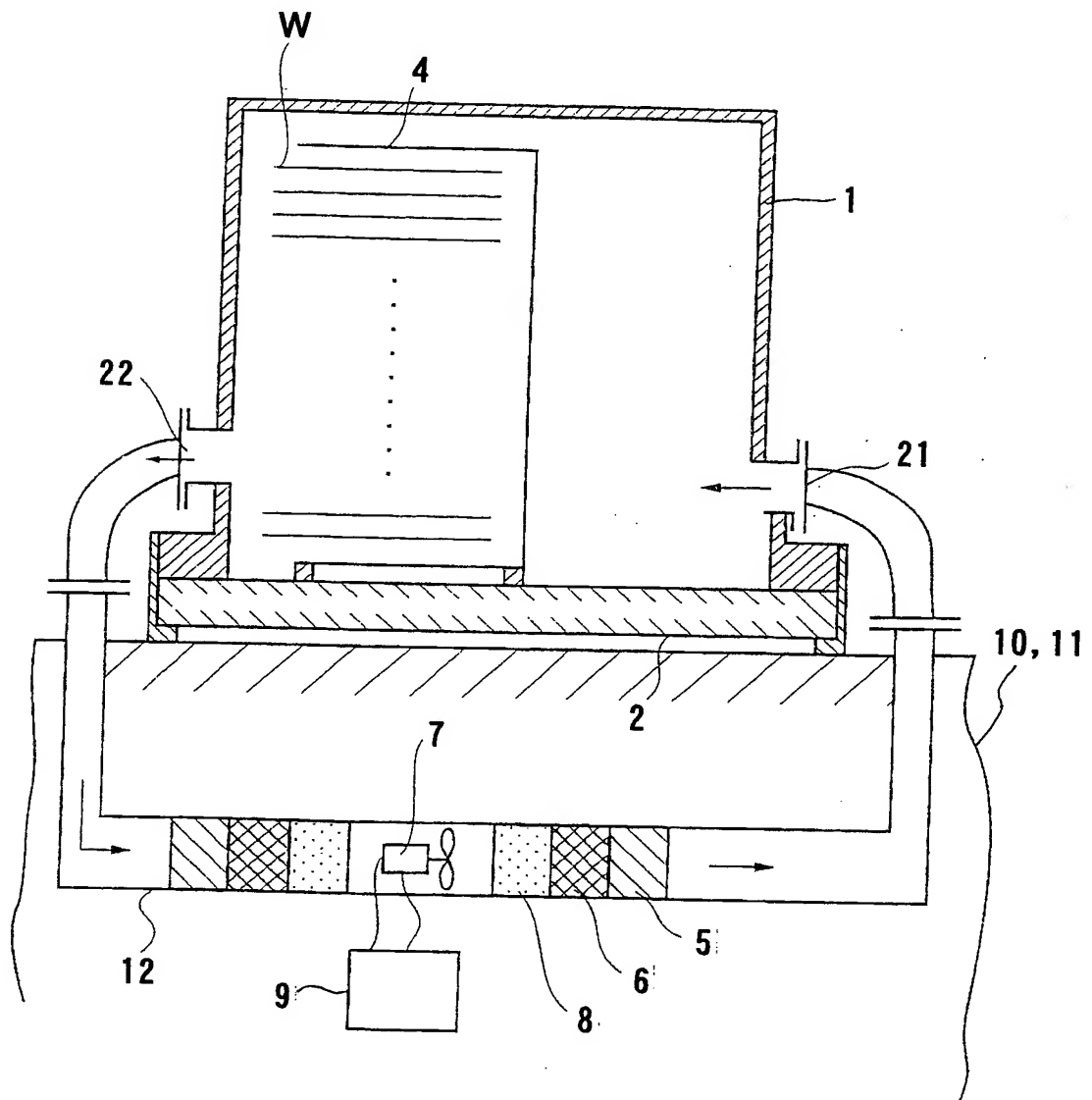
12/101

FIG. 12



13/101

FIG. 13



13/101-FIG. 13

14/101

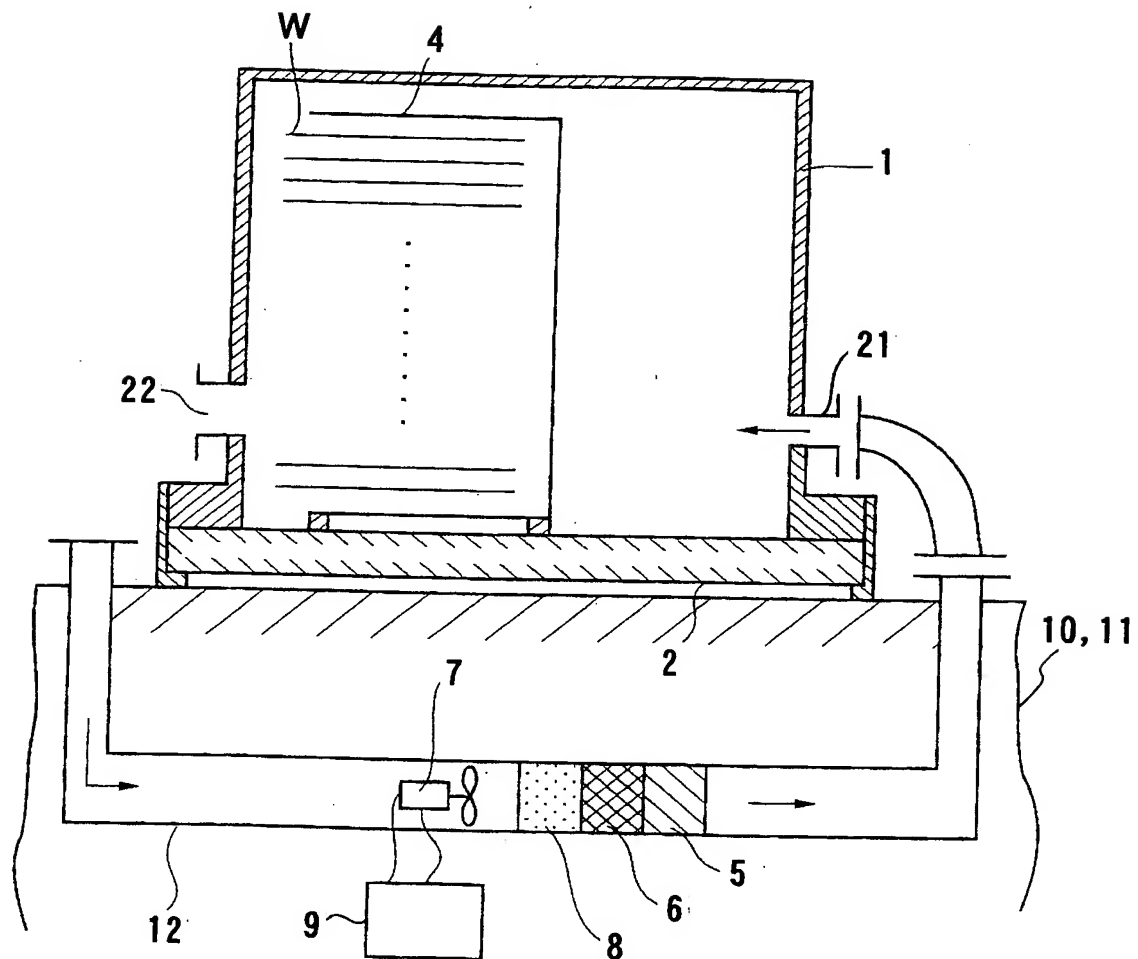


FIG. 15

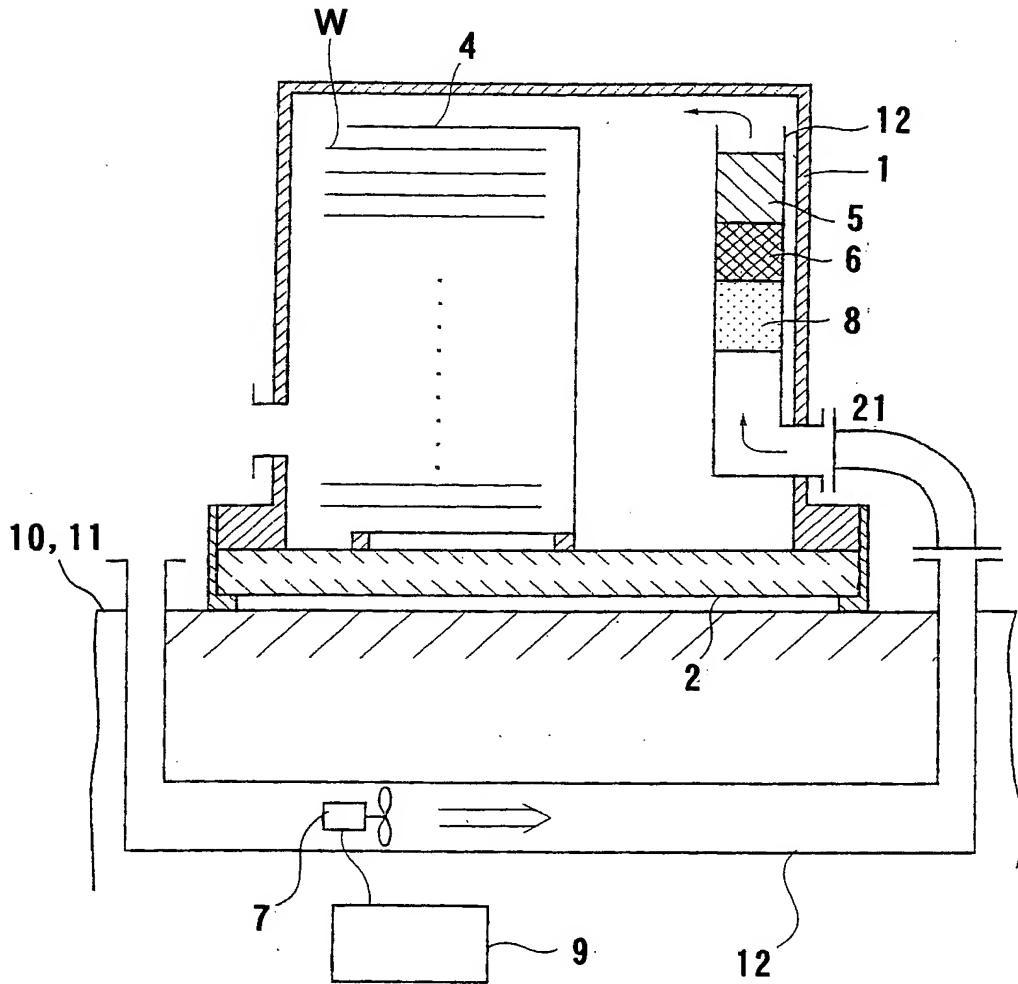
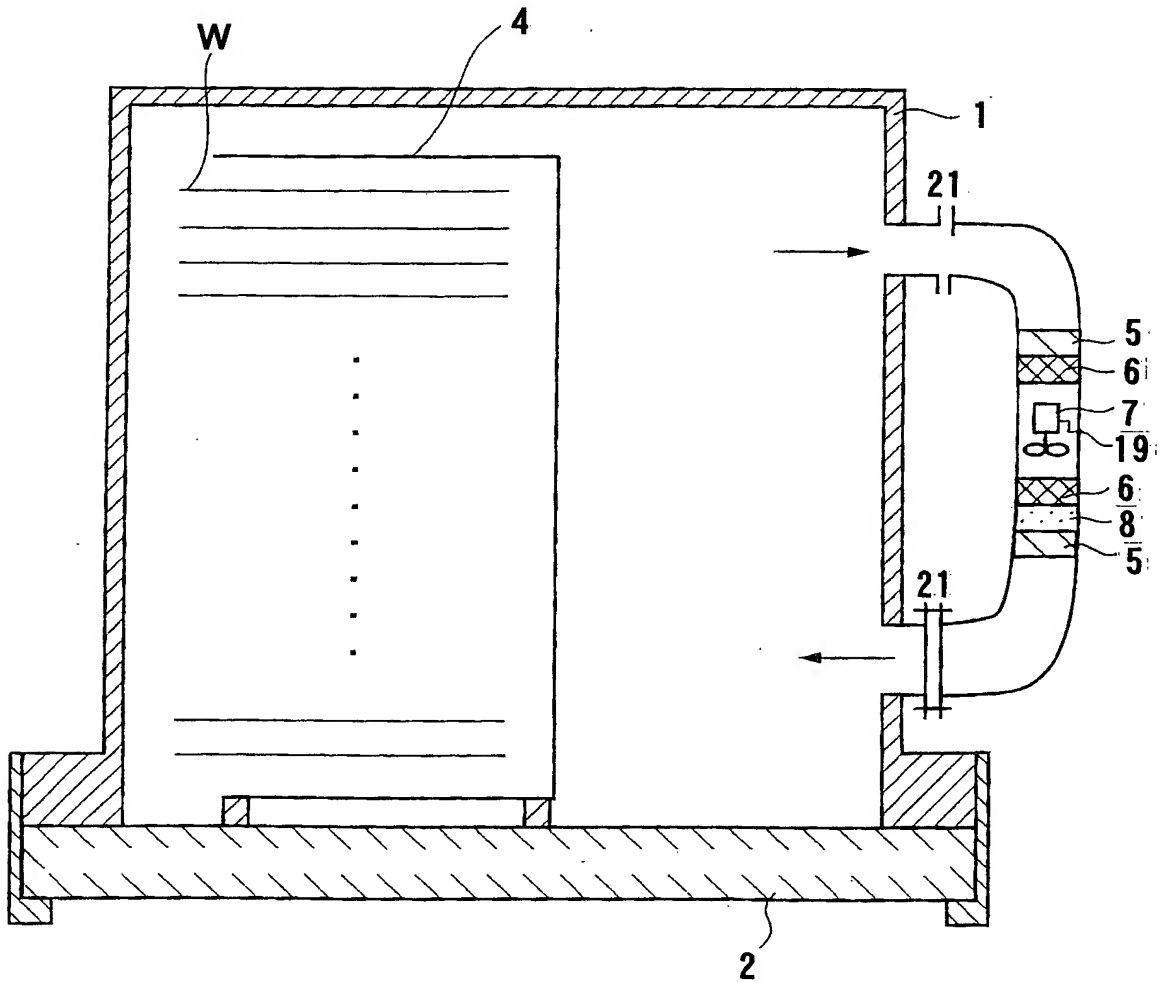
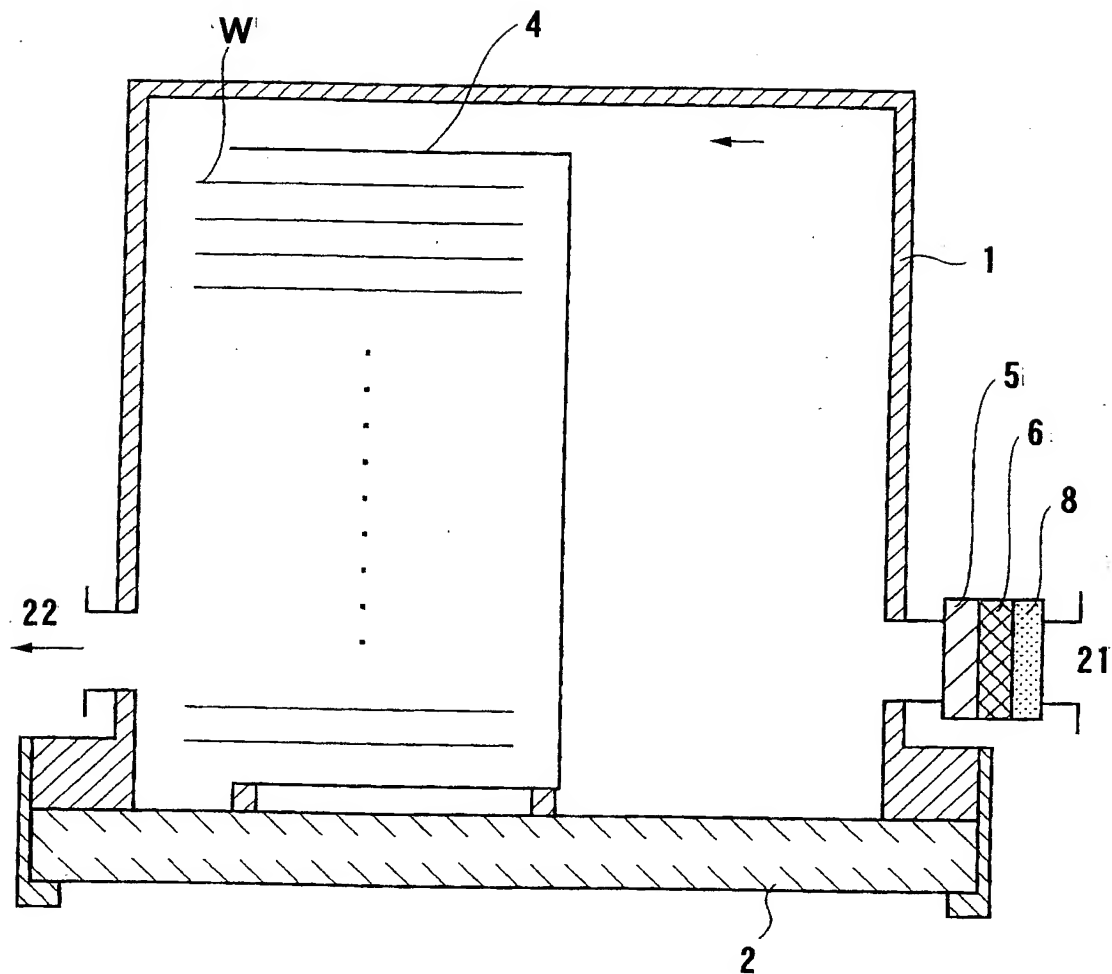


FIG. 16



17/101

FIG. 17



18/101

FIG. 18

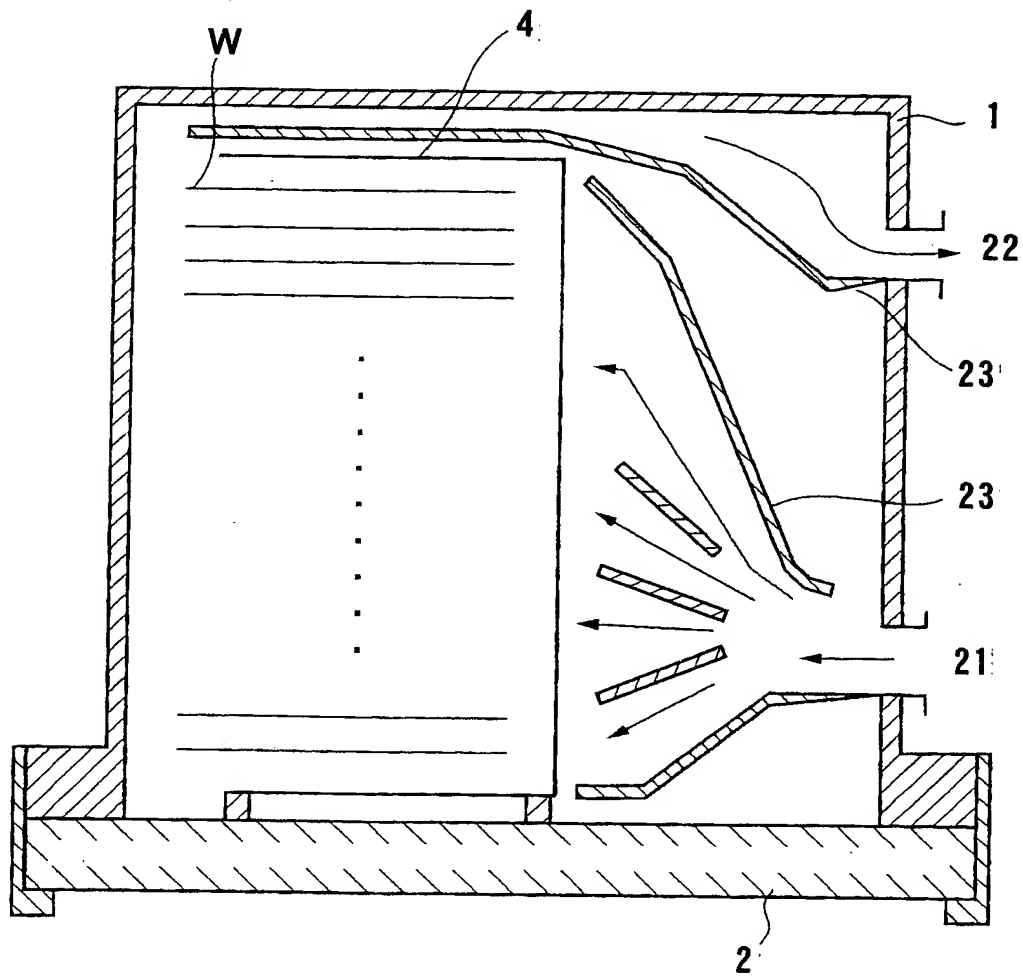
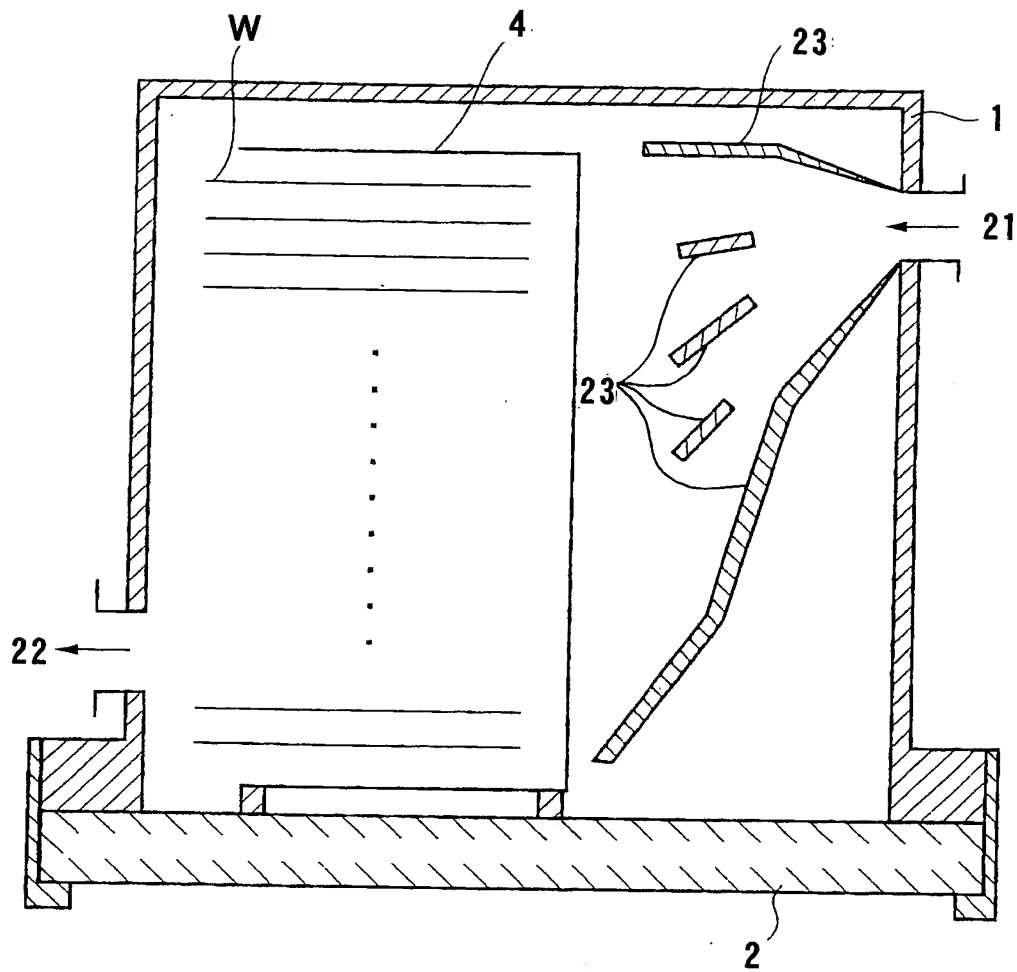


FIG. 19



19/101-1000000

20/101

FIG. 20

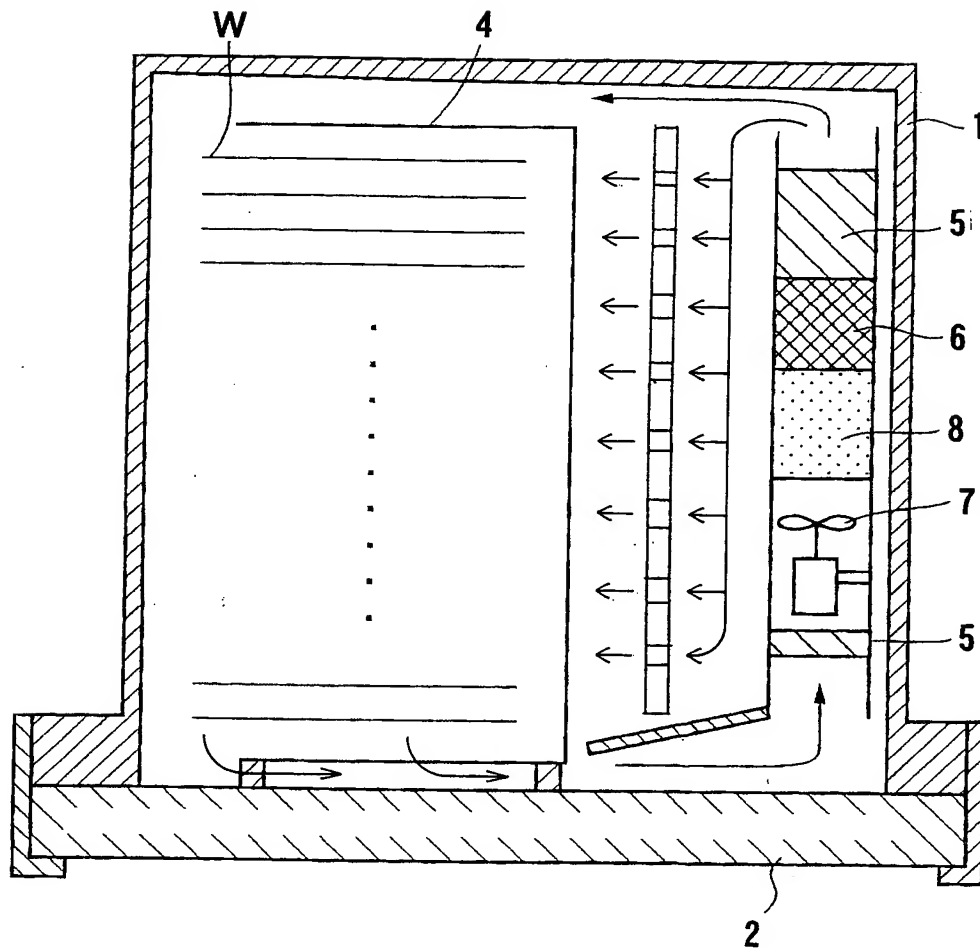


FIG. 21A

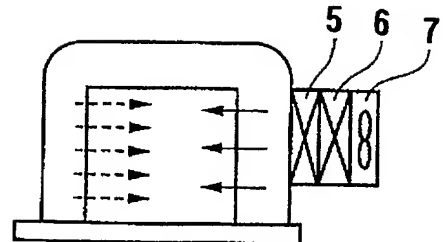
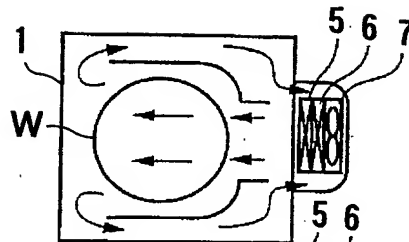


FIG. 21B

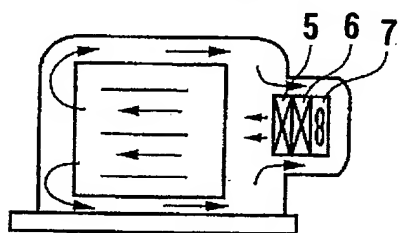
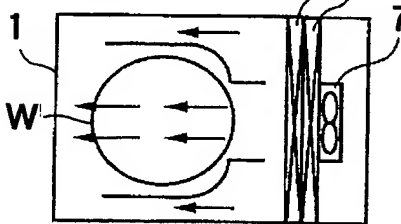


FIG. 21C

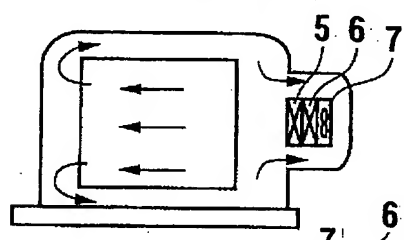
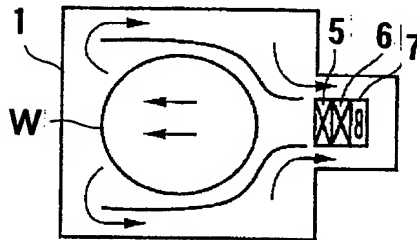


FIG. 21D

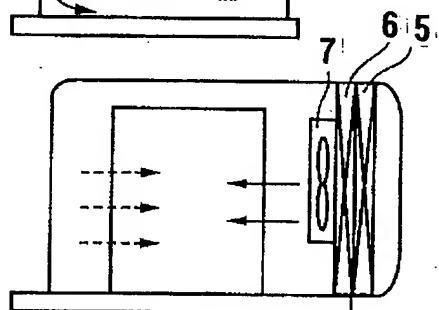
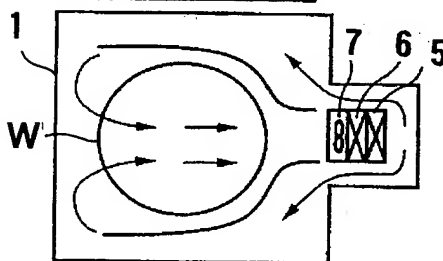


FIG. 21E

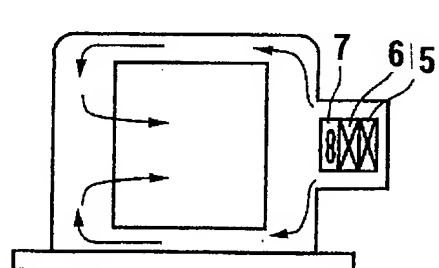
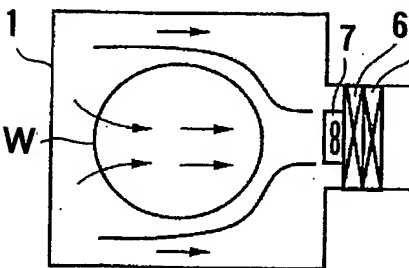
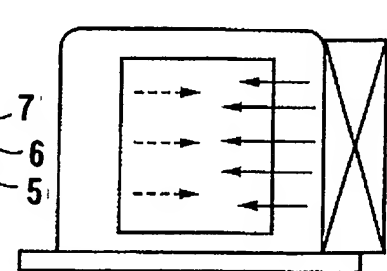
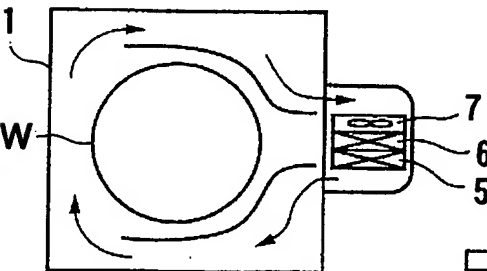
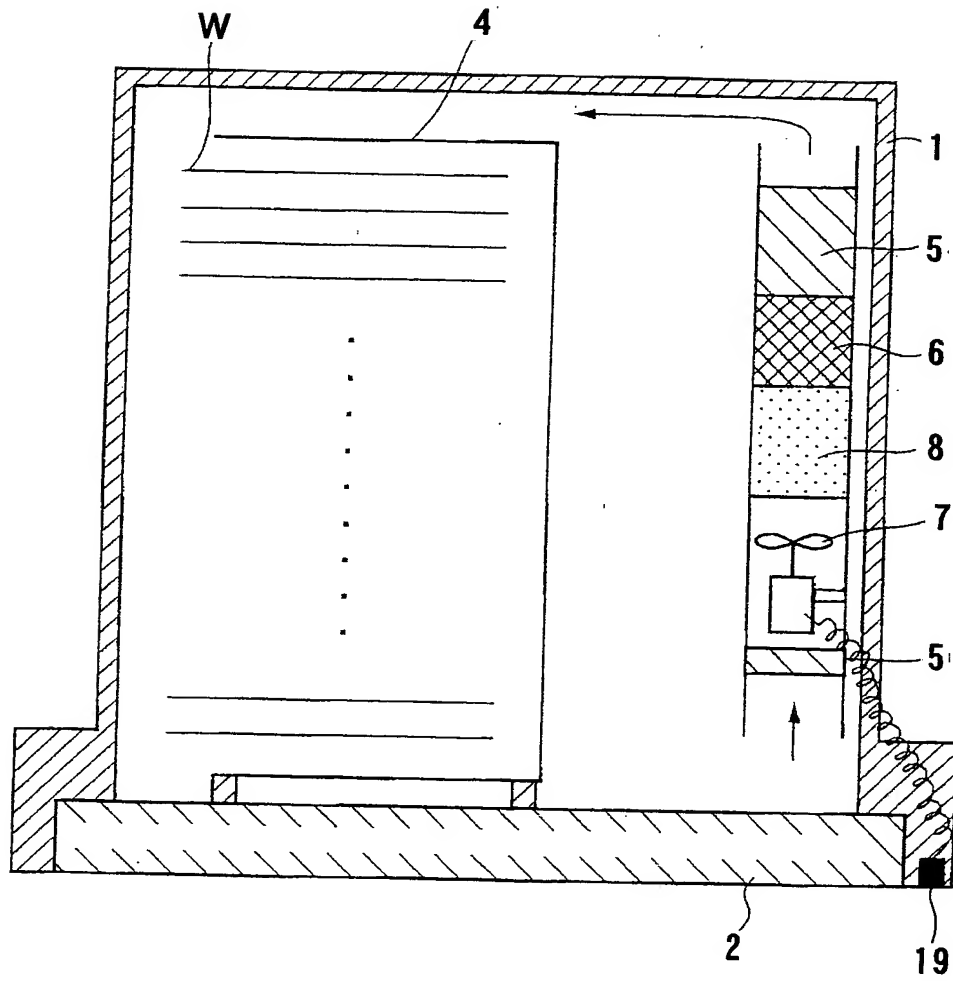


FIG. 21F



22/101

FIG. 22



23/101

FIG. 23A

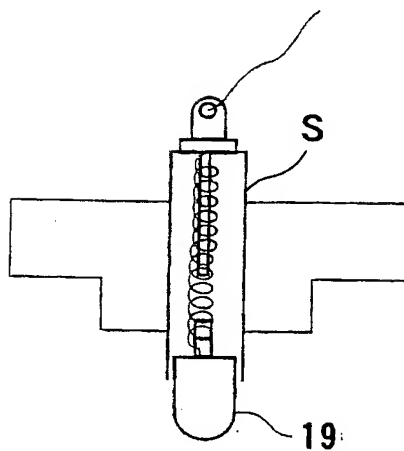
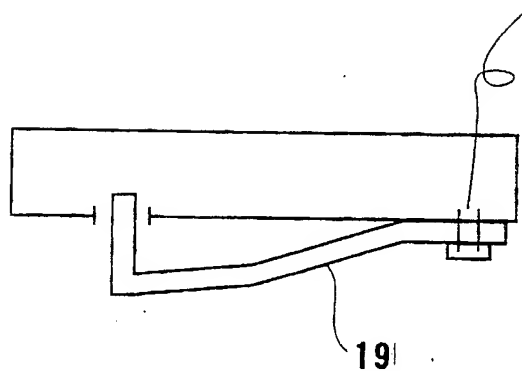
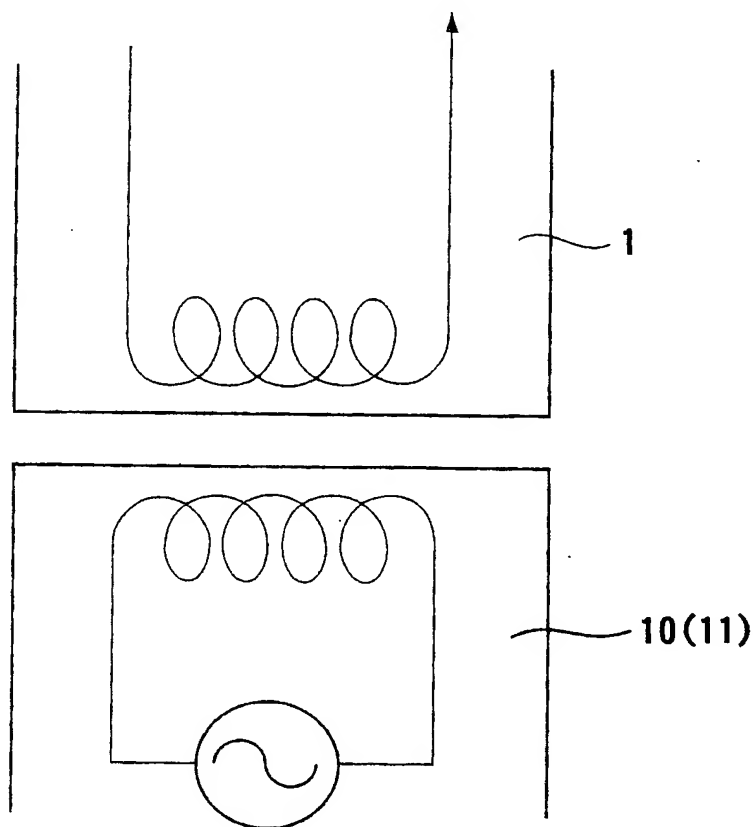


FIG. 23B



24/101

FIG. 24



25/101

FIG. 25

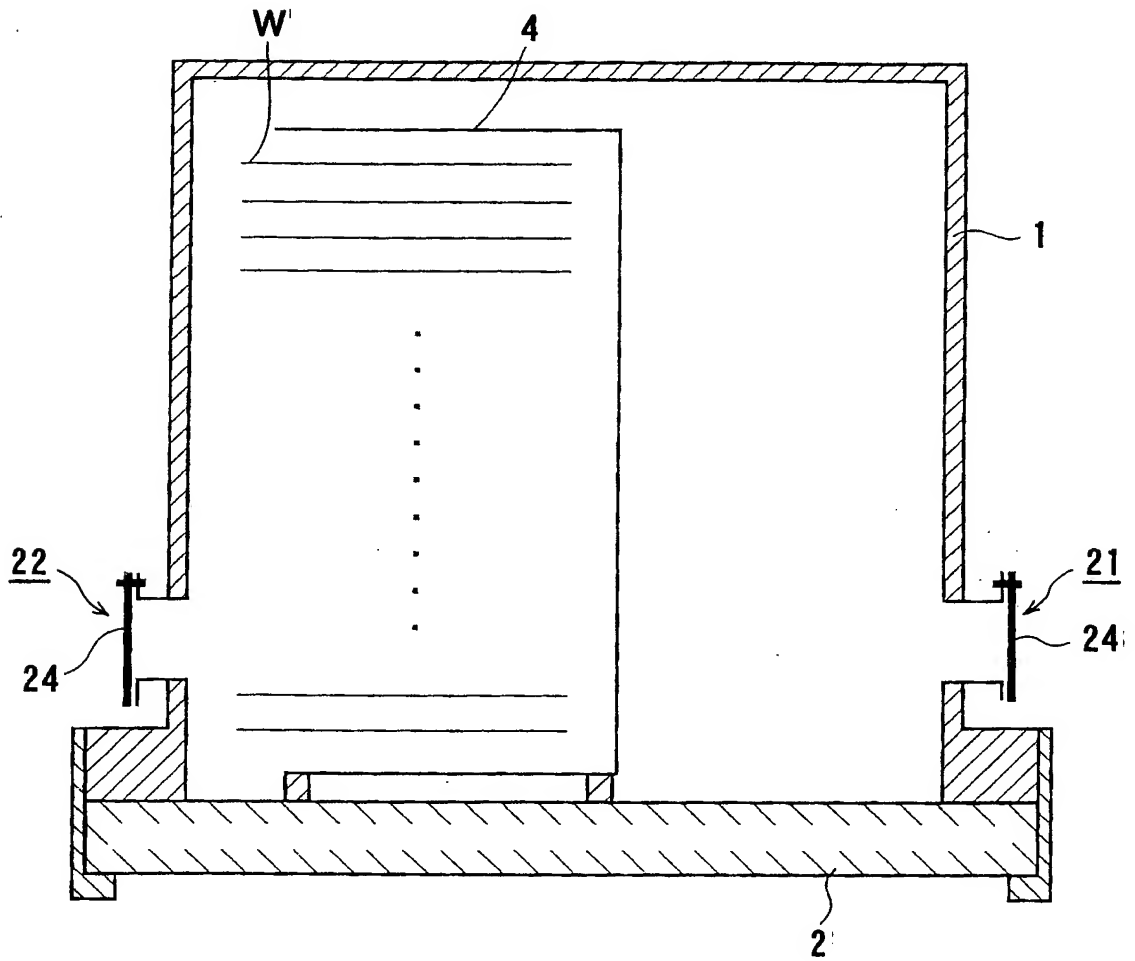


FIG. 26

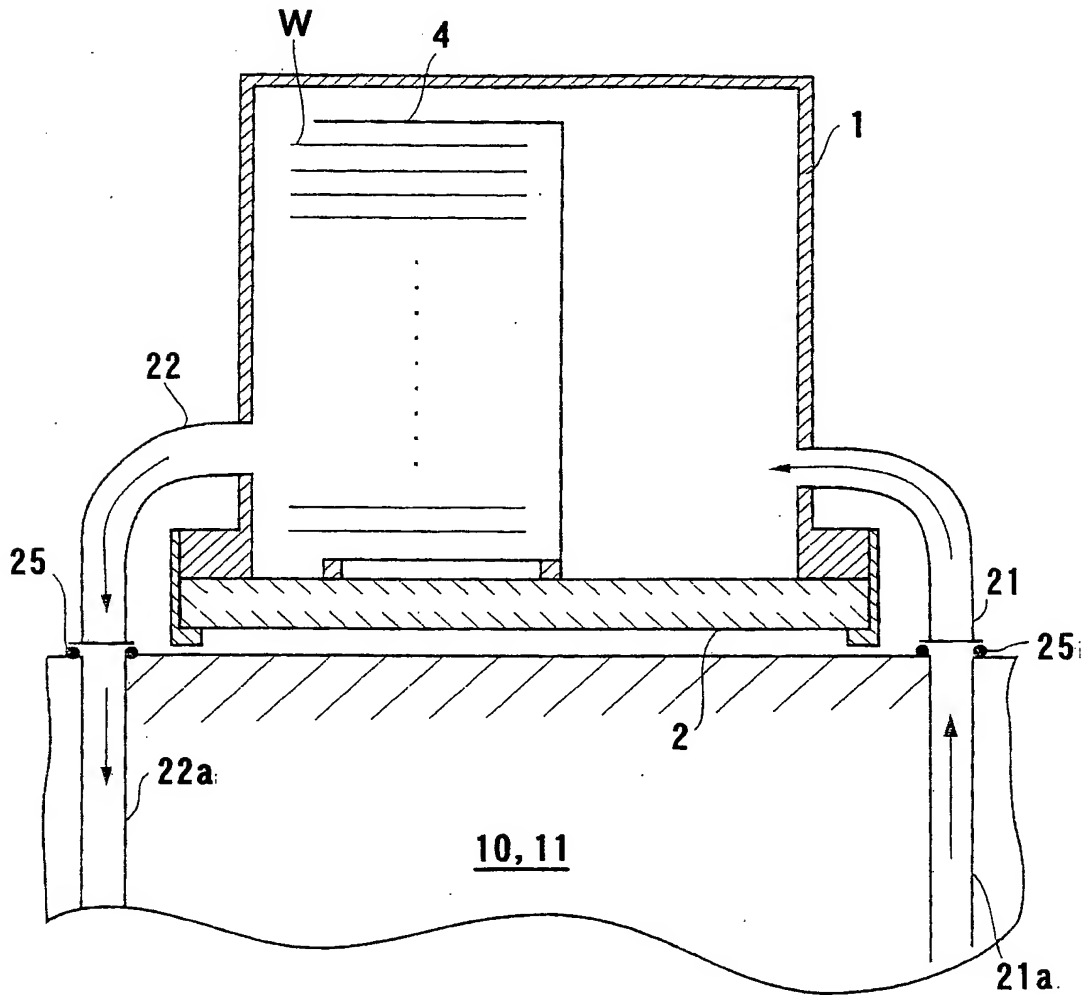


FIG. 27A

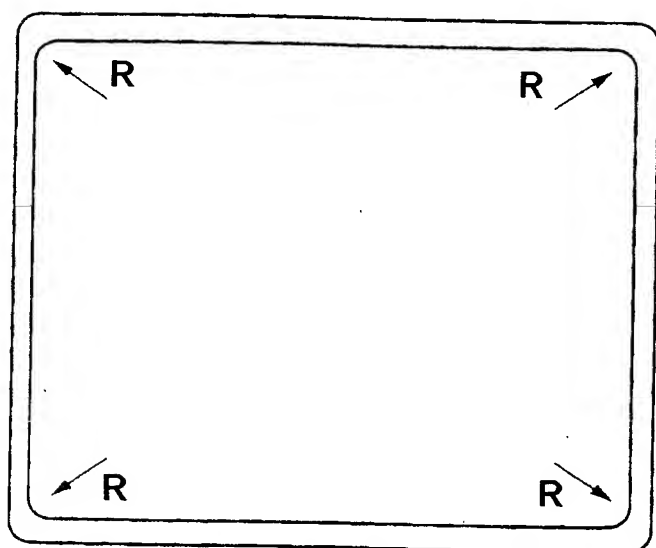
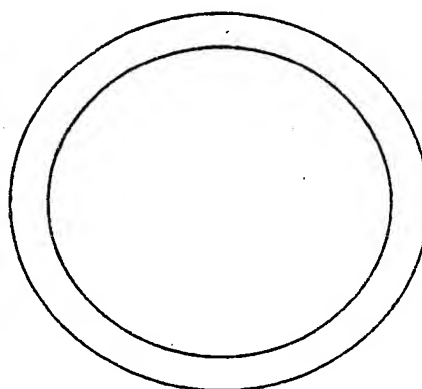


FIG. 27B



2025 RELEASE UNDER E.O. 14176

FIG. 28

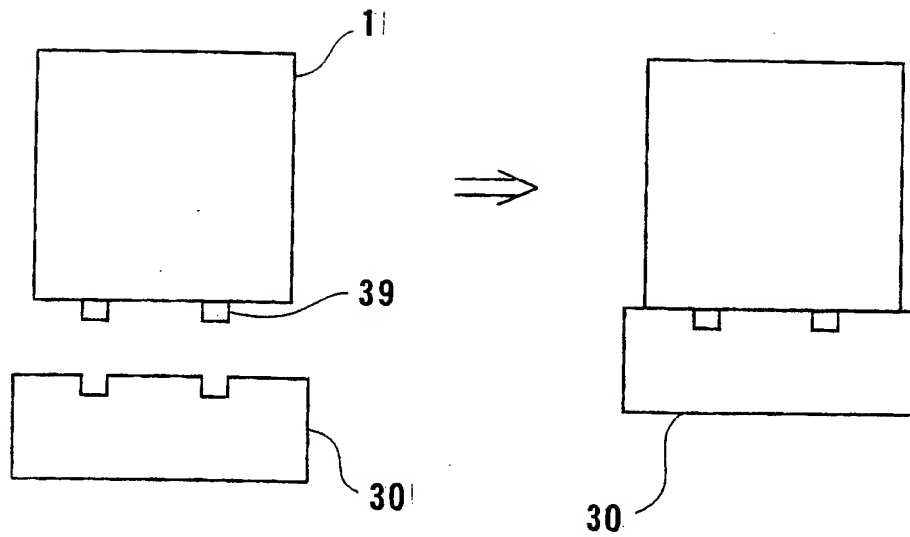


FIG. 29A

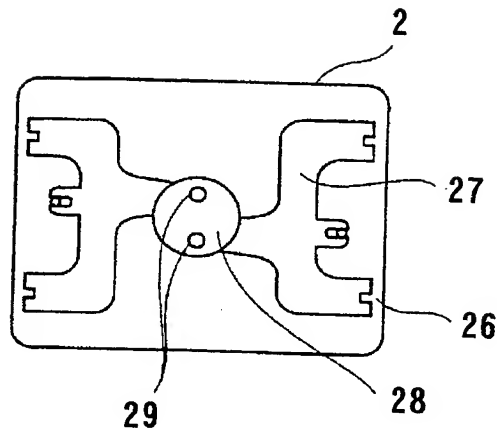


FIG. 29B

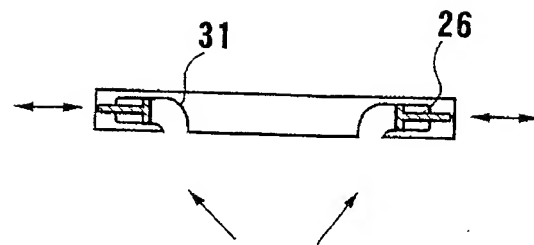


FIG. 29C

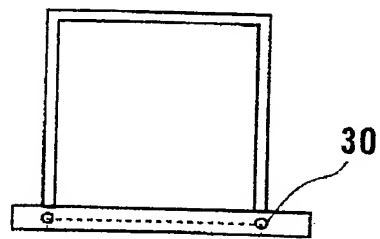


FIG. 29D

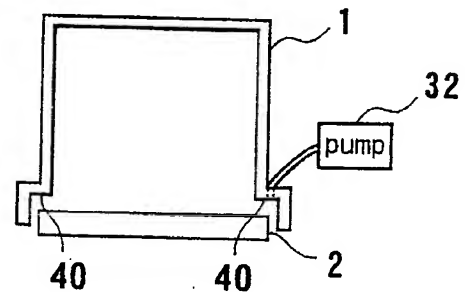


FIG. 29E

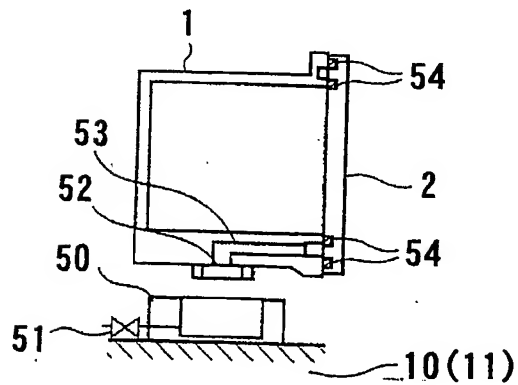
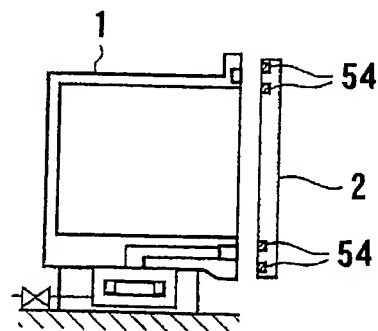


FIG. 29F



30/101

FIG. 30

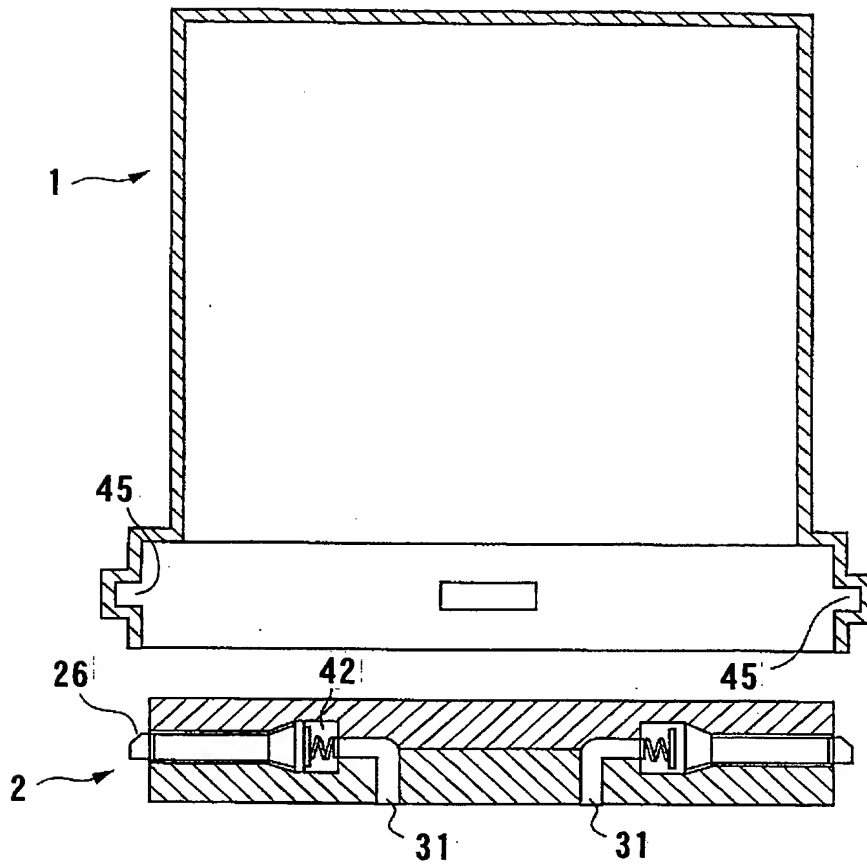


FIG. 31A

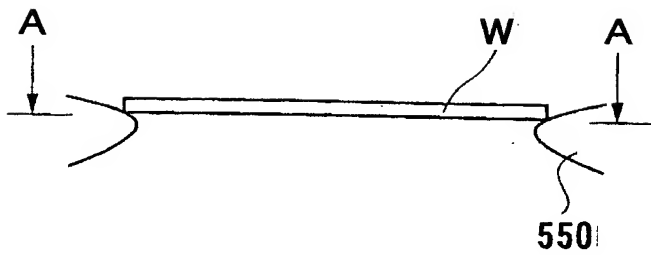


FIG. 31B

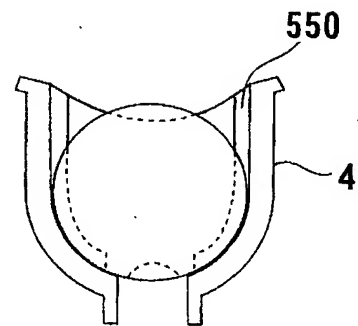


FIG. 32A

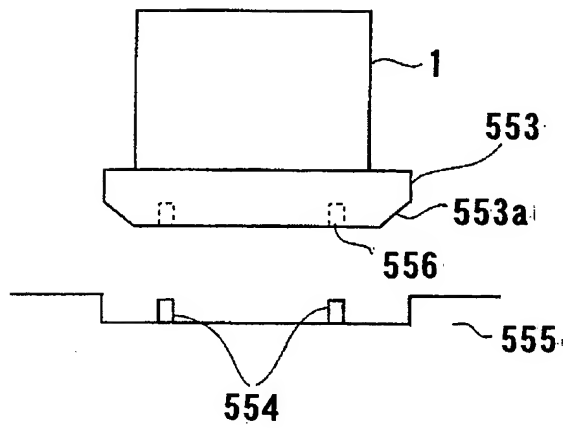


FIG. 32B

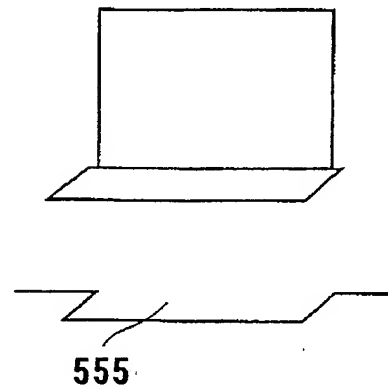


FIG. 32C

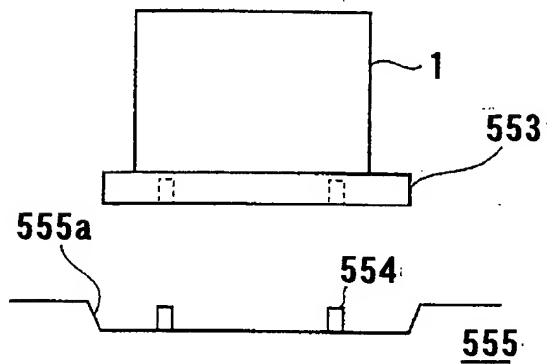


FIG. 33A

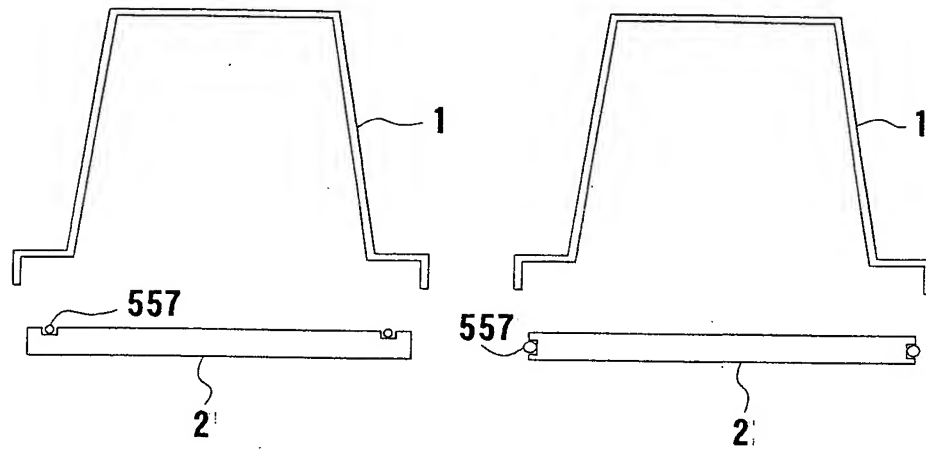


FIG. 33B

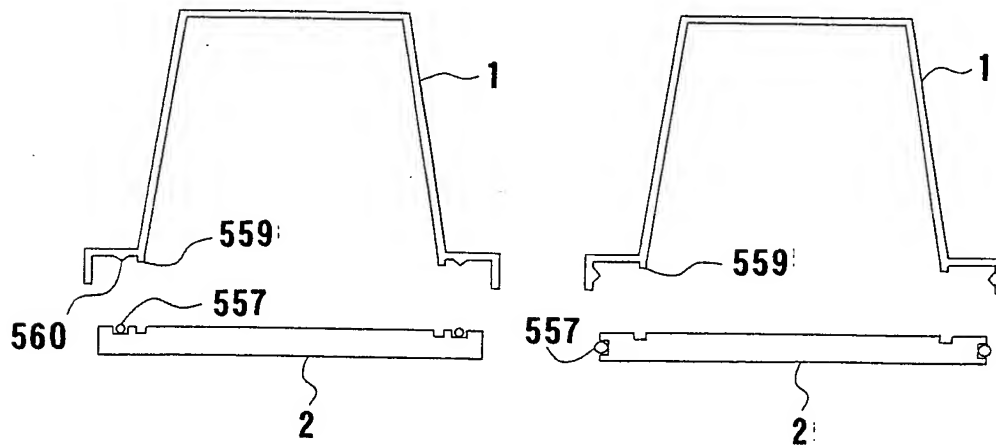


FIG. 34A

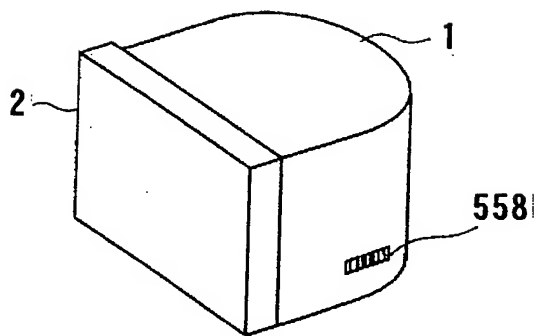


FIG. 34B

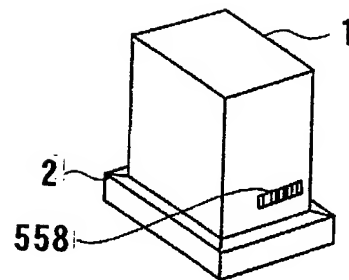


FIG. 35A

FIG. 35B

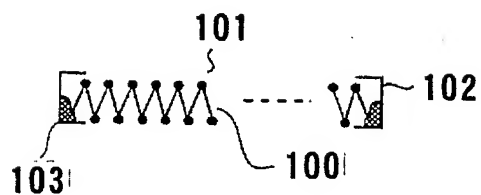
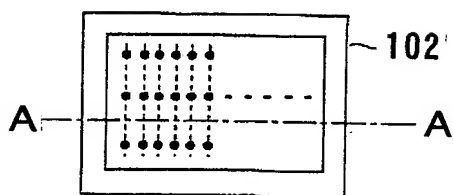


FIG. 35C



FIG. 36A

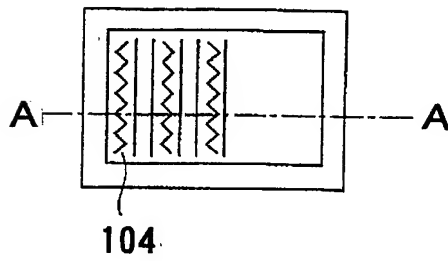


FIG. 36B

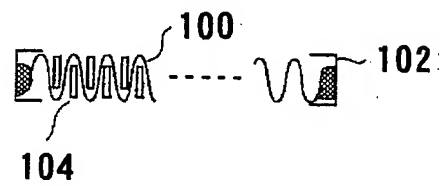
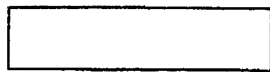
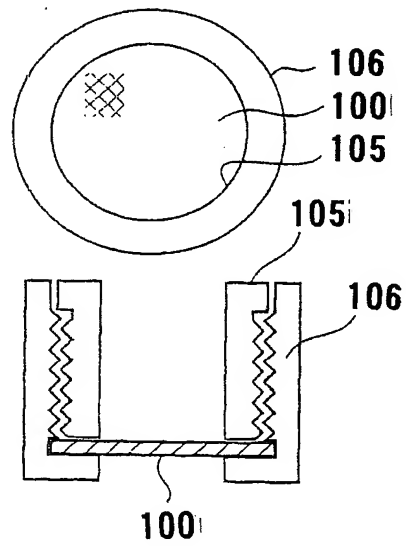


FIG. 36C



37/101

FIG. 37



38/101

FIG. 38

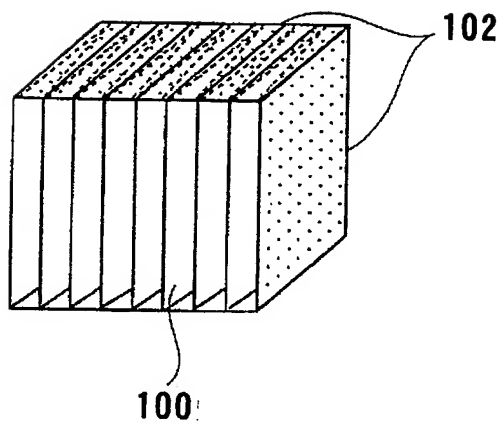


FIG. 39

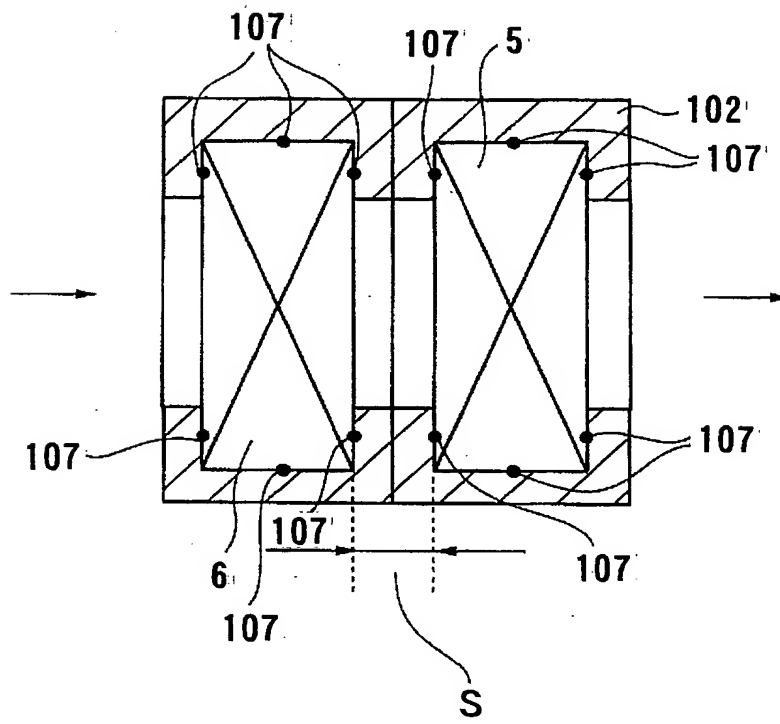


FIG. 40A

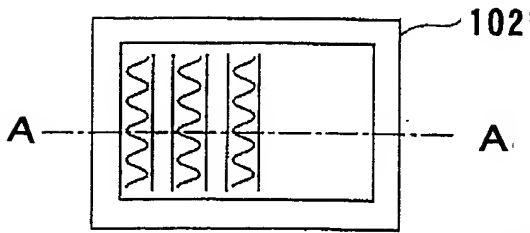


FIG. 40B

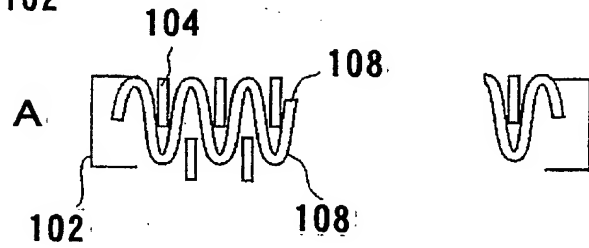


FIG. 40C



603422 "40/101"

41/101

FIG. 41

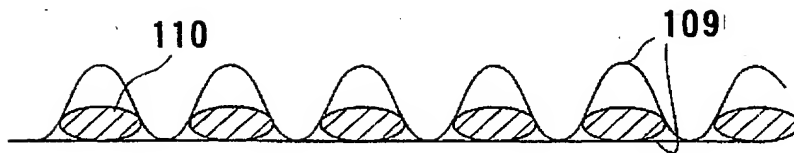


FIG. 42A

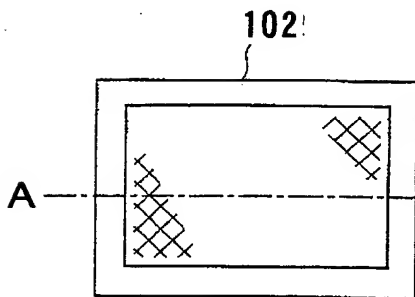


FIG. 42B

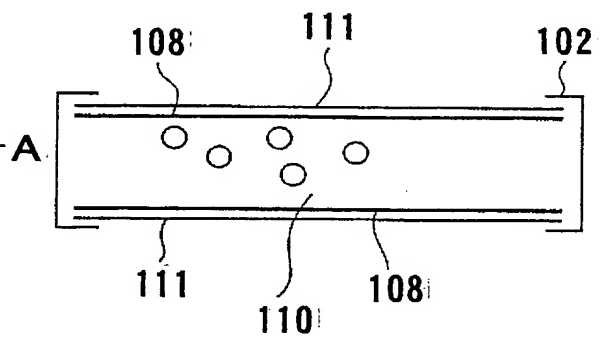


FIG. 42C



FIG. 43A

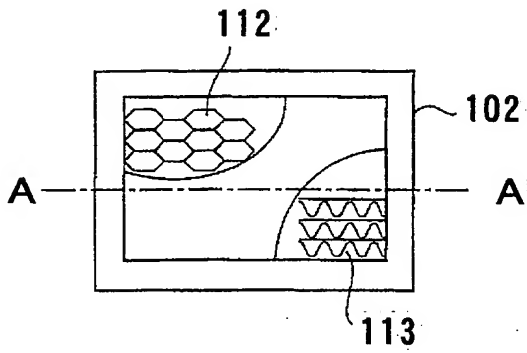


FIG. 43B

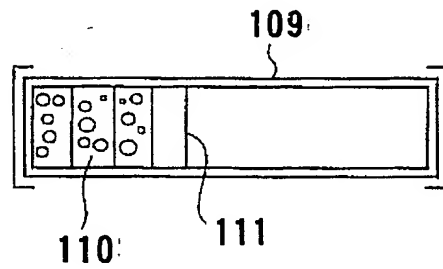


FIG. 43C



FIG. 44A

FIG. 44B

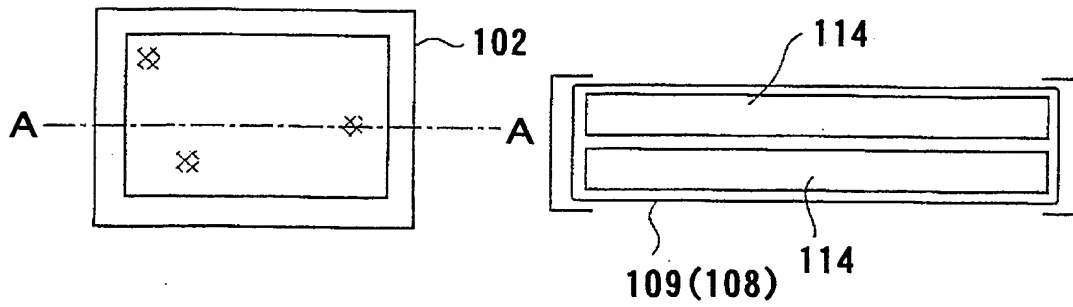


FIG. 44C



2025 RELEASE UNDER E.O. 14176

45/101

FIG. 45A

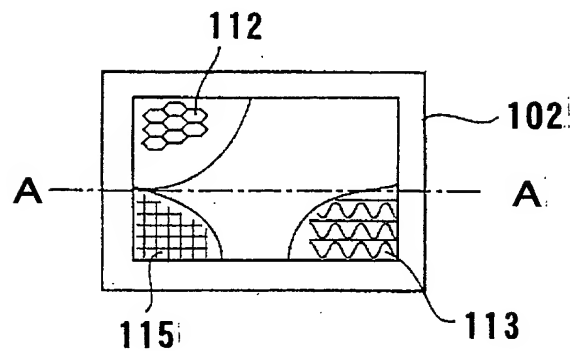


FIG. 45B



FIG. 46A

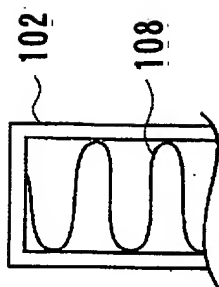


FIG. 46C

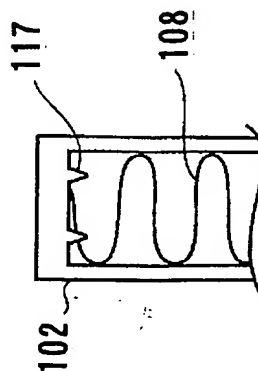


FIG. 46B

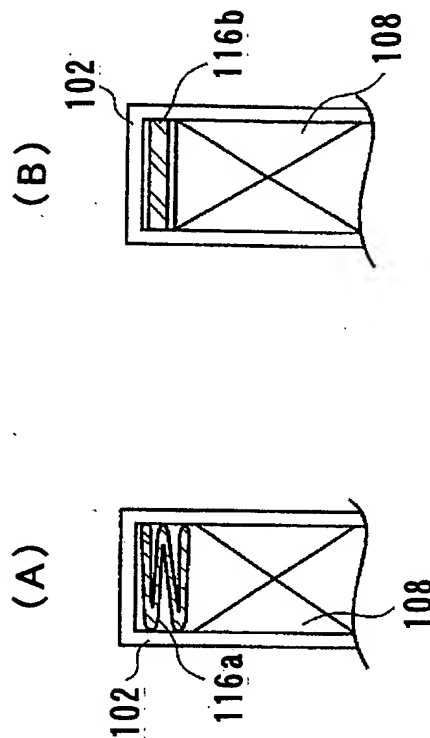
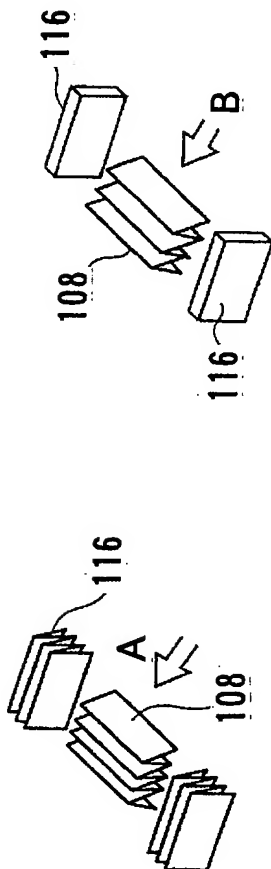


FIG. 47

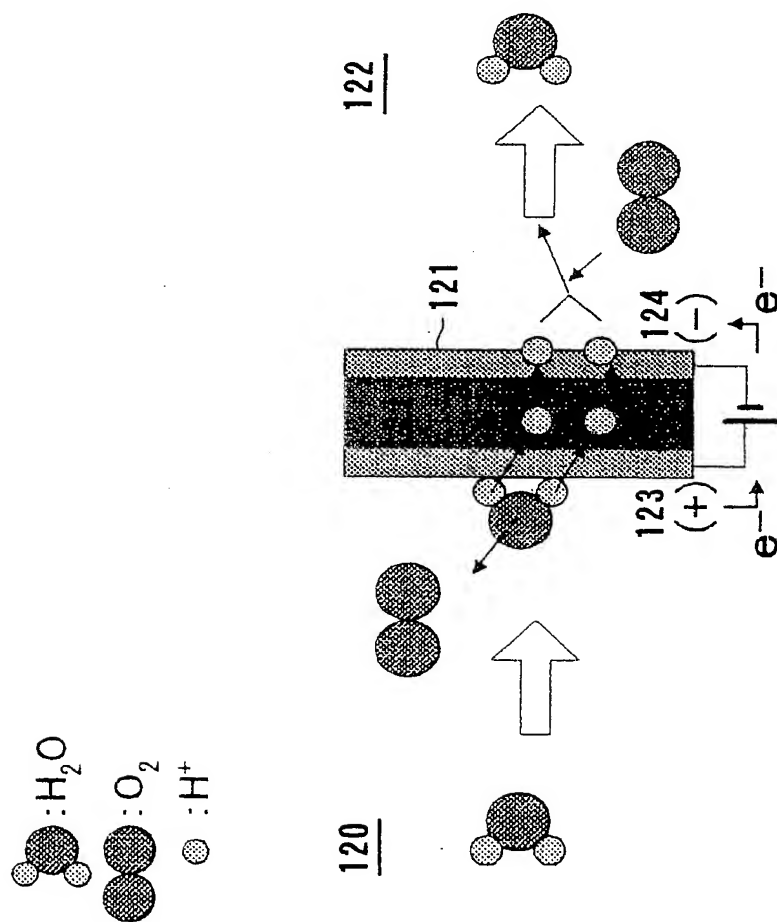
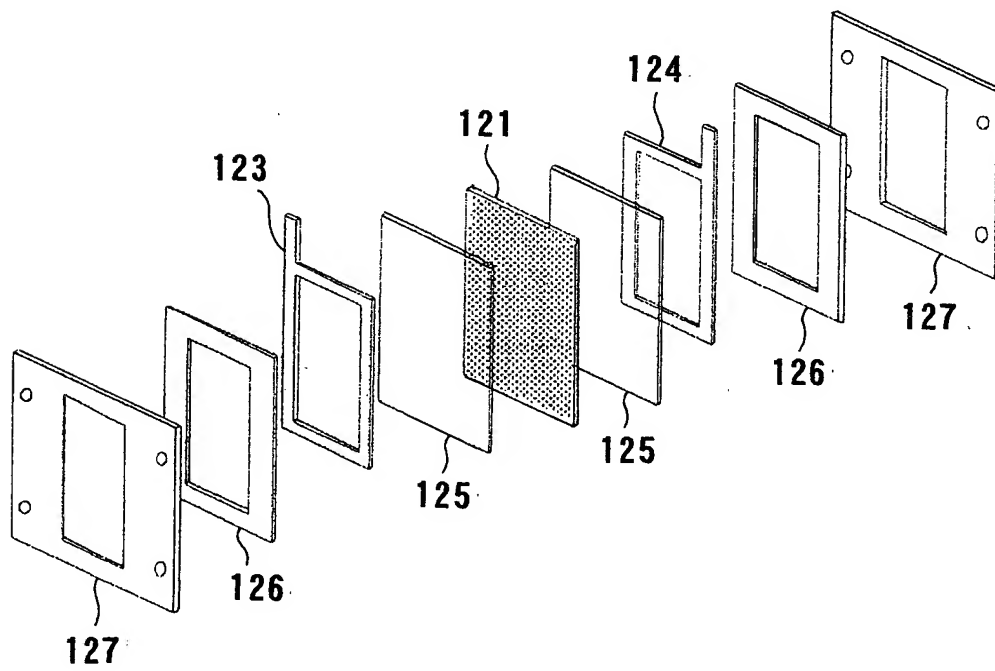
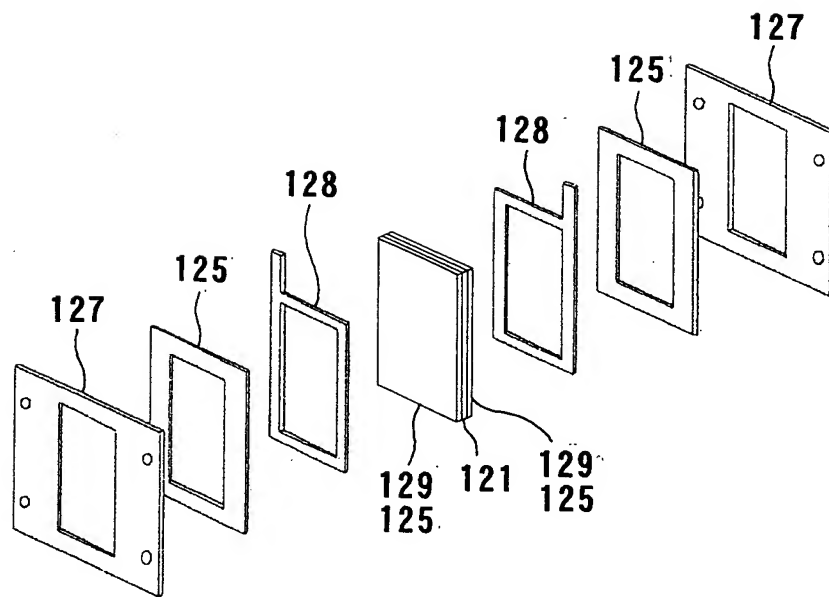


FIG. 48



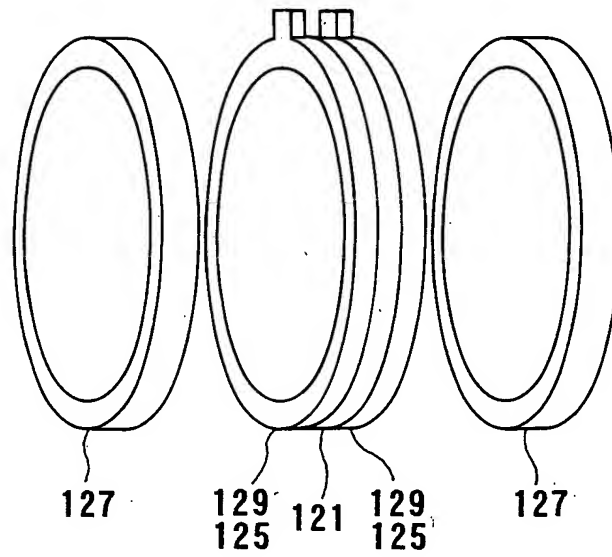
49/101

FIG. 49



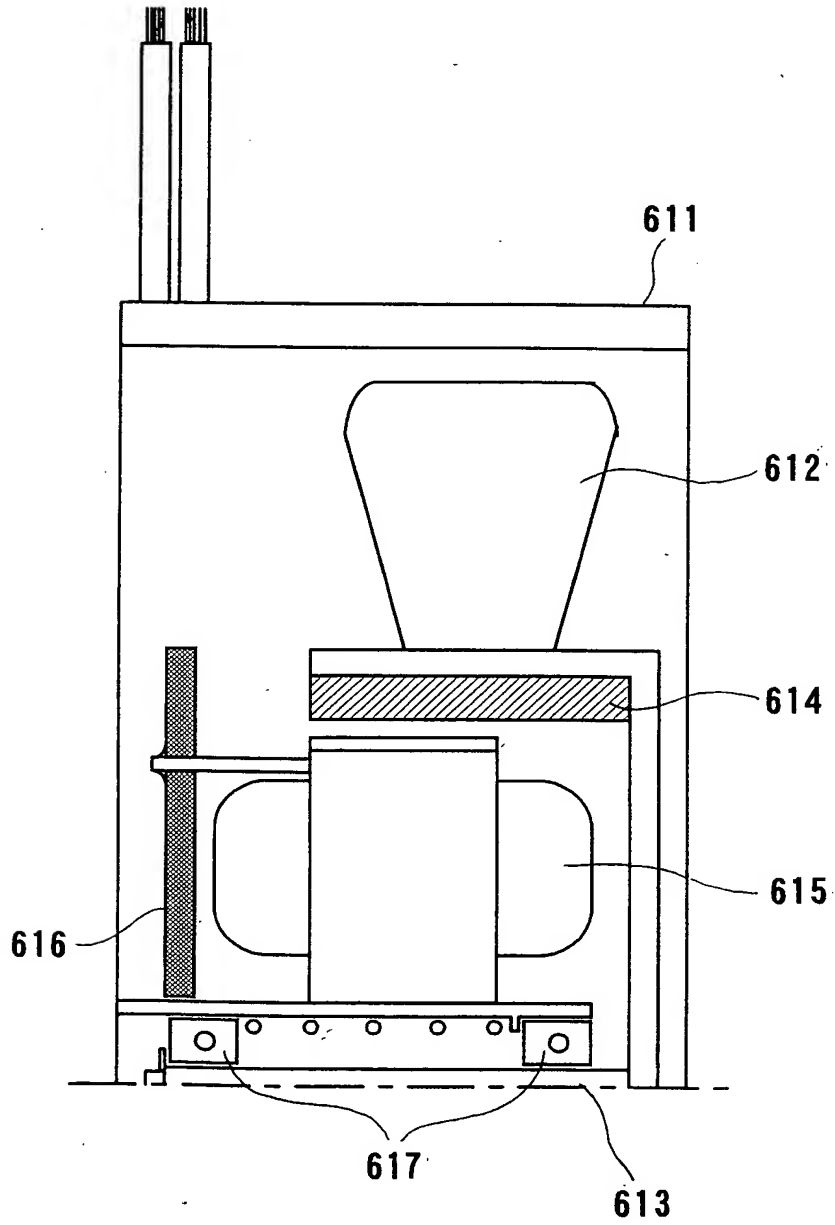
50/101

FIG. 50



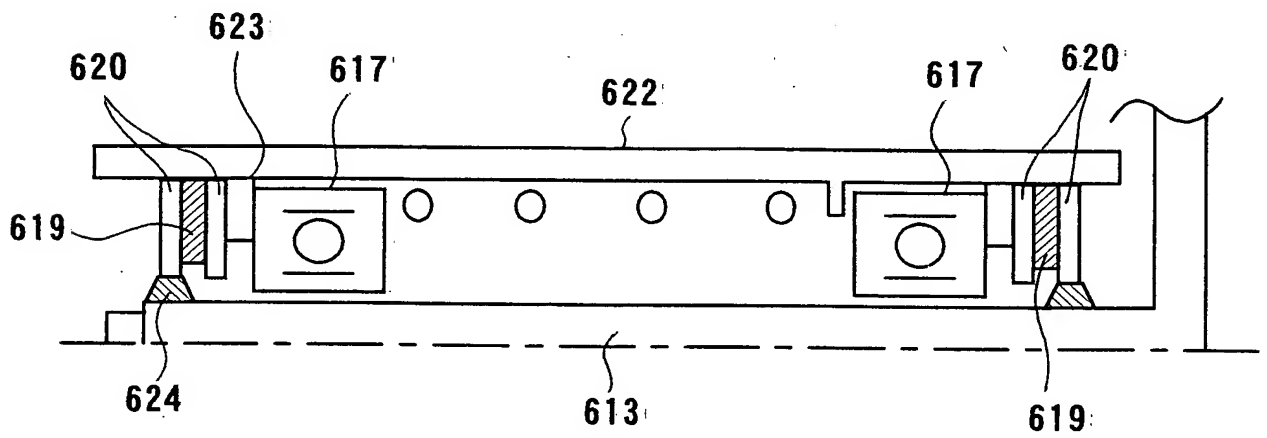
51/101

FIG. 51



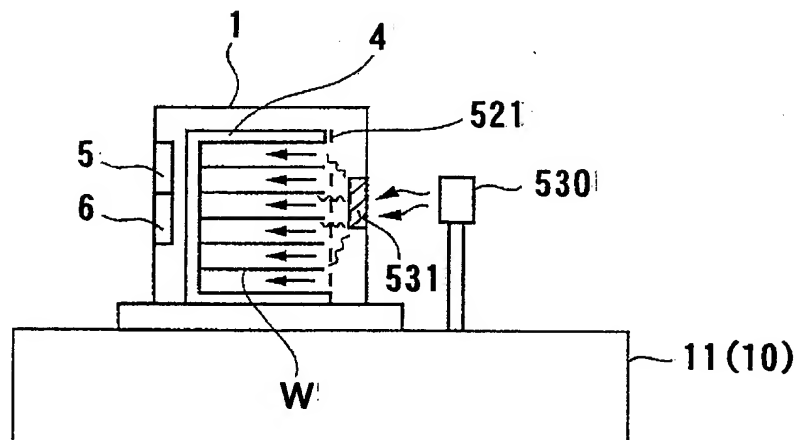
52/101

FIG. 52



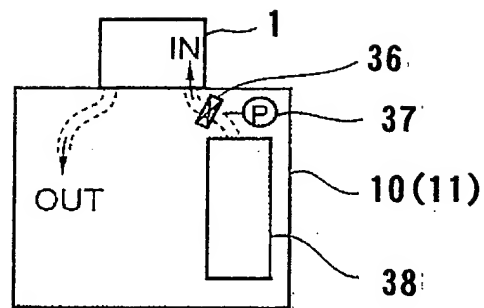
53/101

FIG. 53



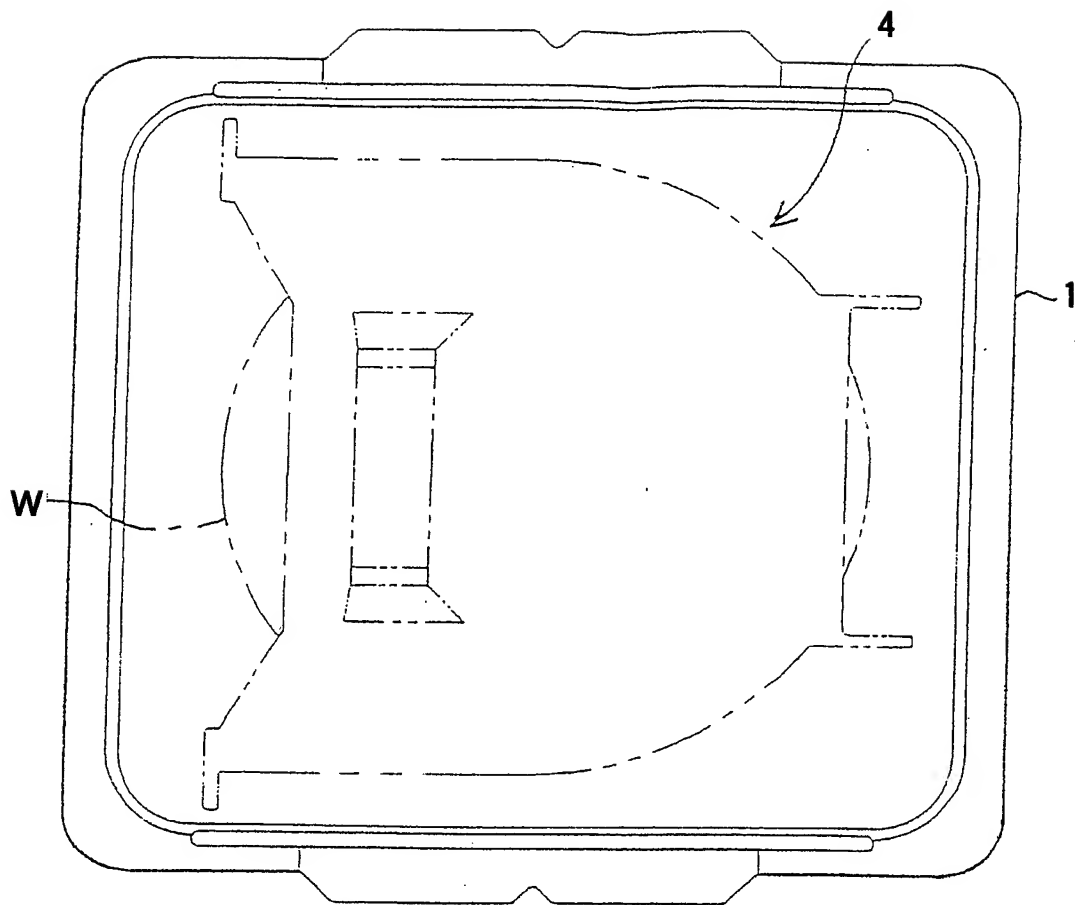
54/101

FIG. 54



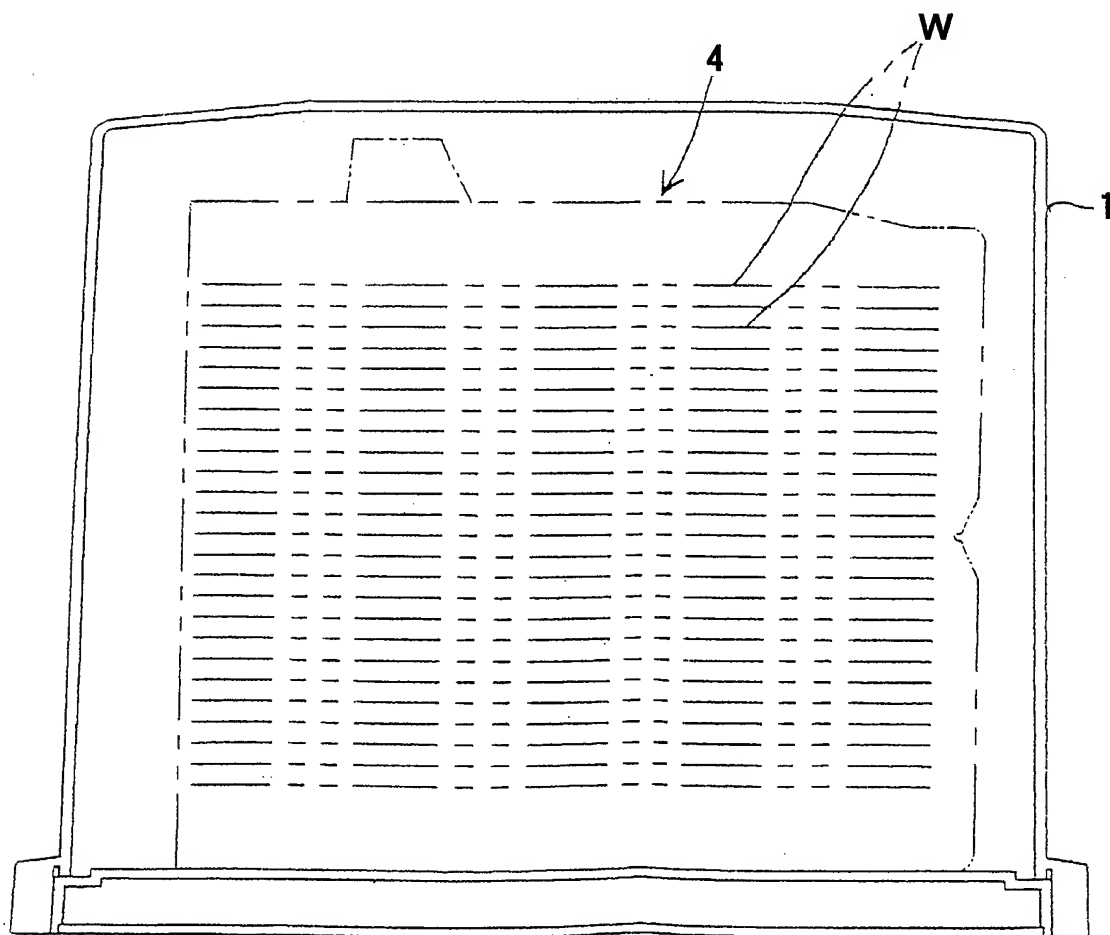
55/101

FIG. 55



56/101

FIG. 56



57/101

FIG. 57A

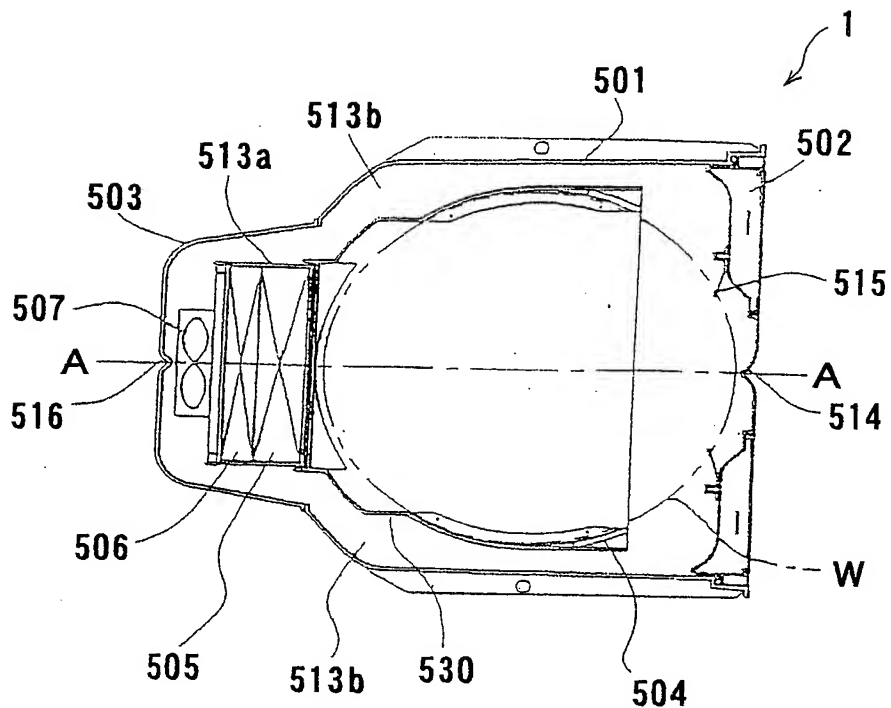
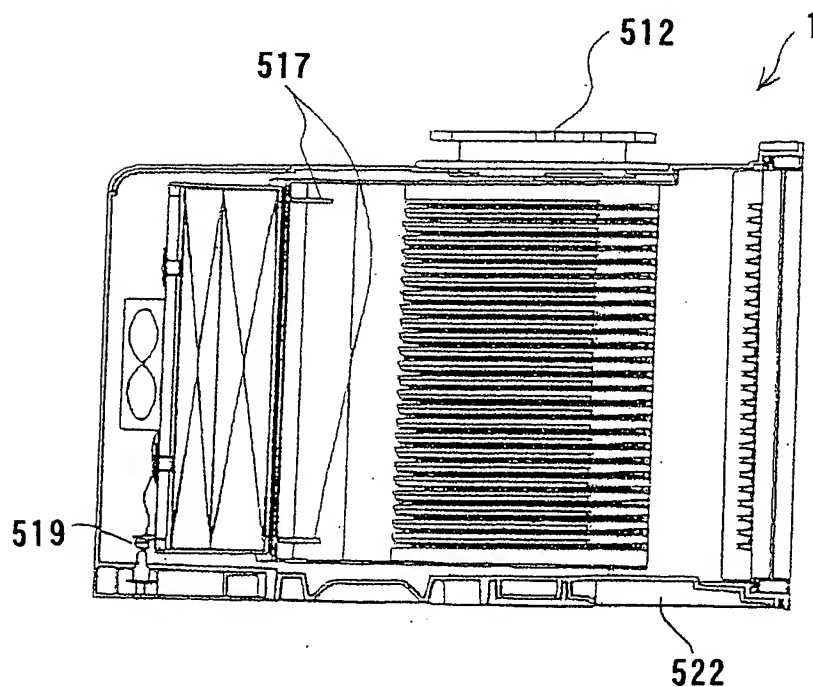


FIG. 57B



58/101

FIG. 58A

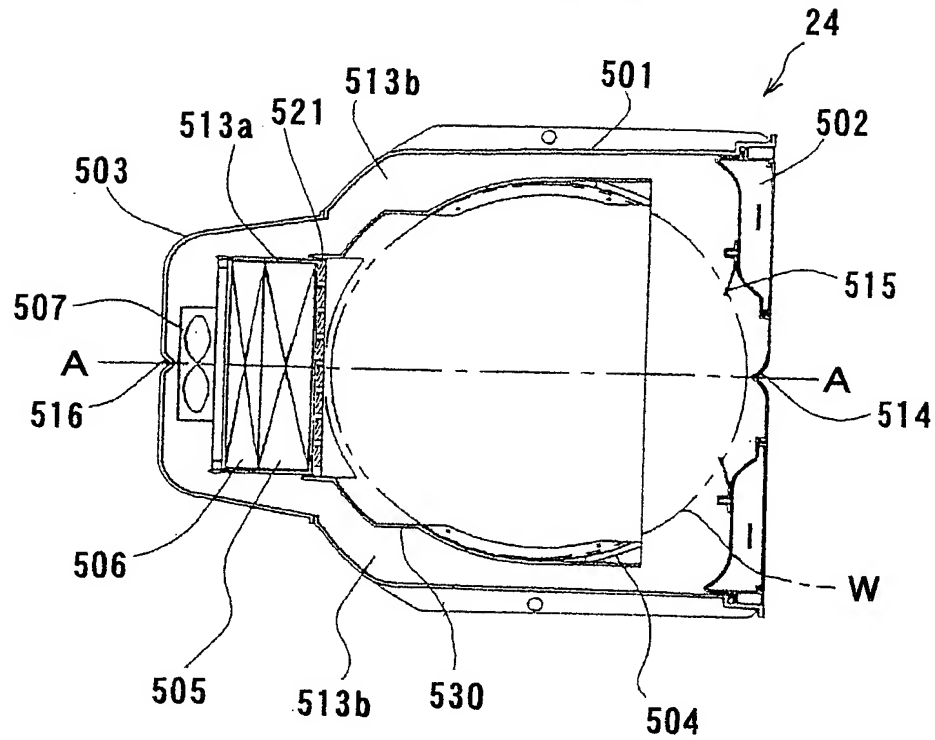
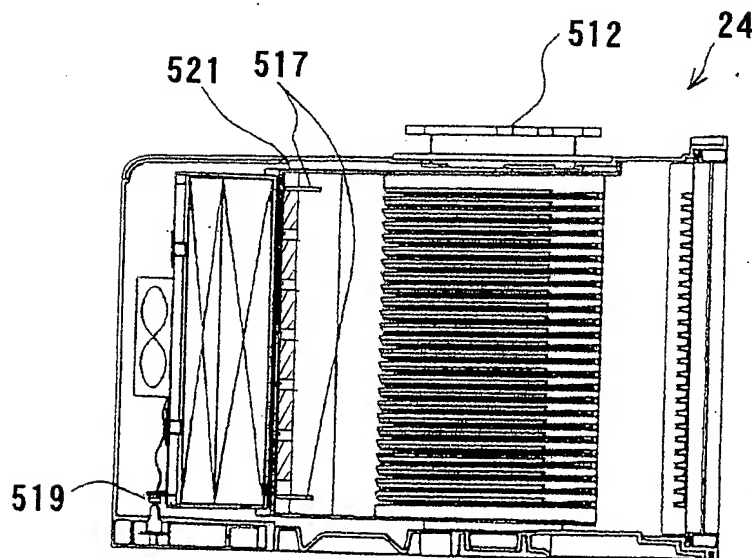


FIG. 58B



59/101

FIG. 59A

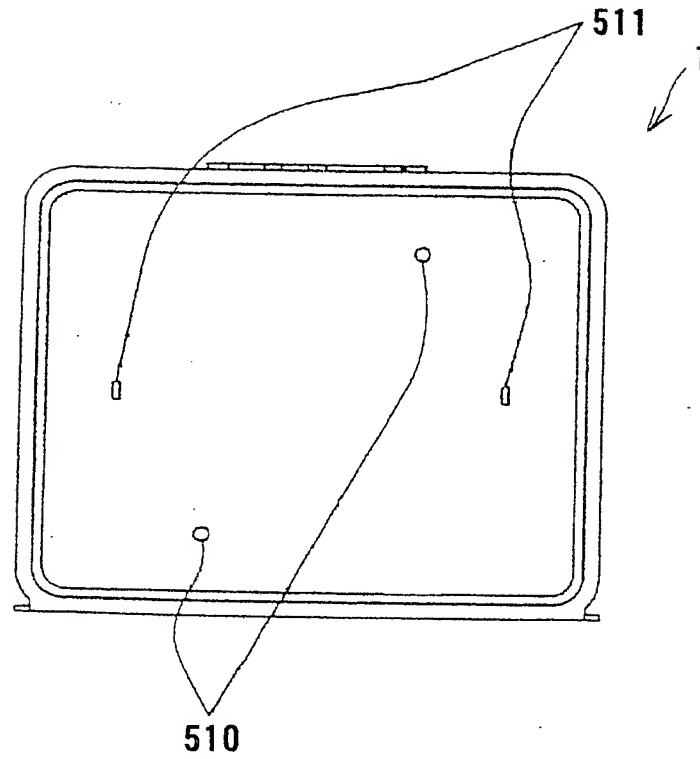
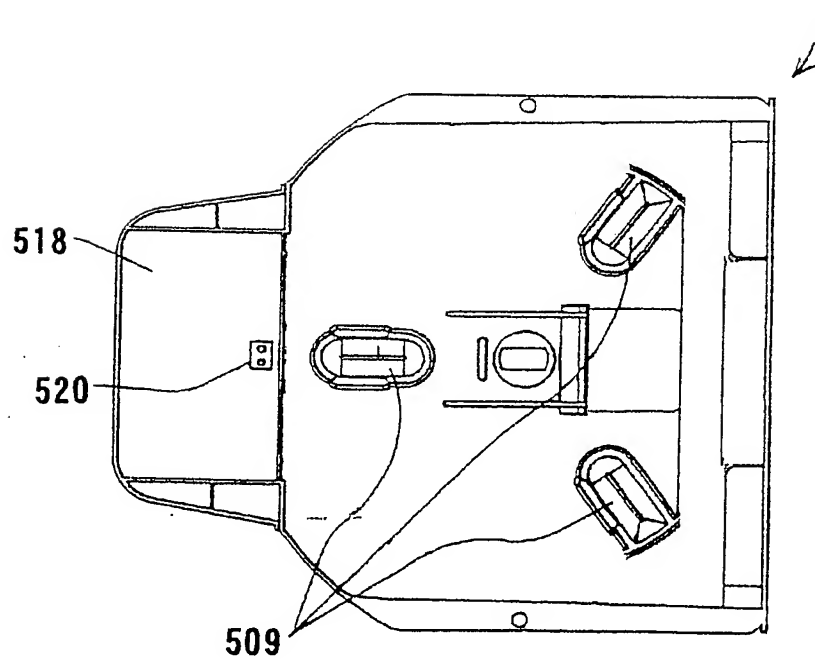


FIG. 59B



60/101

FIG. 60A

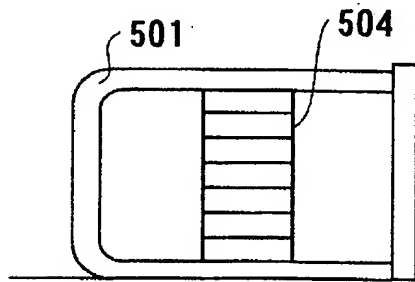


FIG. 60B

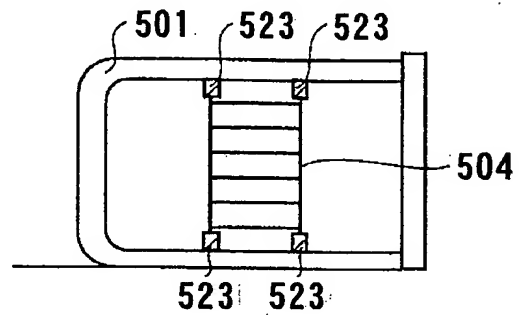


FIG. 60C

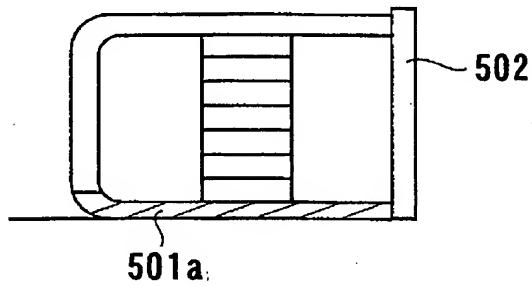


FIG. 60D

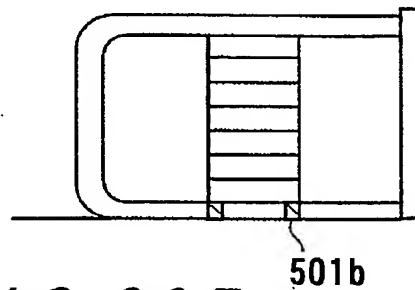


FIG. 60E

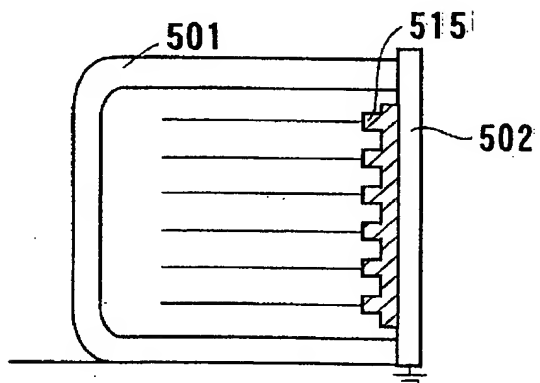


FIG. 60F

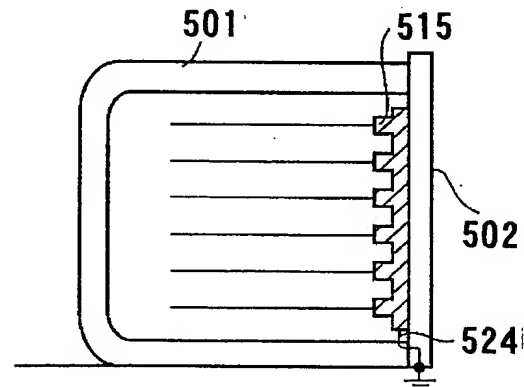


FIG. 60G

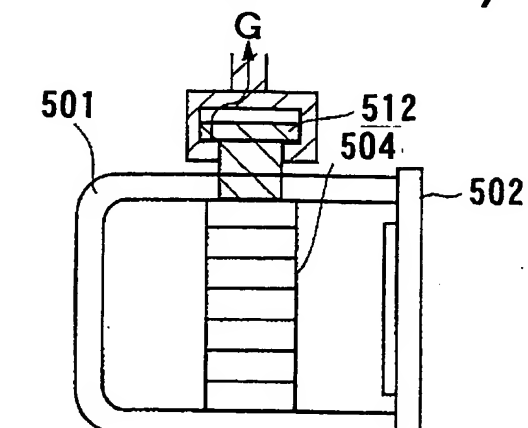
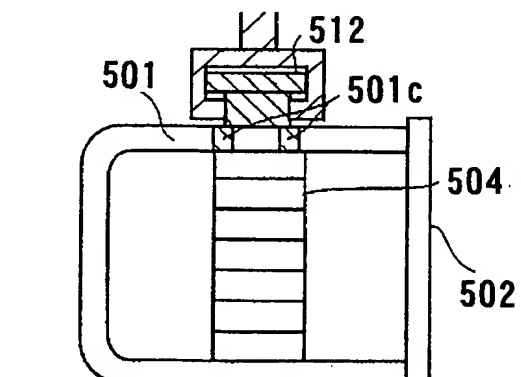
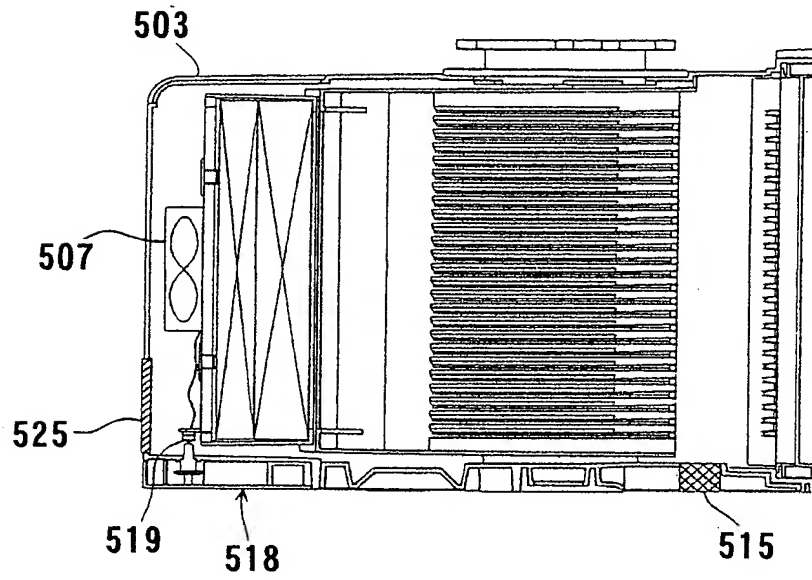


FIG. 60H



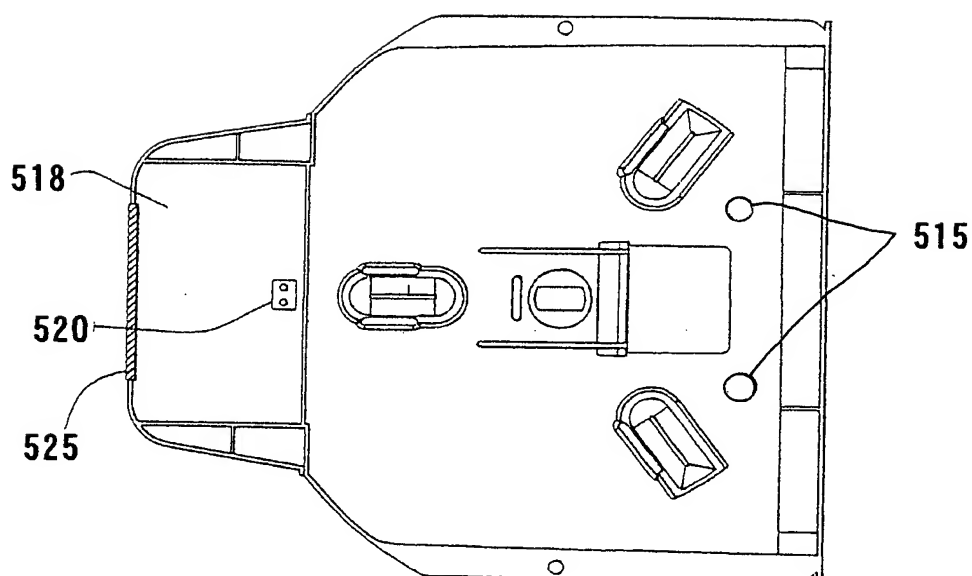
62/101

FIG. 62



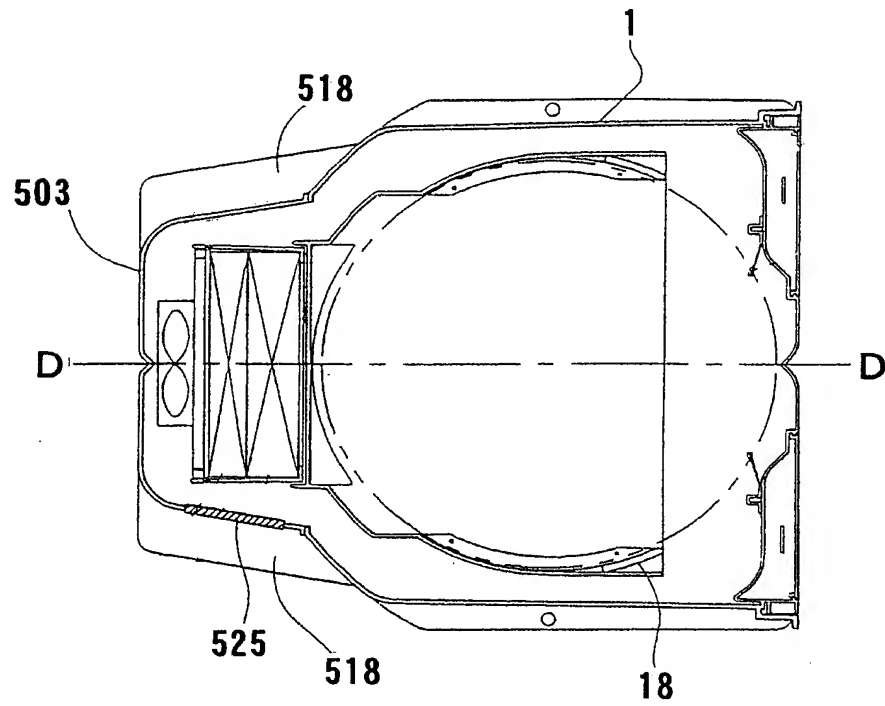
63/101

FIG. 63



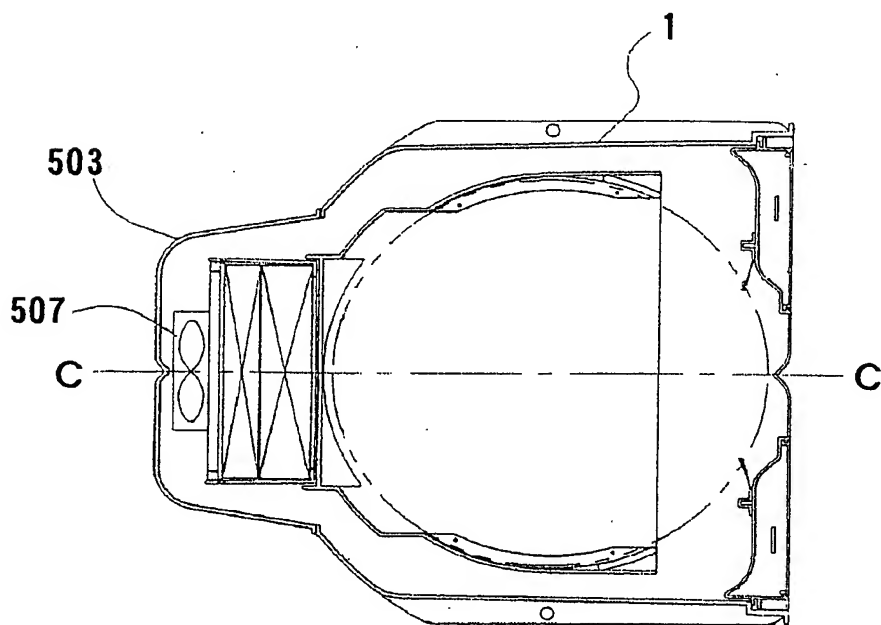
64/101

FIG. 64



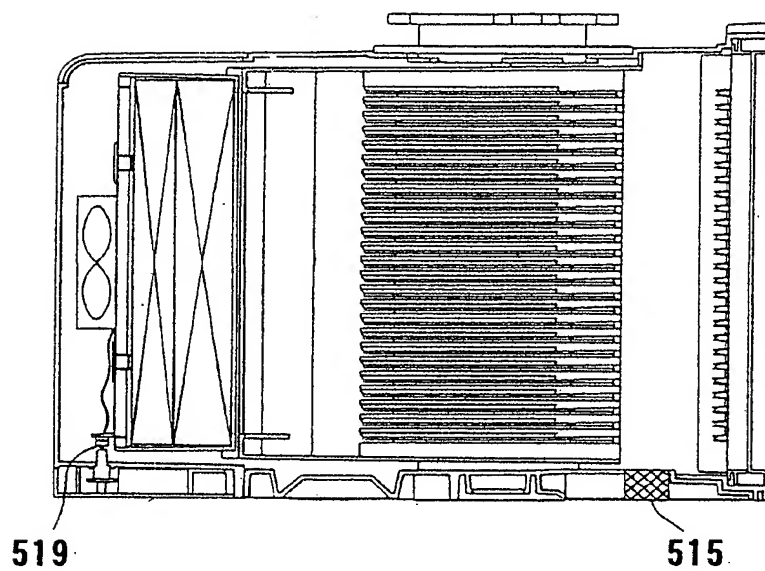
61/101

FIG. 61



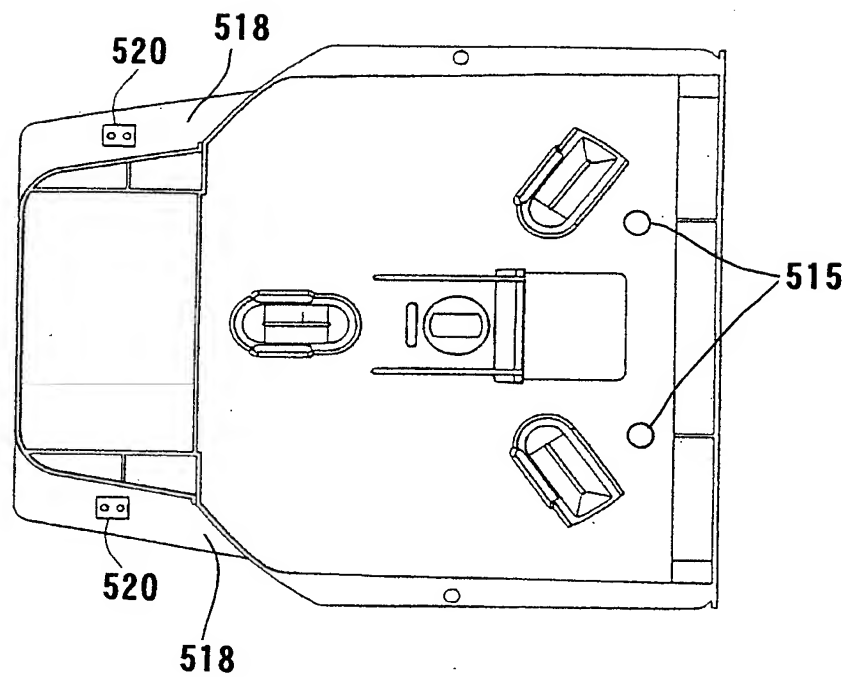
65/101

FIG. 65



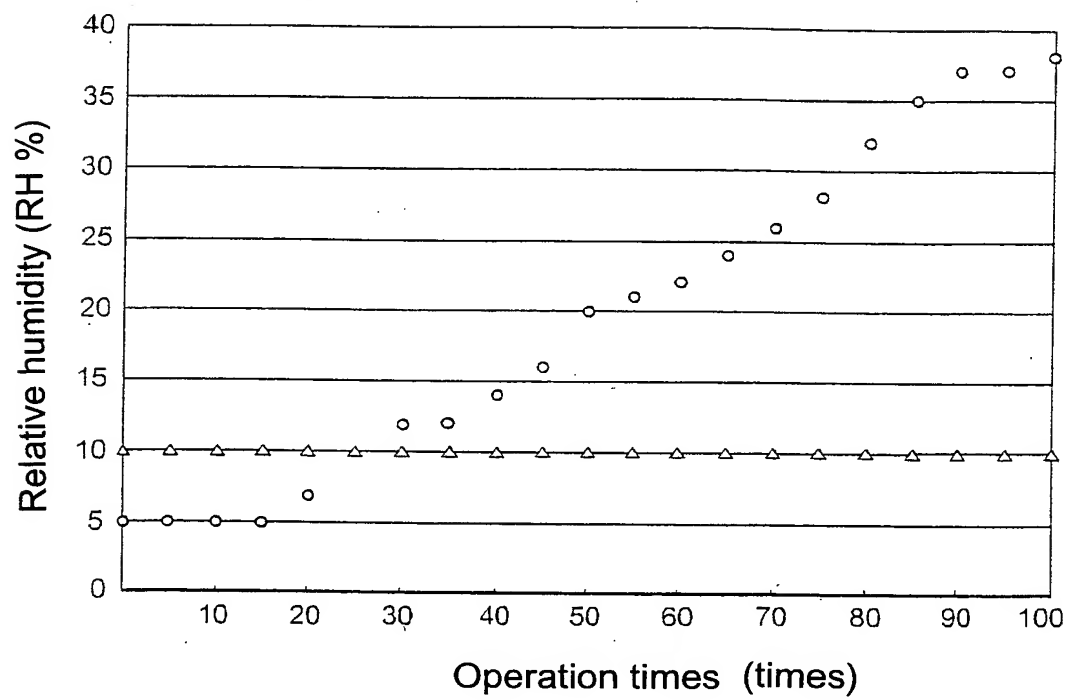
66/101

FIG. 66



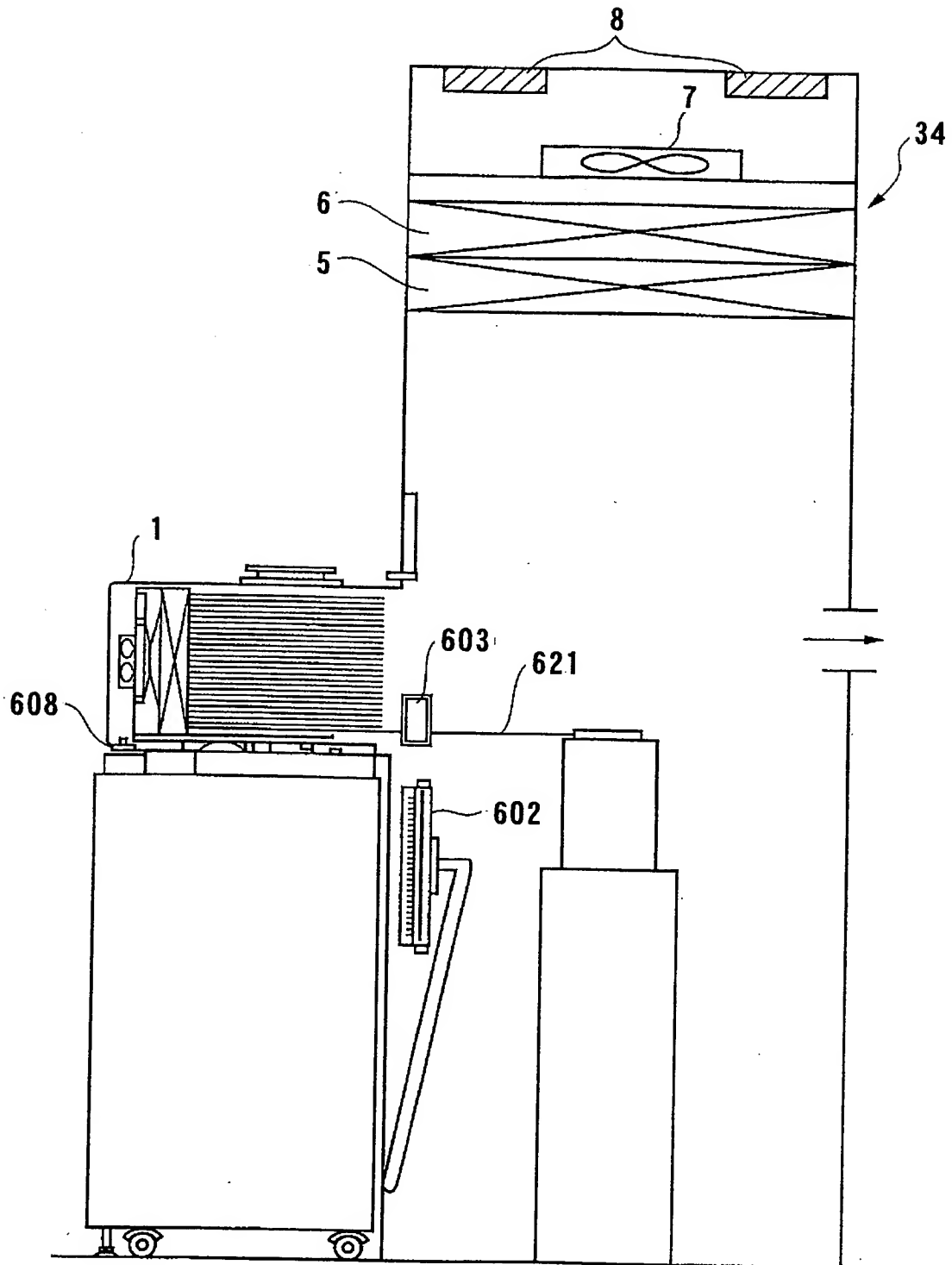
67/101

FIG. 67



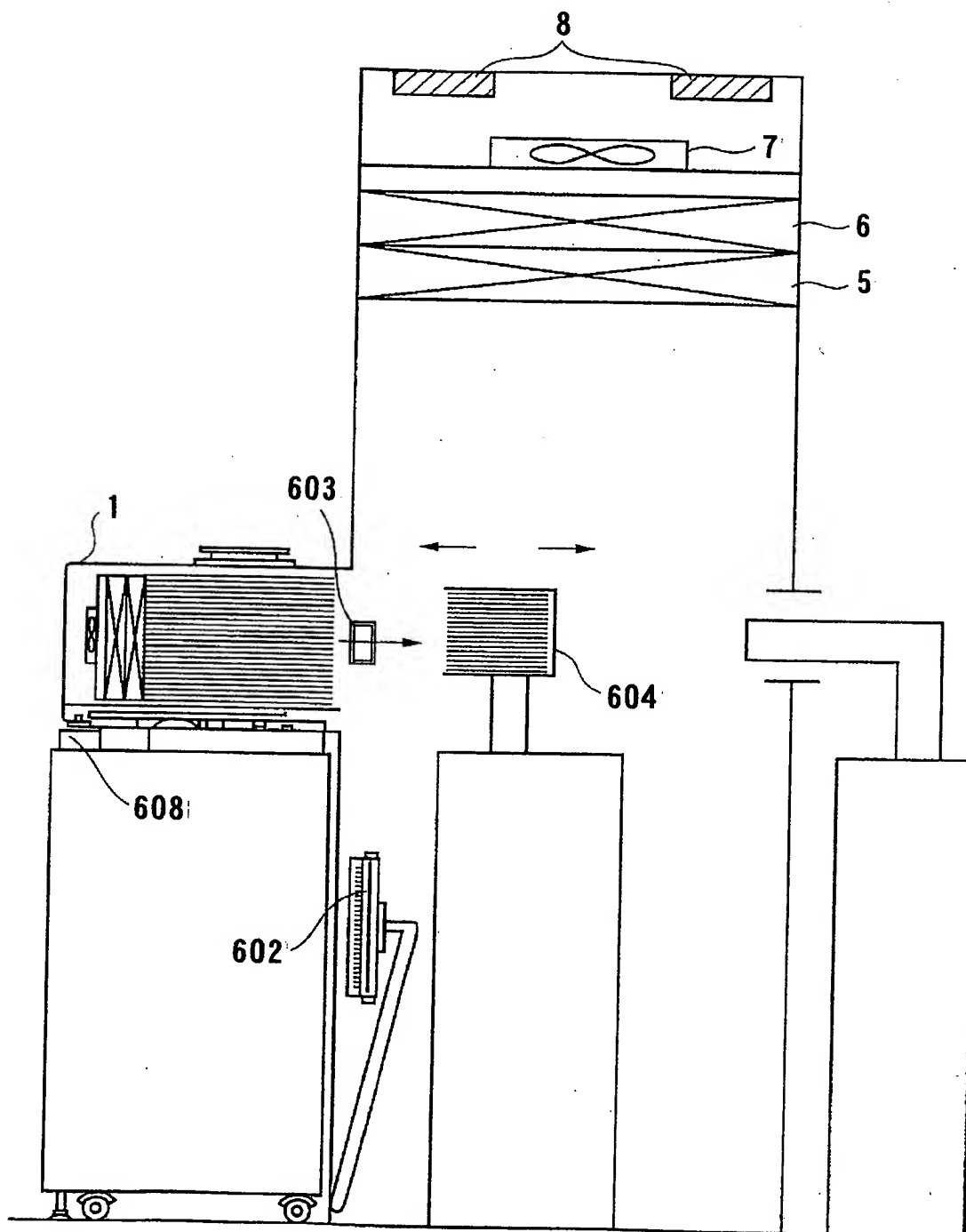
68/101

FIG. 68



69/101

FIG. 69



70/101

FIG. 70A

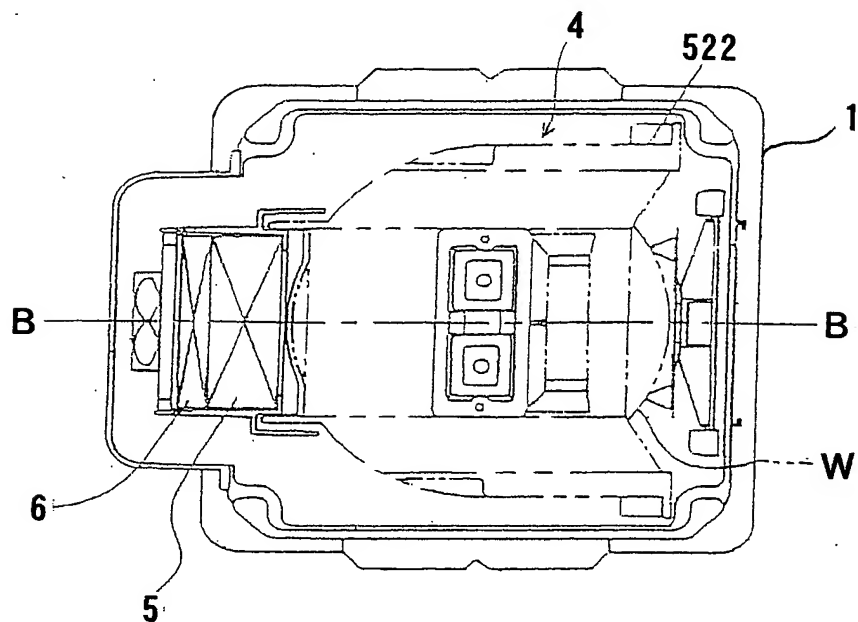
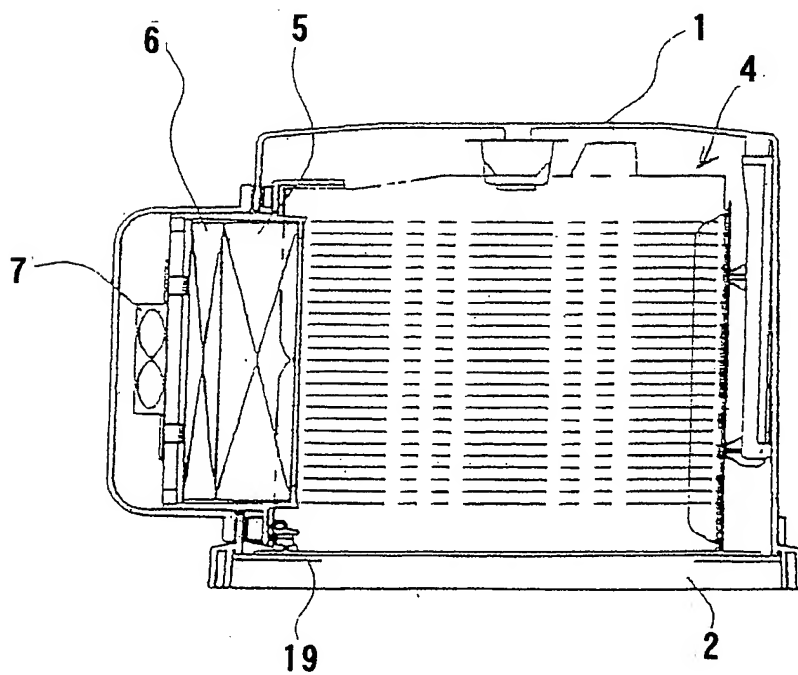


FIG. 70B



[illegible]

71/101

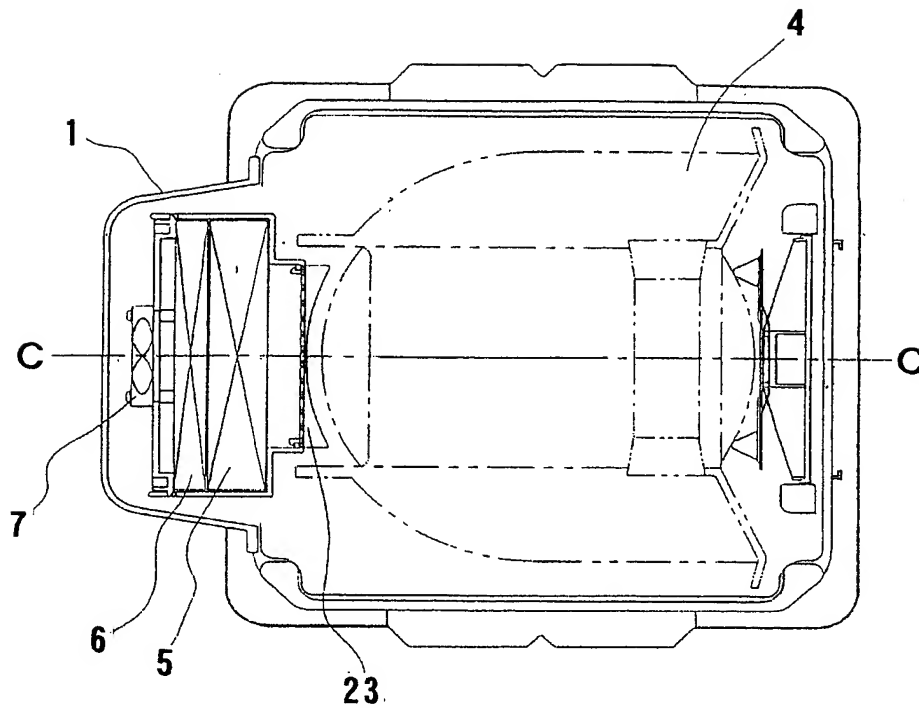
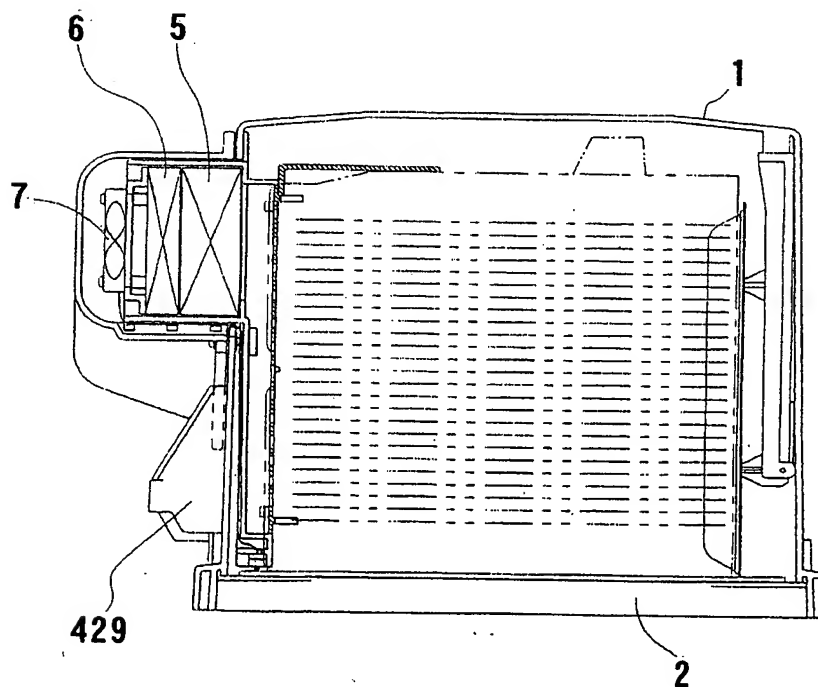
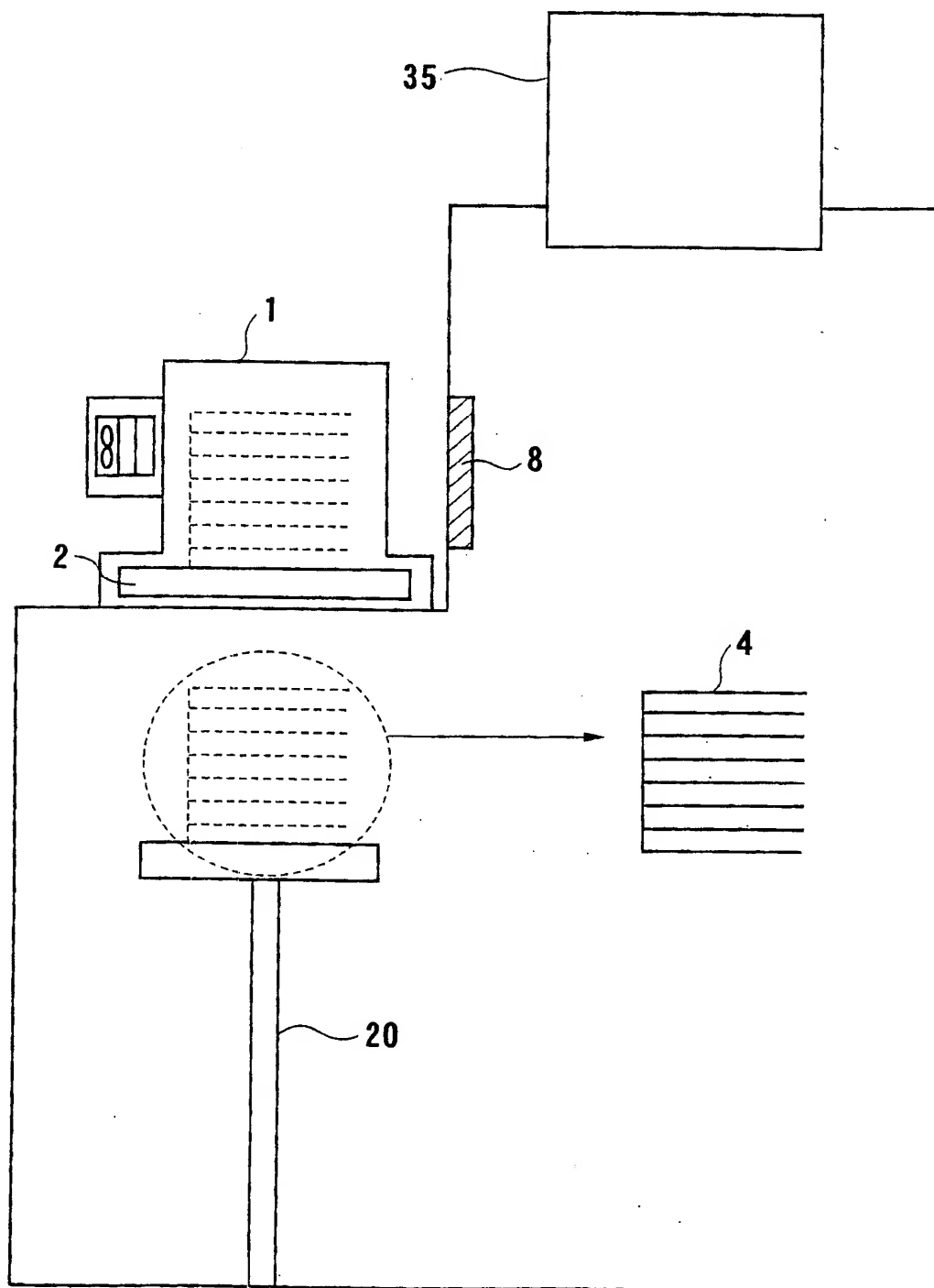


FIG. 71B



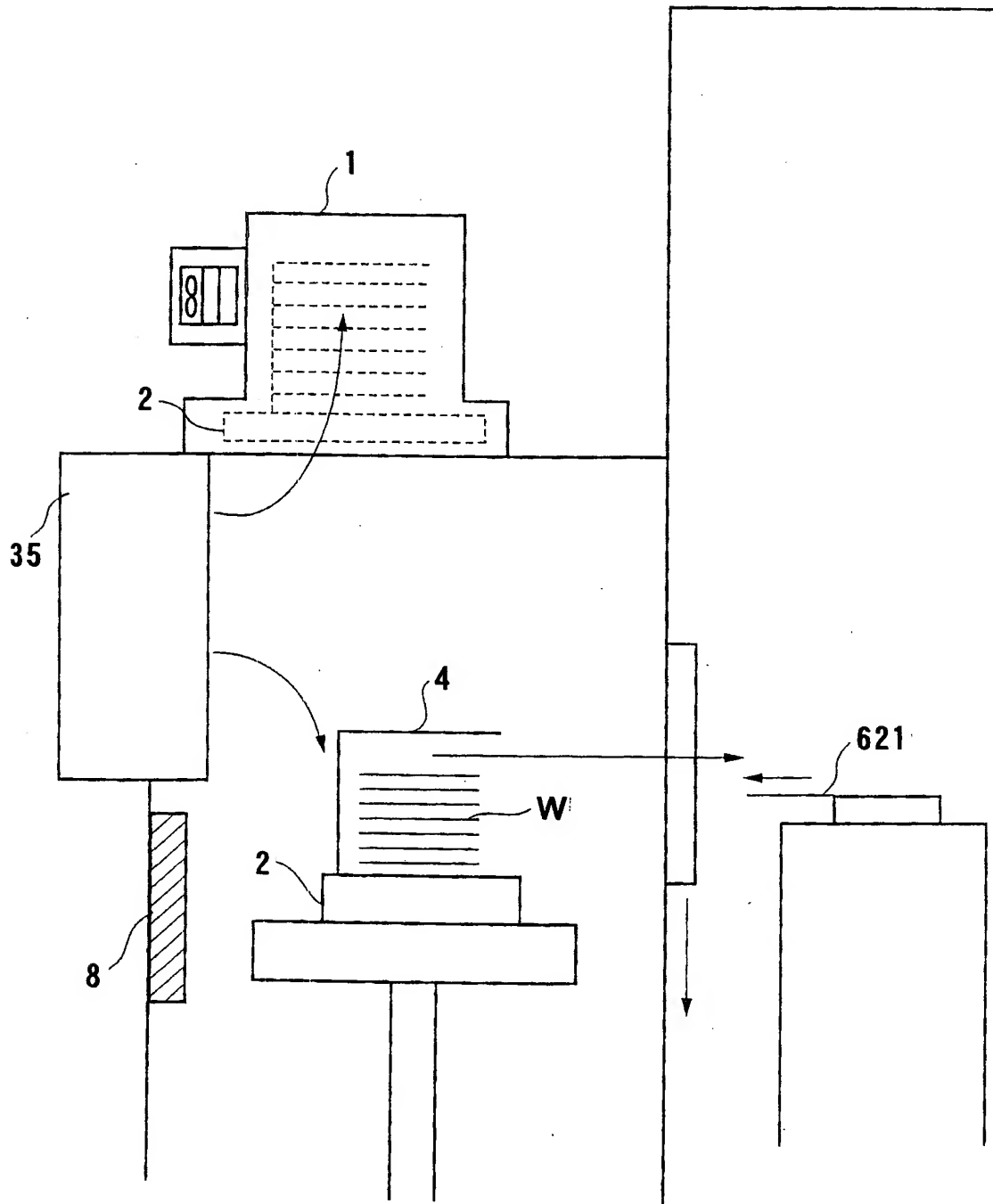
72/101

FIG. 72



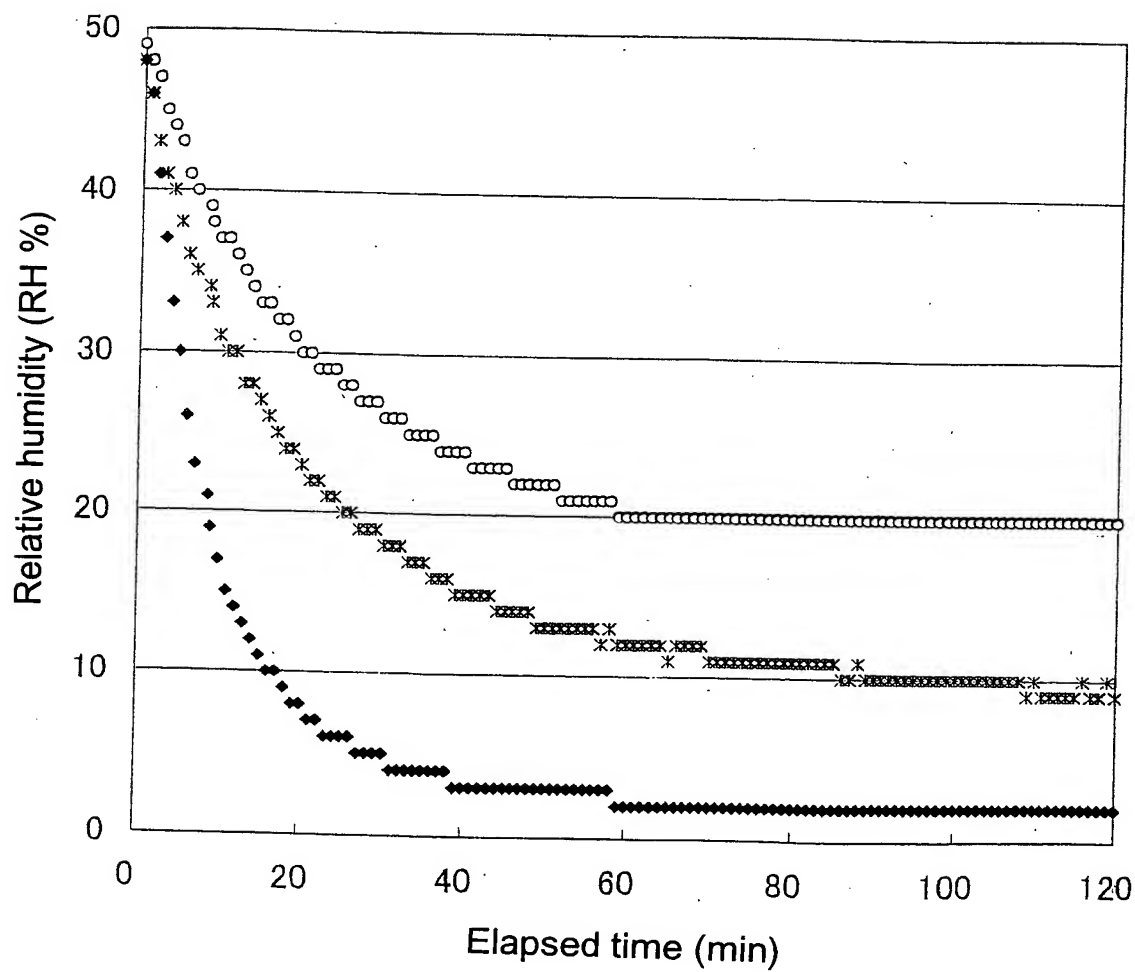
73/101

FIG. 73



74/101

FIG. 74



75/101

FIG. 75

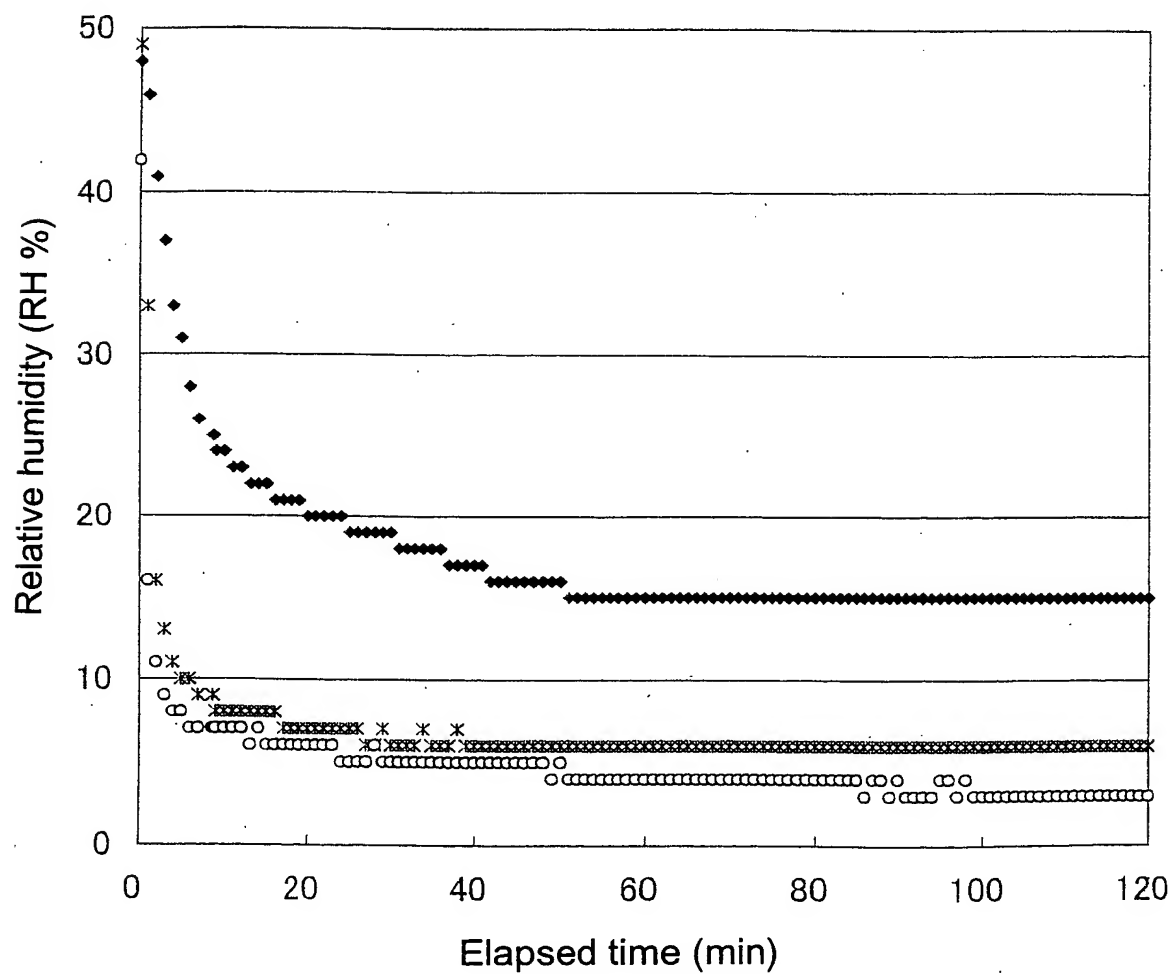


FIG. 76.

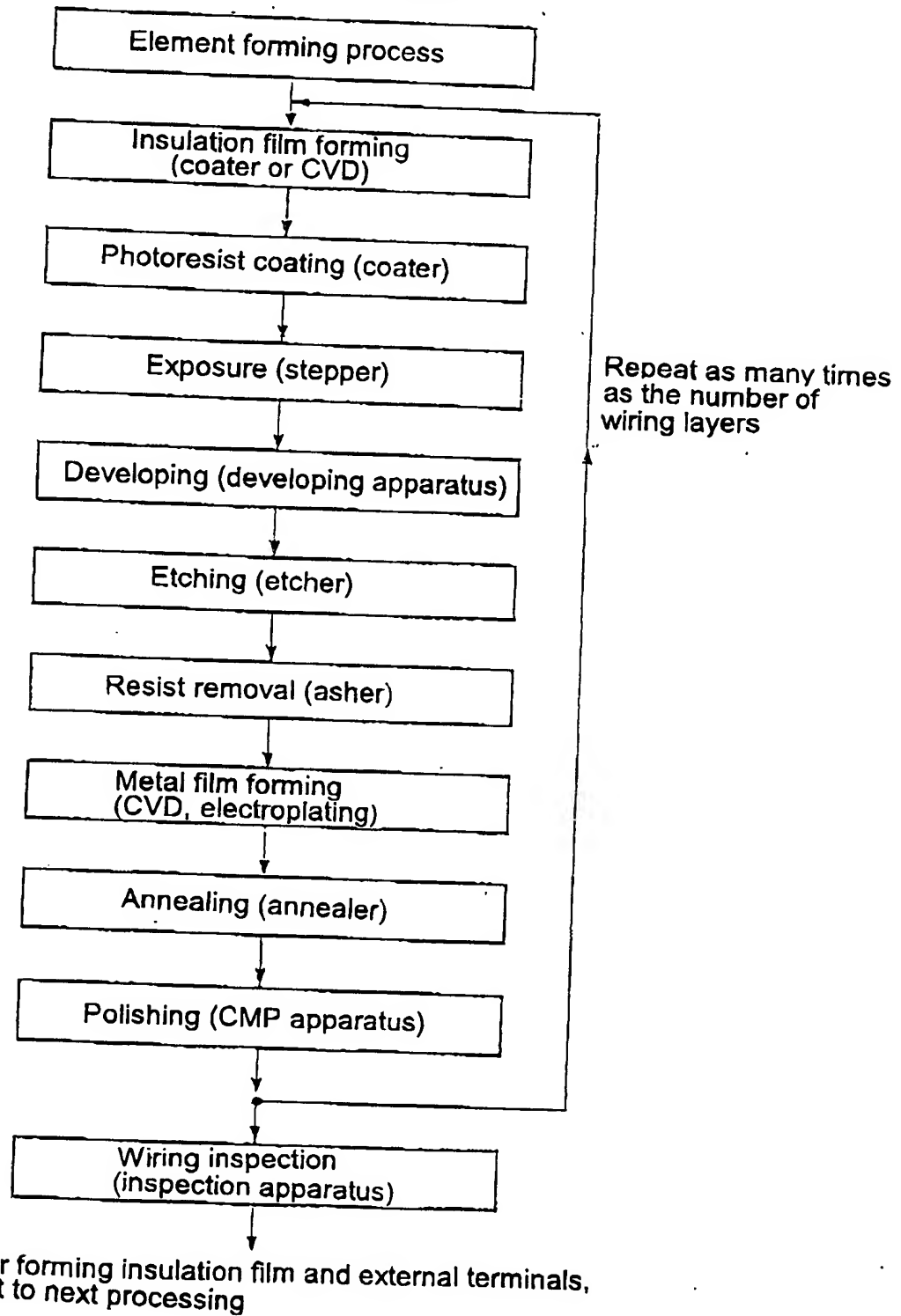
SEMICONDUCTOR MANUFACTURING
PROCESS FLOWCHART

FIG. 76

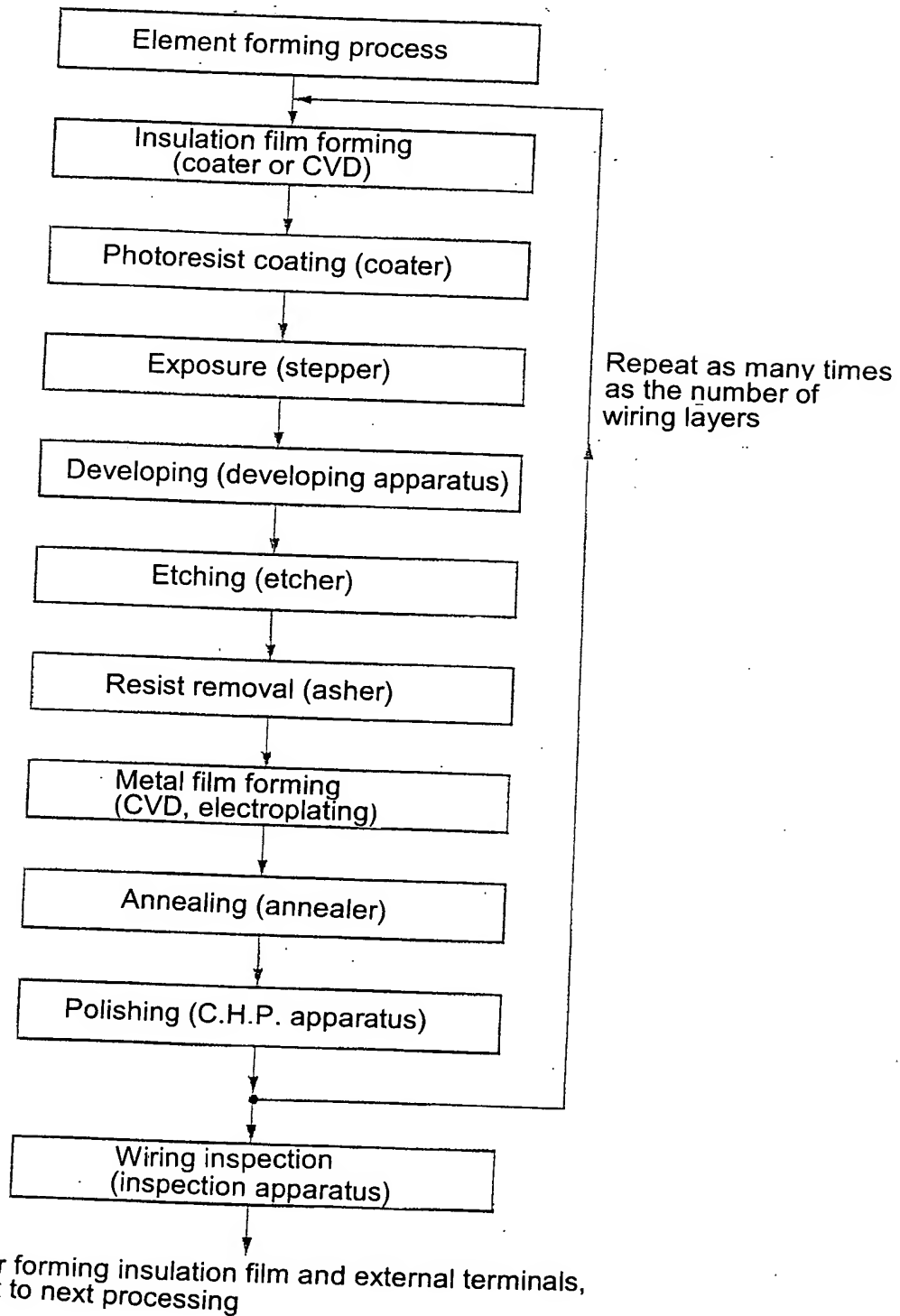
SEMICONDUCTOR MANUFACTURING
PROCESS FLOWCHART

FIG. 77A

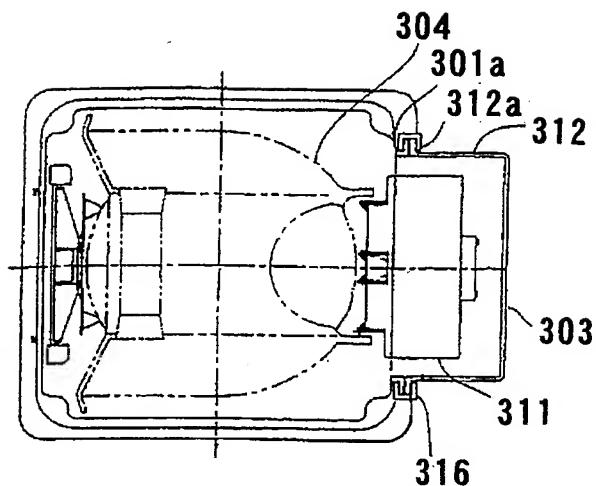


FIG. 77B

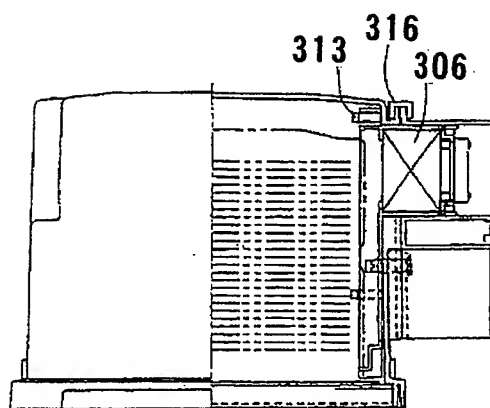


FIG. 77C

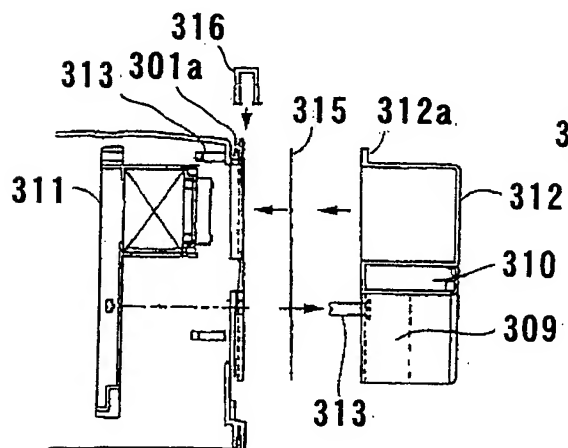


FIG. 77D

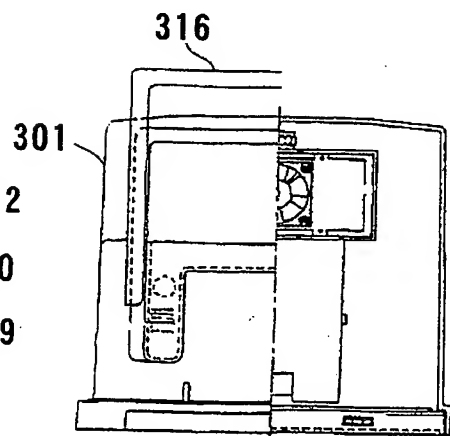


FIG. 78A

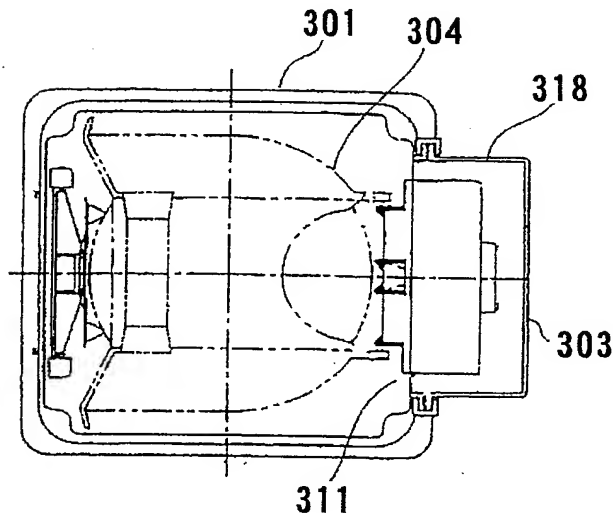


FIG. 78B

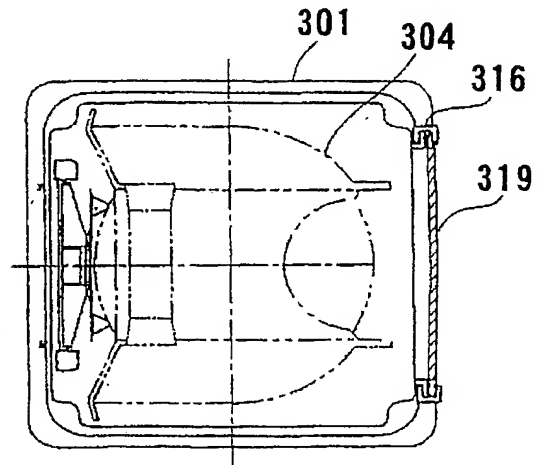


FIG. 78C

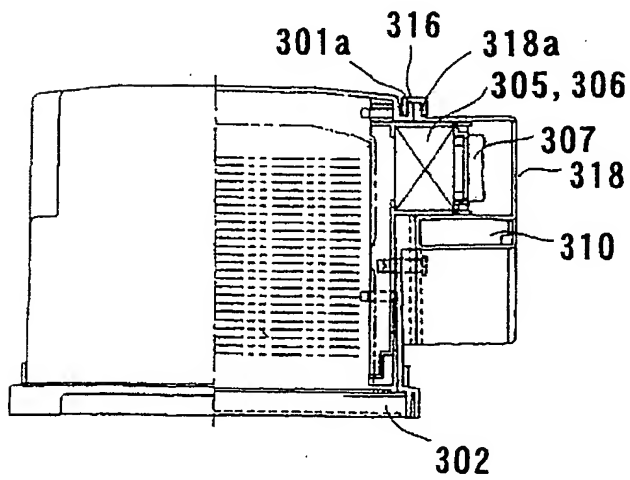


FIG. 78D

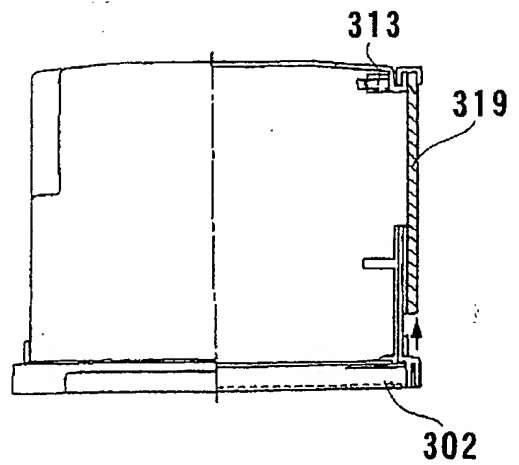


FIG. 79A

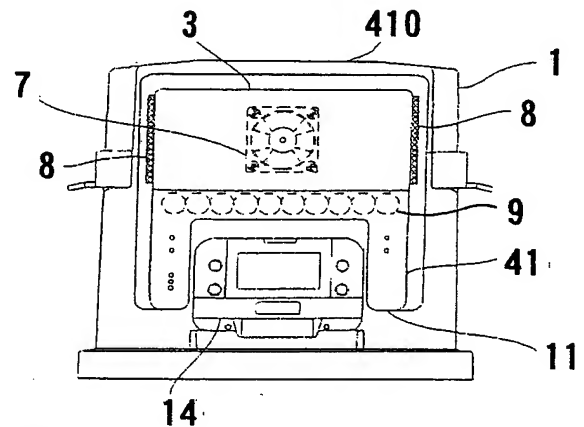


FIG. 79B

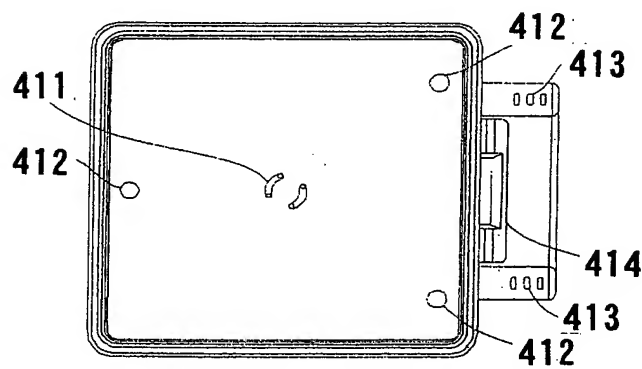
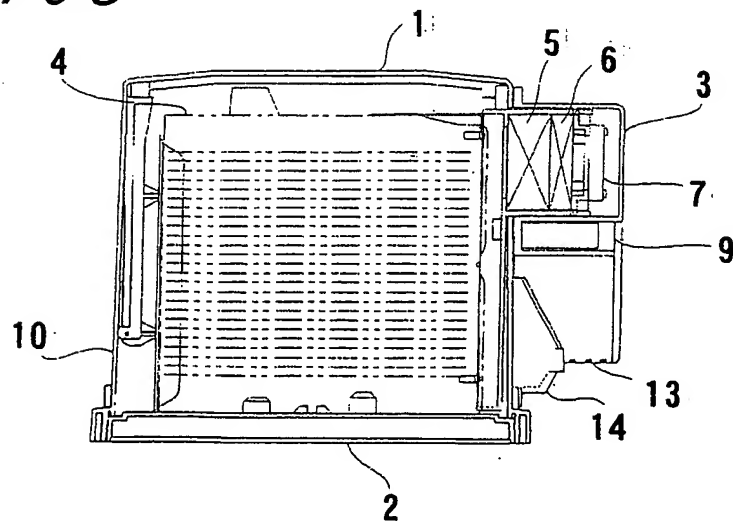


FIG. 79C



80/101

FIG. 80A

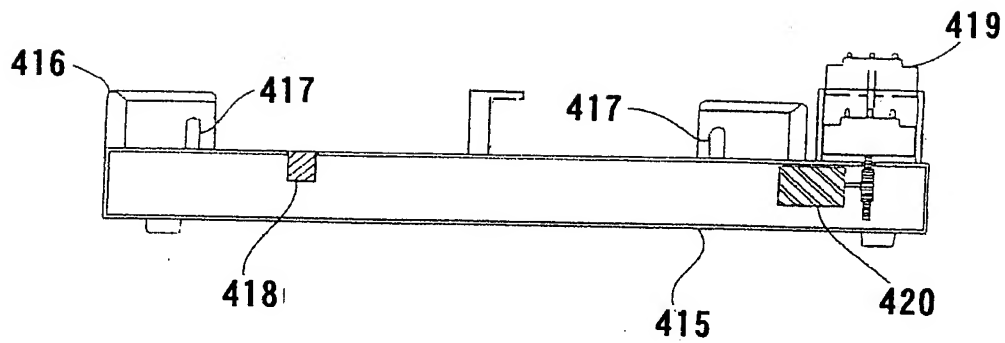
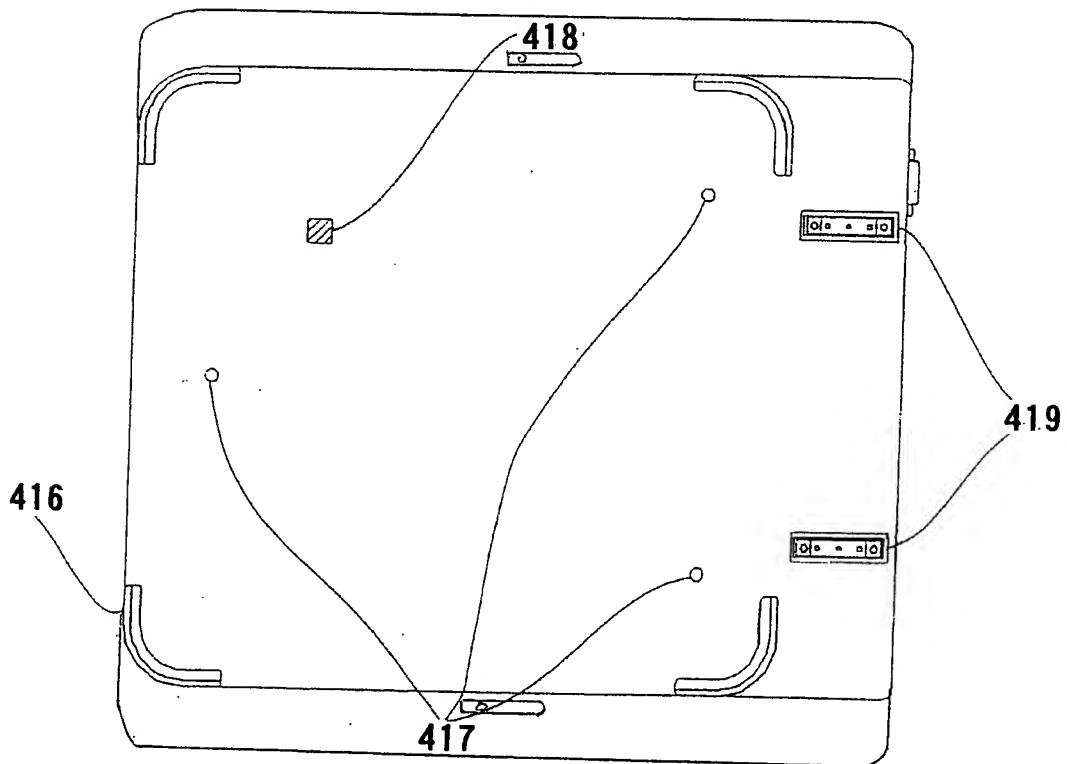


FIG. 80B



81/101

FIG. 81A

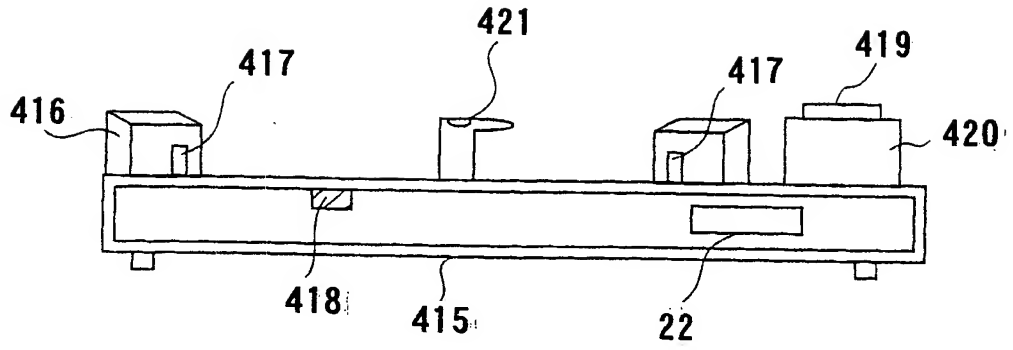
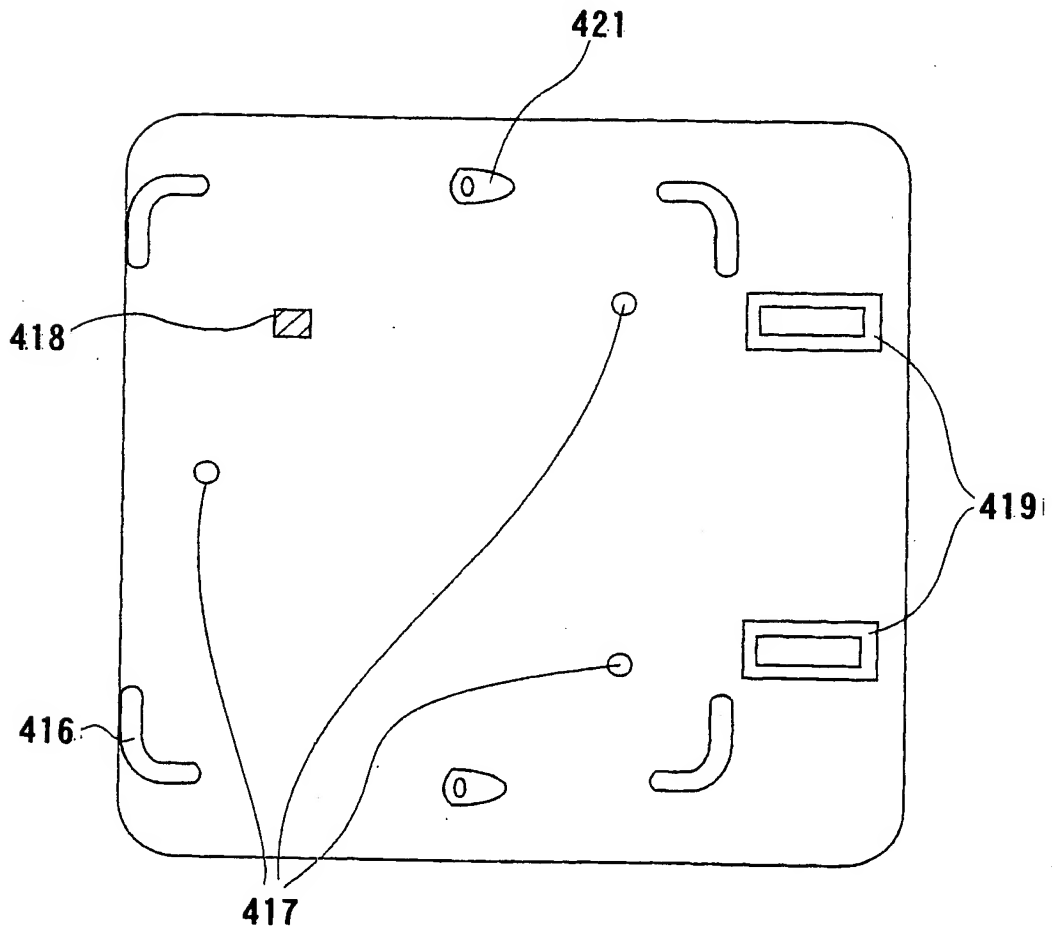
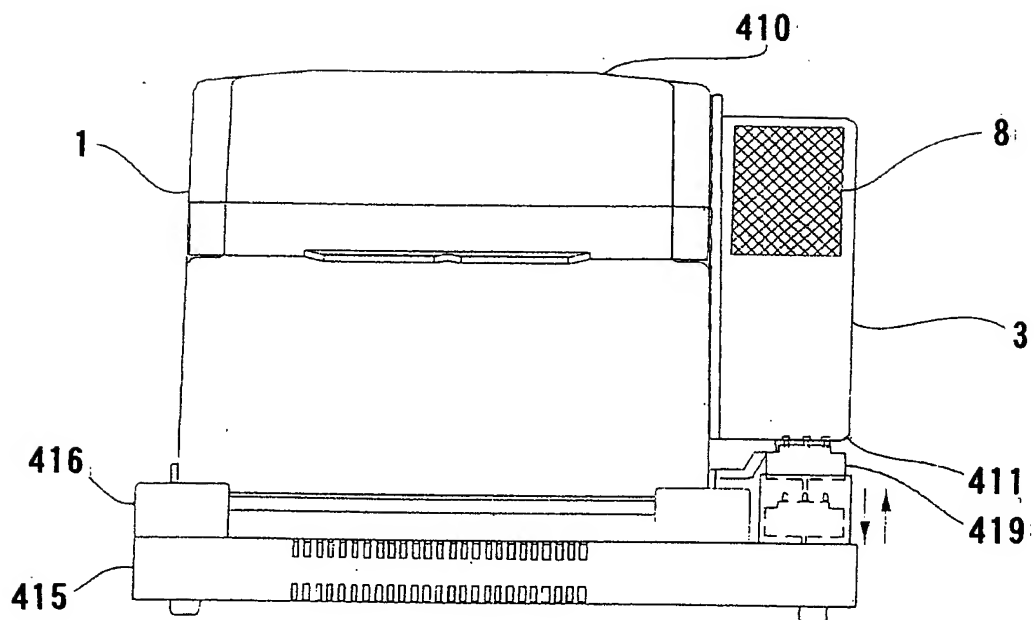


FIG. 81B



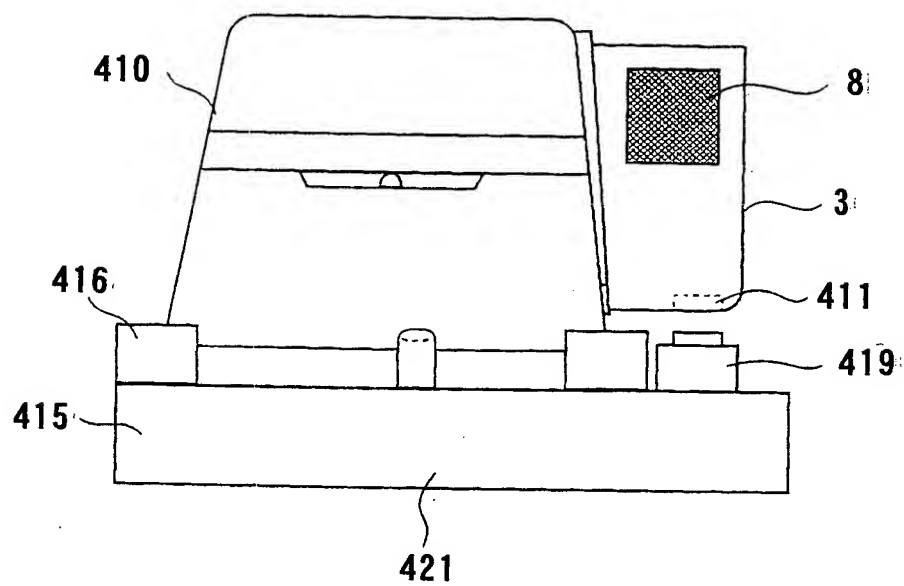
82/101

FIG. 82



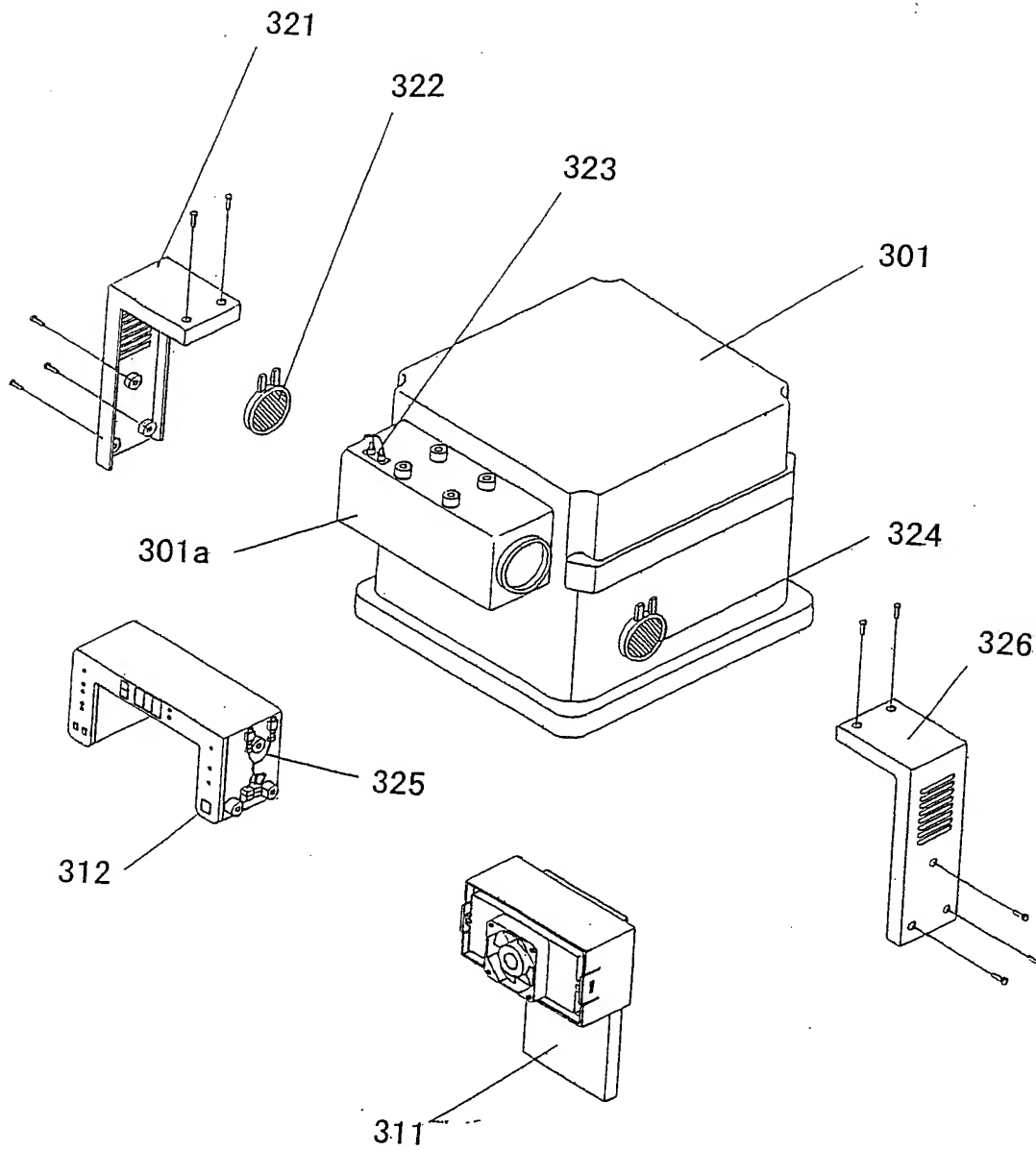
83/101

FIG. 83



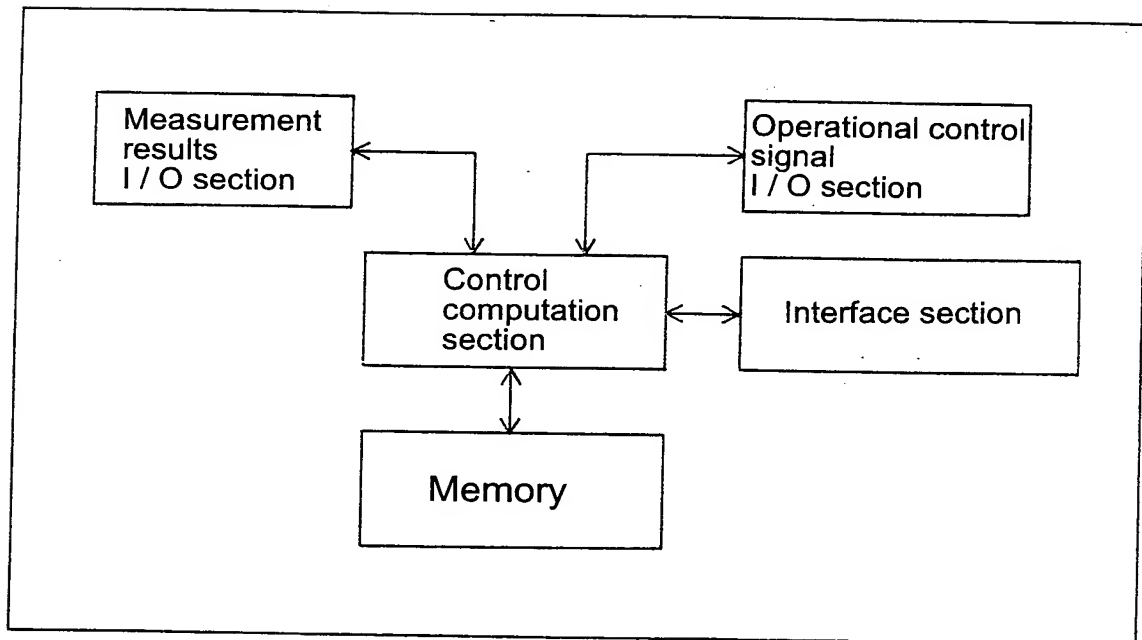
84/101

FIG. 84



85/101

FIG. 85



U.S. Pat. 4,100,000

86/101

FIG. 86

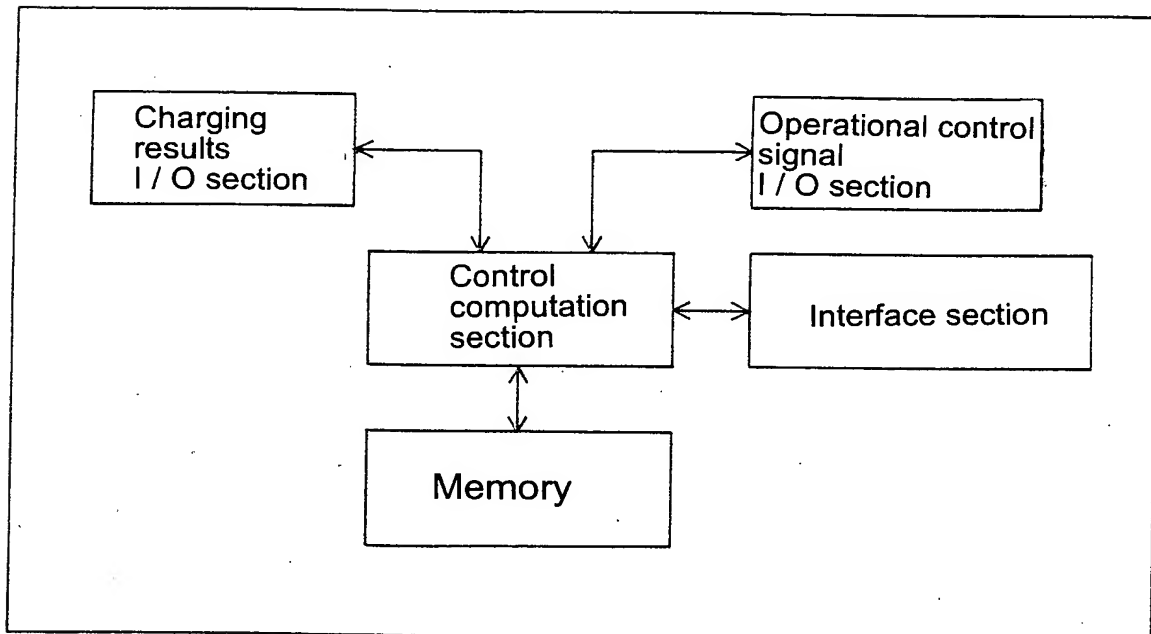


FIG. 87A

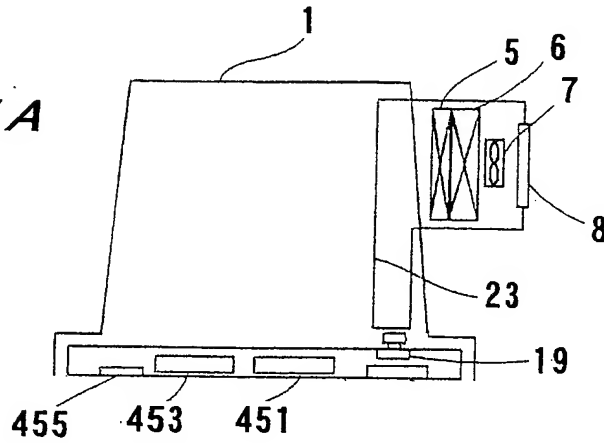


FIG. 87B

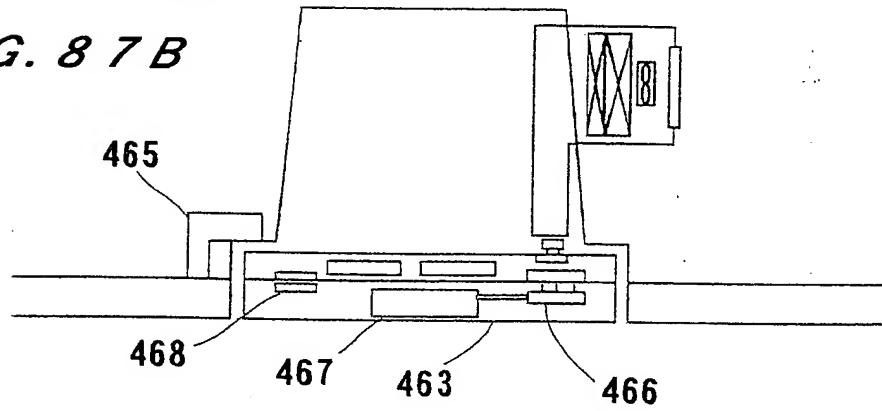


FIG. 87C

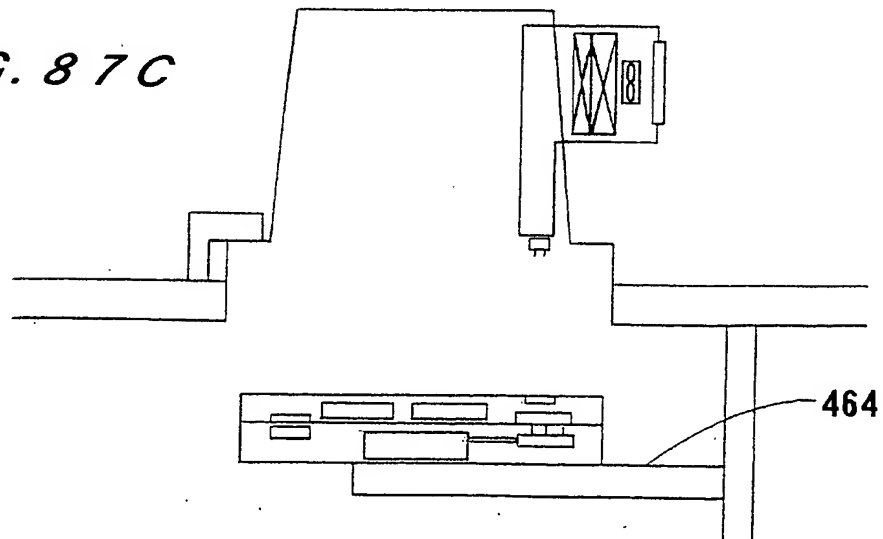


FIG. 88A

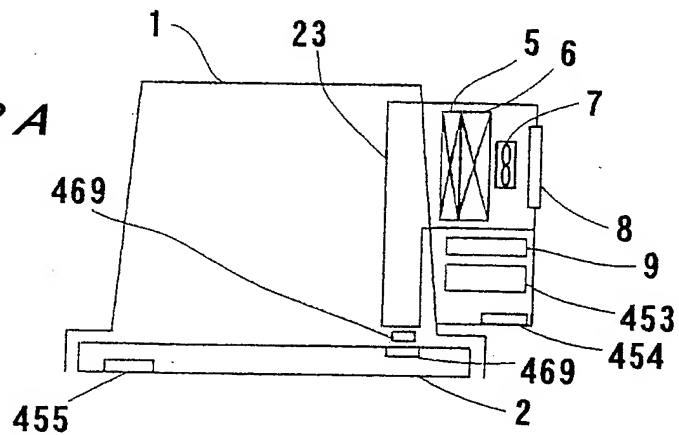


FIG. 88B

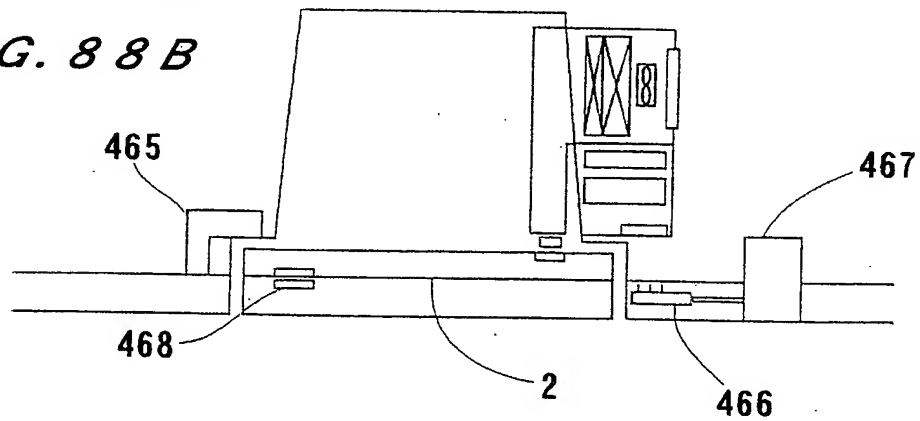
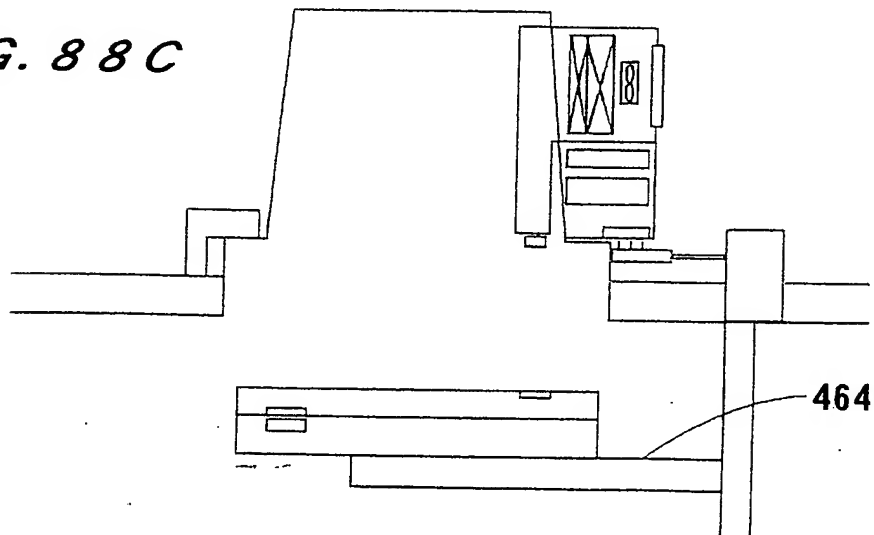


FIG. 88C



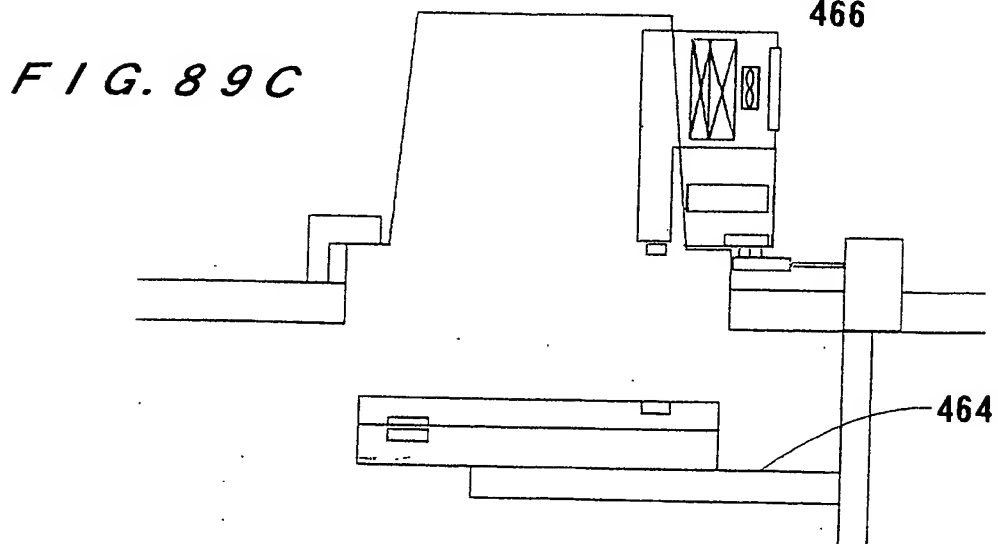
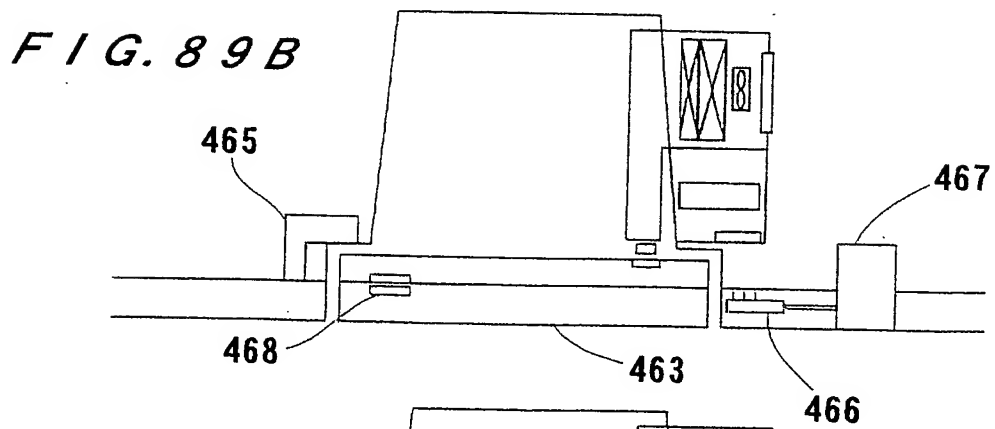
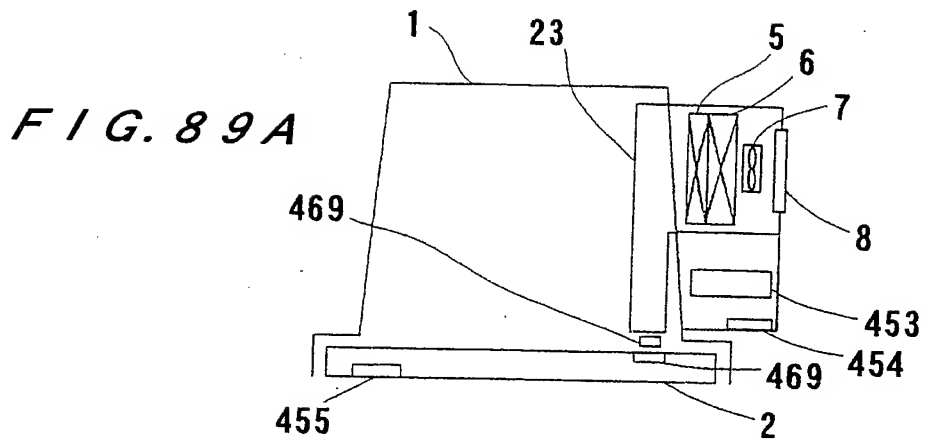


FIG. 90A

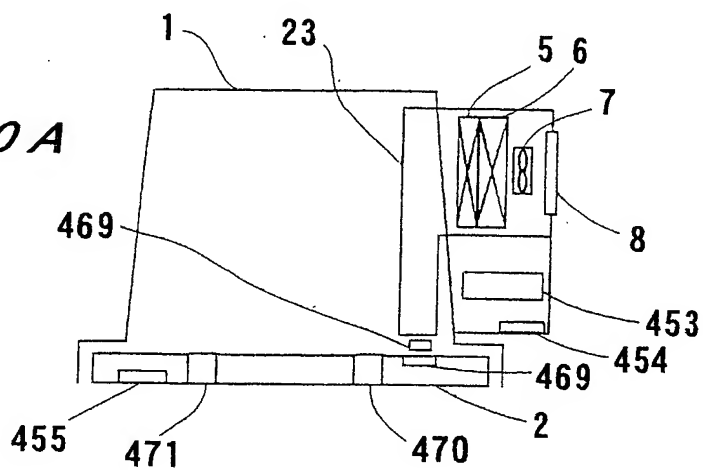


FIG. 90B

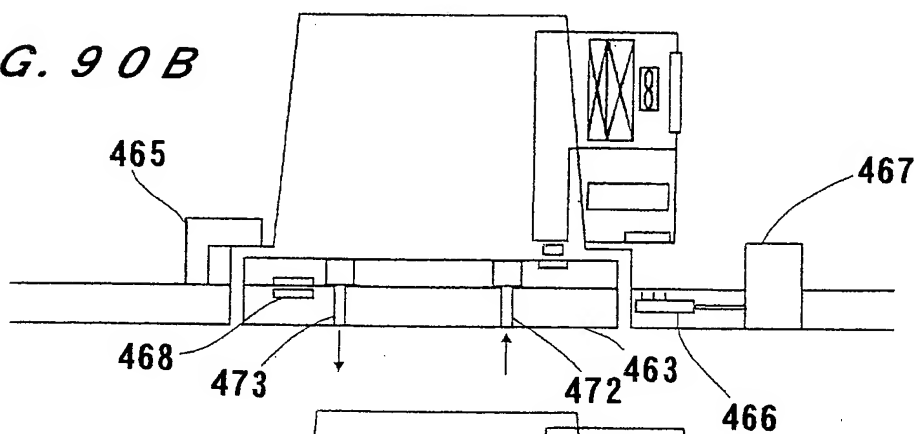


FIG. 90C

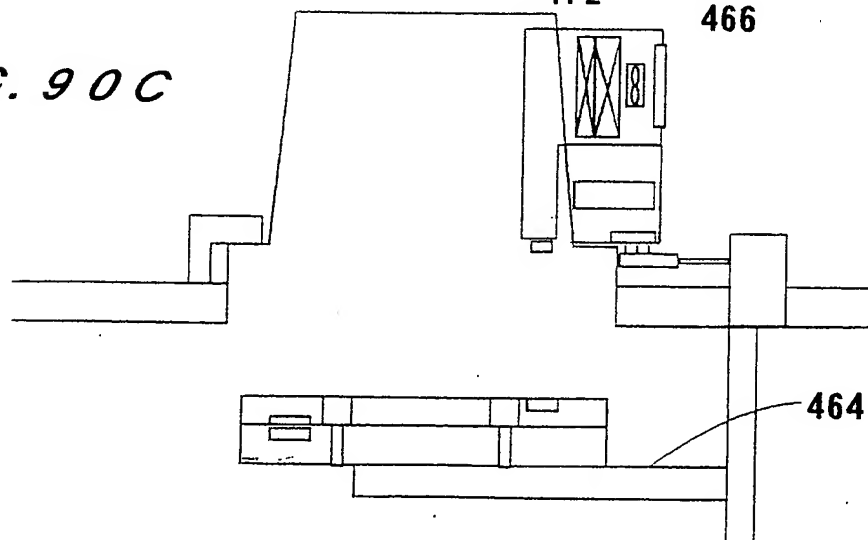
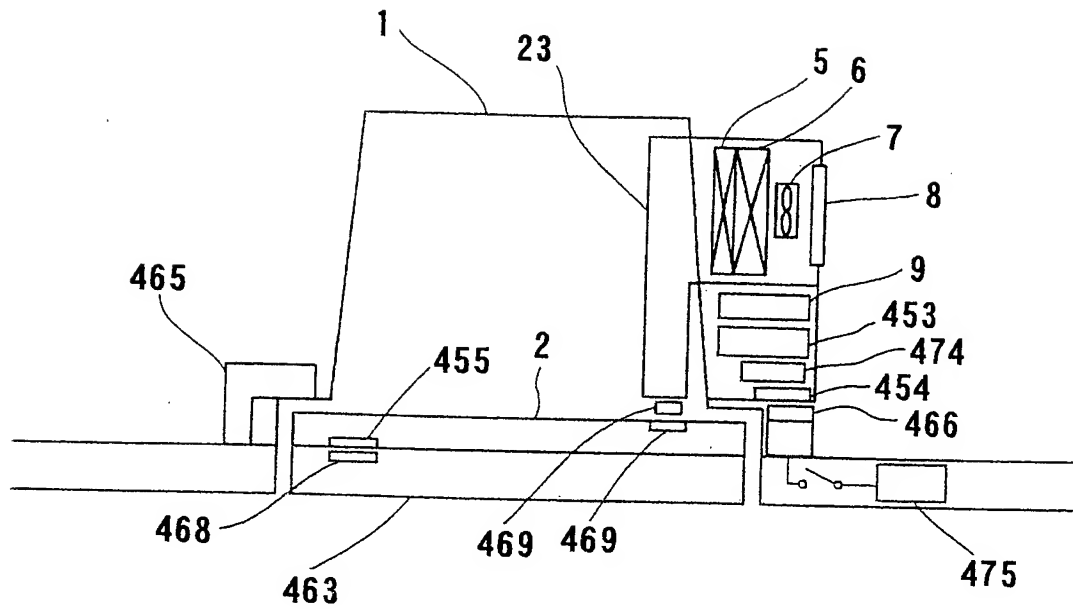
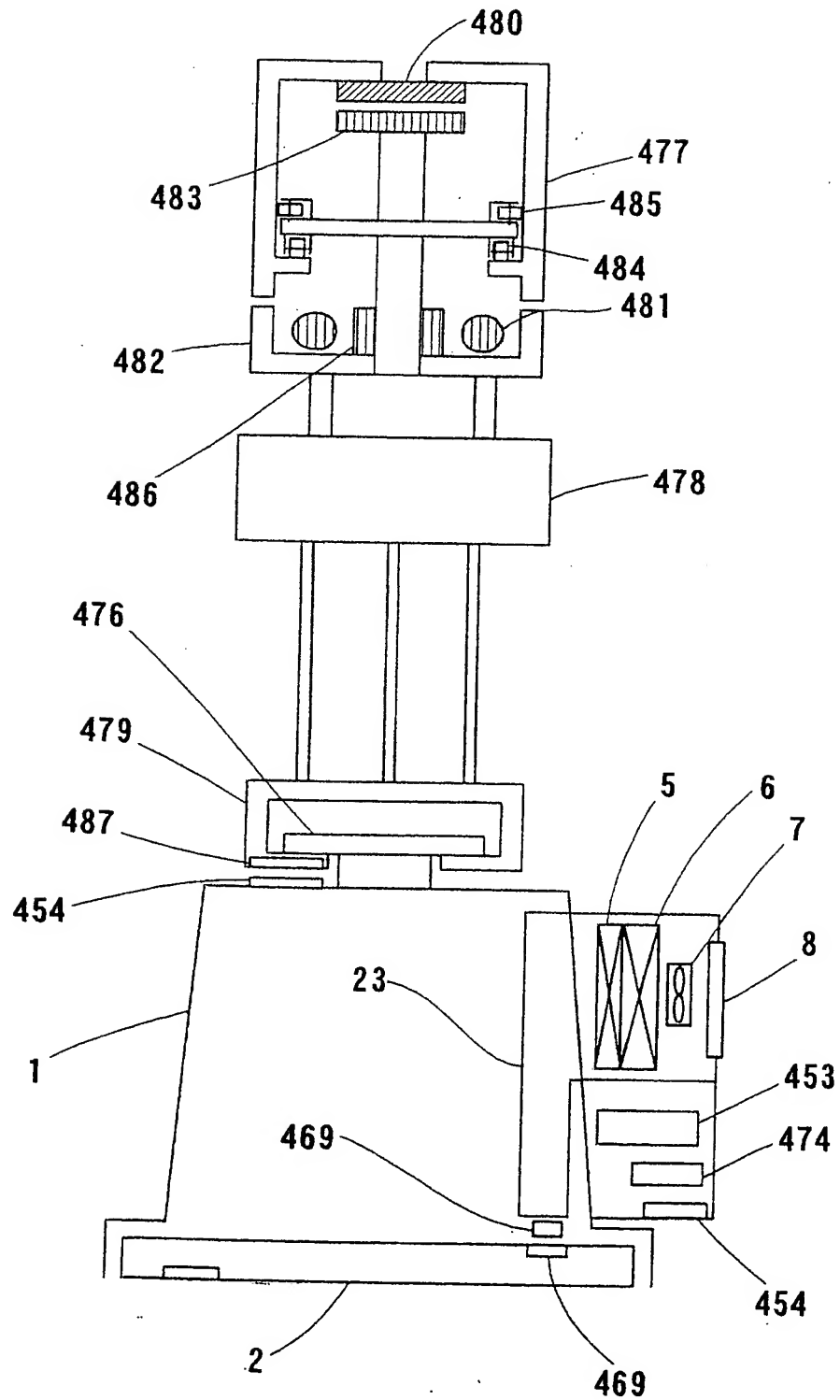


FIG. 91



92/101

FIG. 92



93/101

FIG. 93

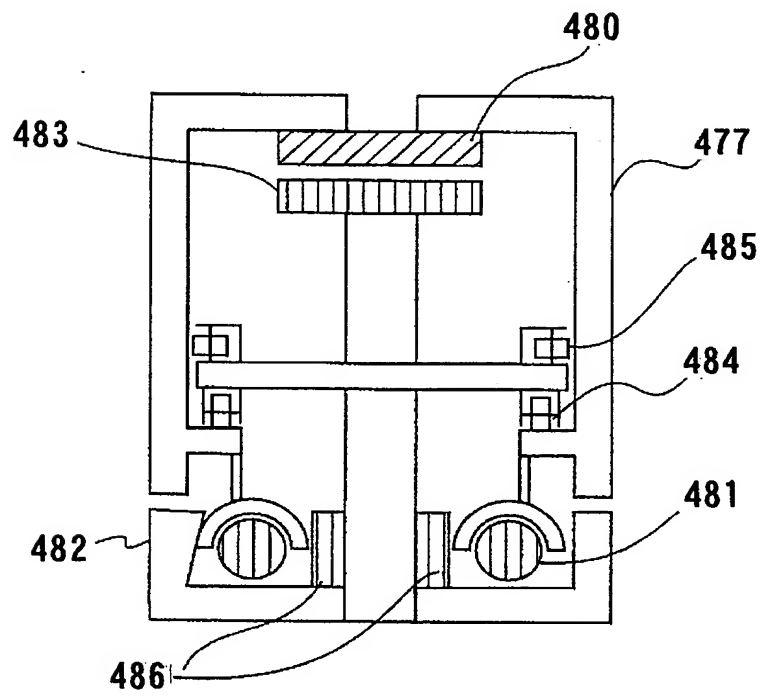


FIG. 94

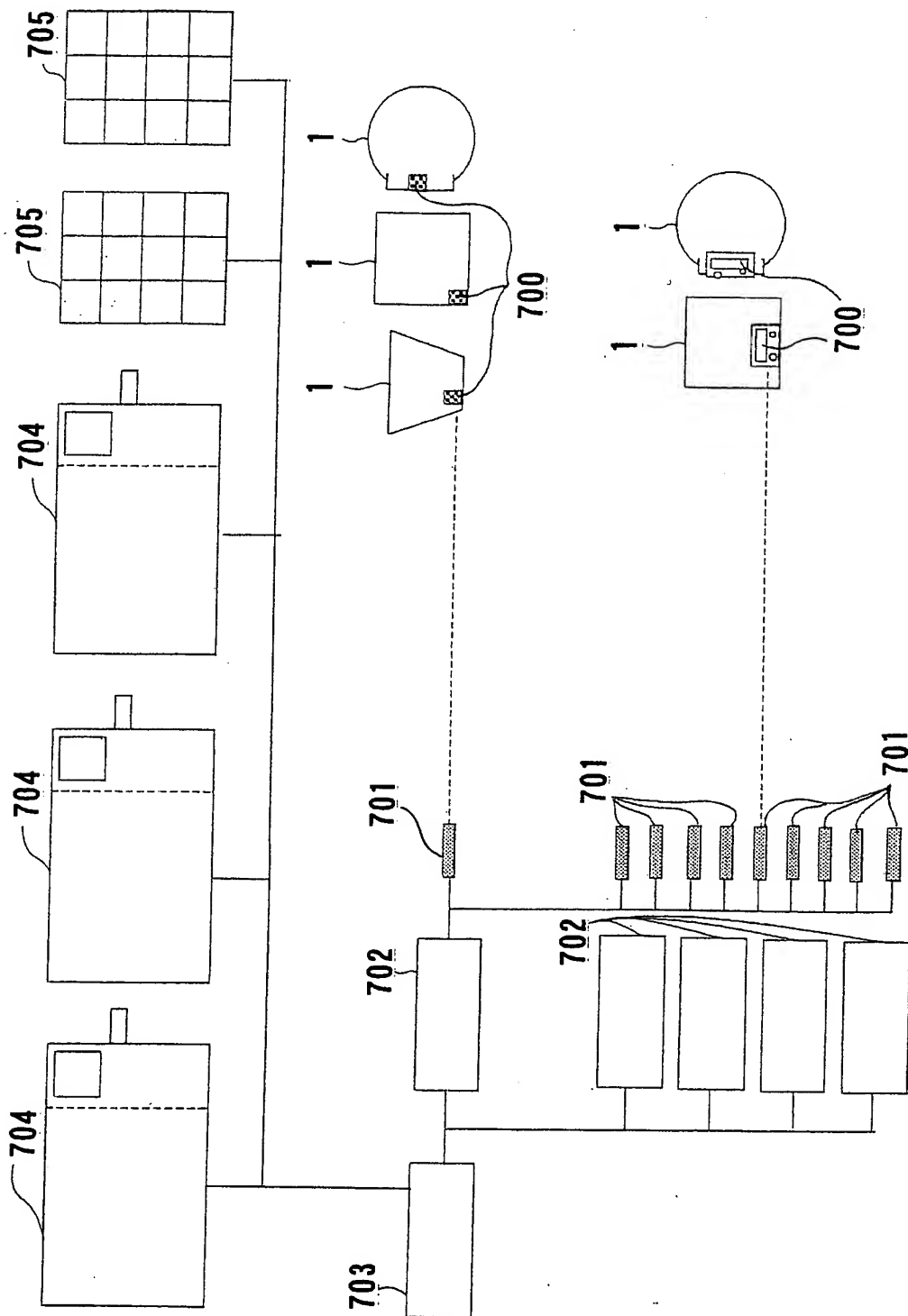


FIG. 95

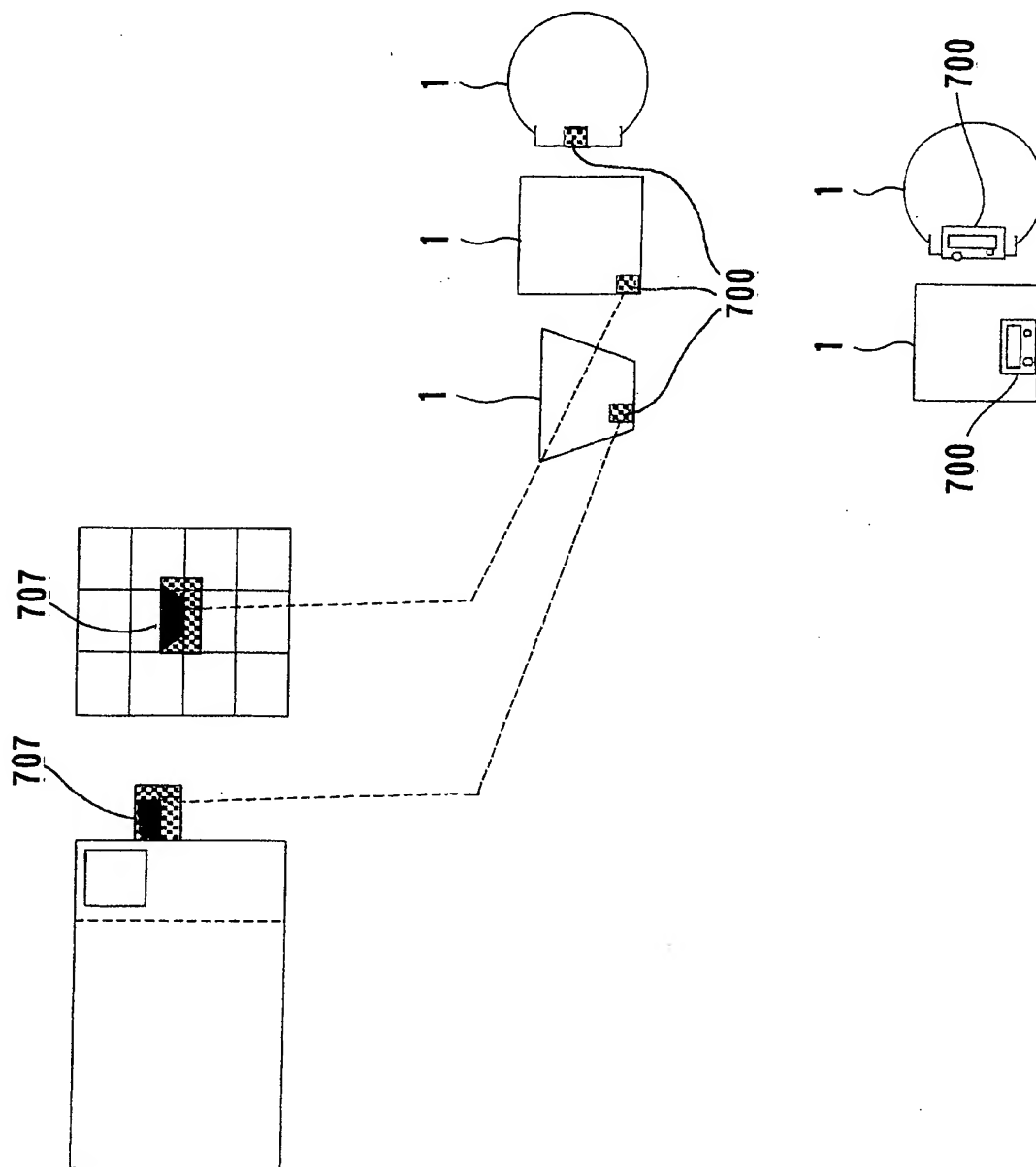
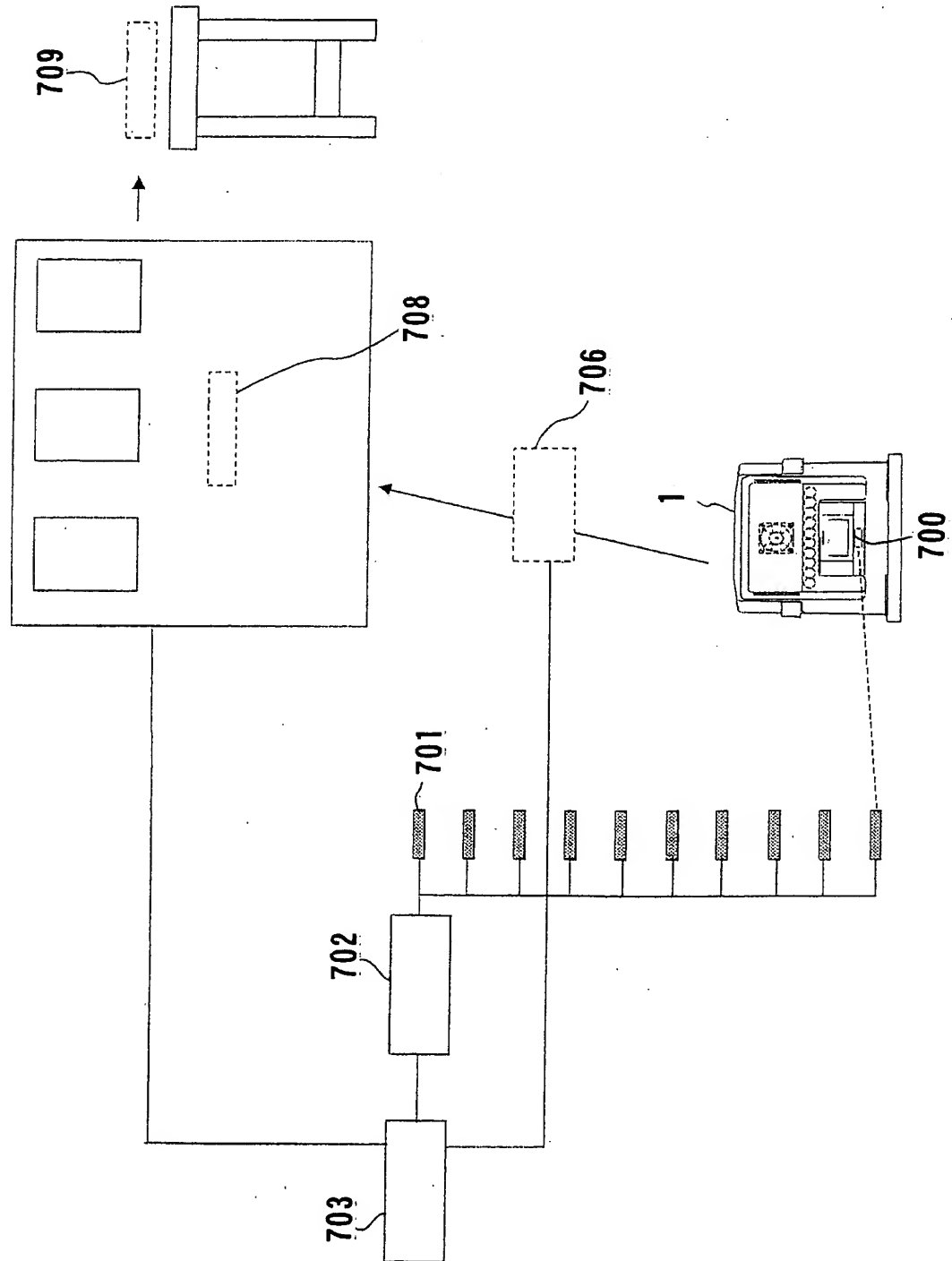


FIG. 96



97/101

FIG. 97

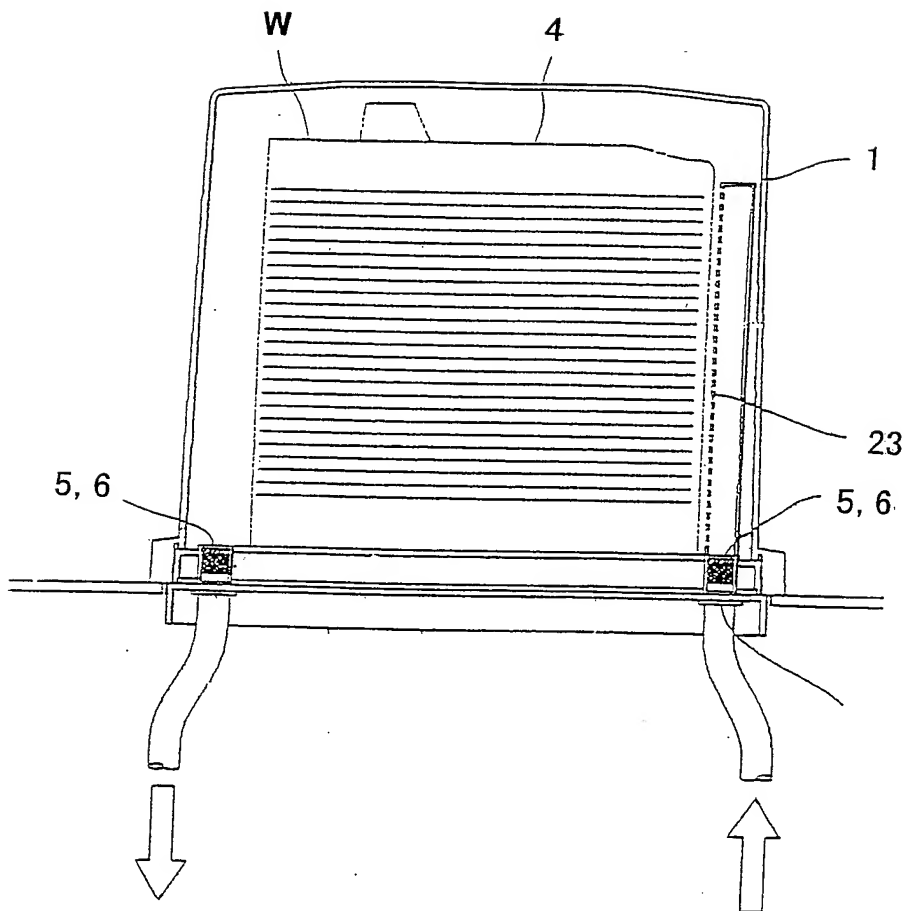
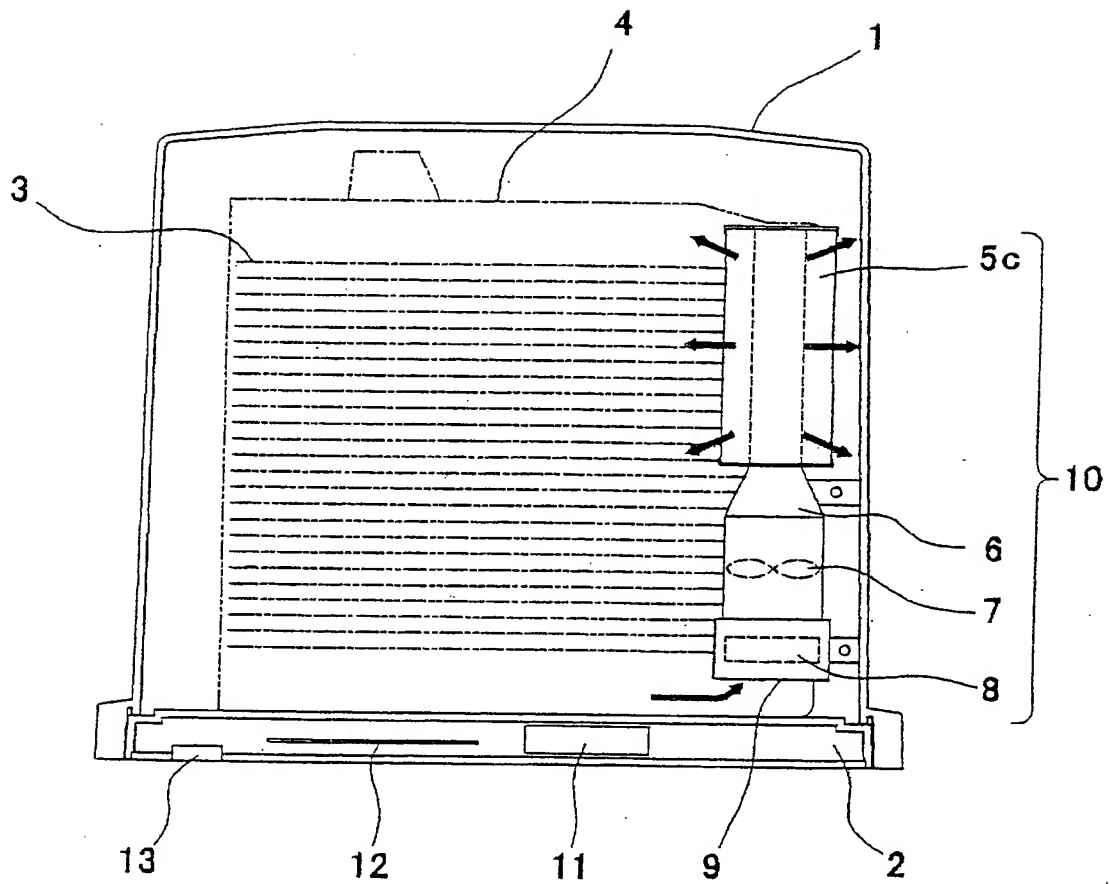
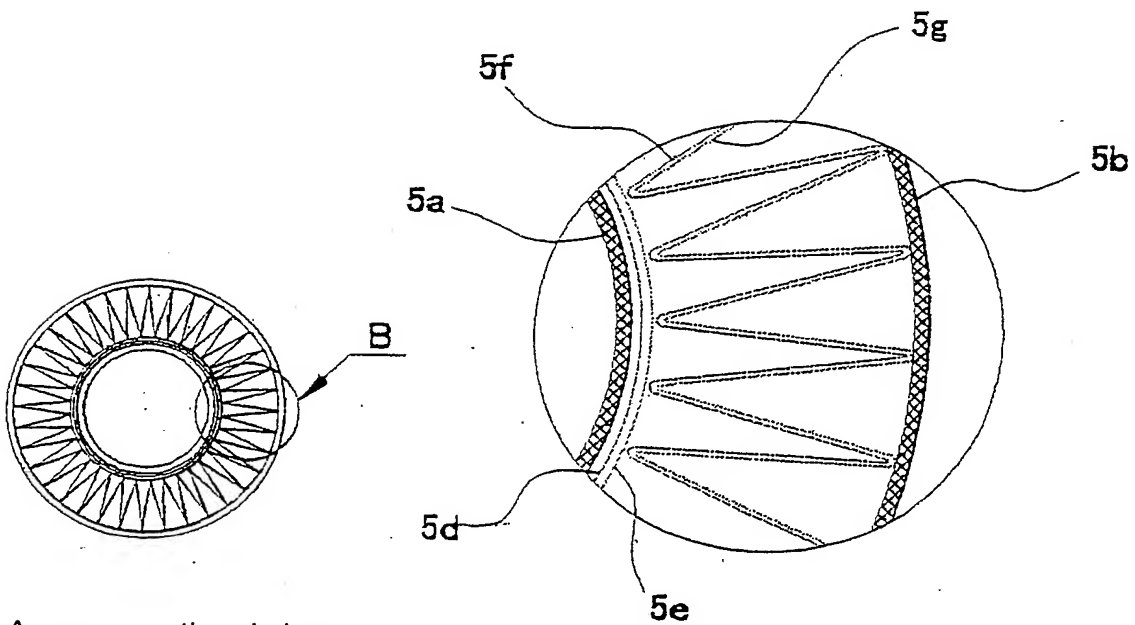
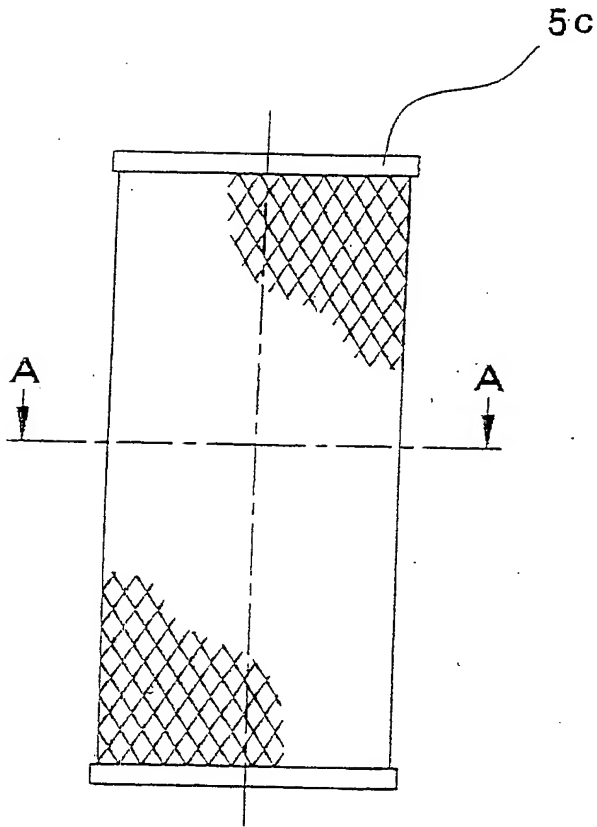


FIG. 98



99/101

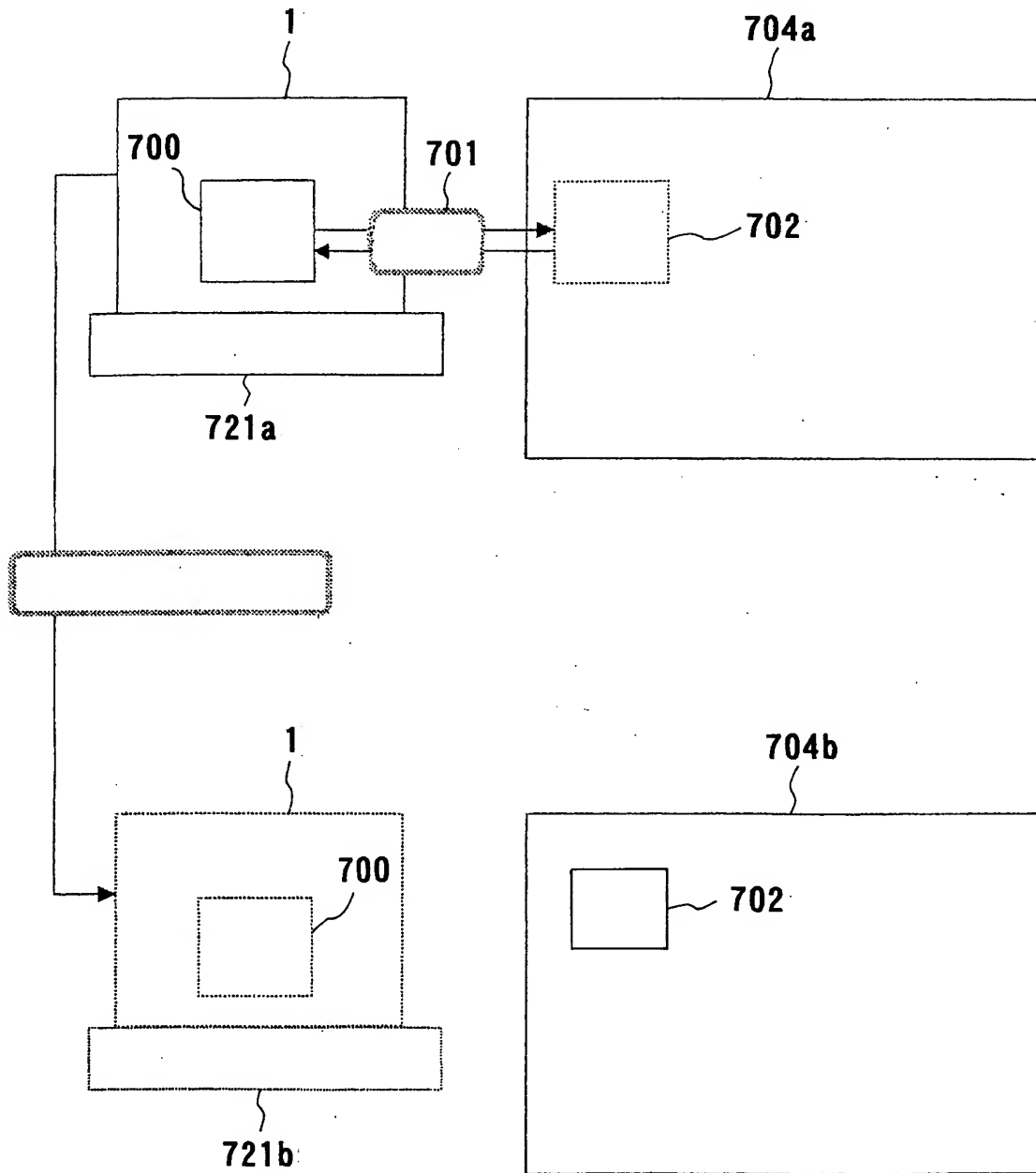
FIG. 99



A - A cross-sectional view

B enlarged view

FIG. 100



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FIG. 101

